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**TOSHIBA Original CMOS 8-bit Microcontroller** 

TLCS-870/C Series

TMP86C829A, TMP86CH29A, TMP86CM29A TMP86PM29A

Databook

3rd Edition

**TOSHIBA CORPORATION** 

#### CMOS 8-Bit Microcontroller

# TMP86C829AU/AF, TMP86CH29AU/AF, TMP86CM29AU/AF

The TMP86C829A/H29A/M29A are the high-speed, high-performance and low power consumption 8-bit microcomputer, including ROM, RAM, LCD driver, multi-function timer/counter, serial interface (UART / SIO), a 10-bit AD converter and two clock generators on chip.

Product No.	ROM	RAM	Package	OTP MCU
TMP86C829AU/AF	8 K x 8-bit	512 × 8 bit	D 1 OFBC4 4040 0 50	
TMP86CH29AU/AF	16 K × 8-bit		P-LQFP64-1010-0.50	TMP86PM29AU/AF
TMP86CM29AU/AF	32 K × 8-bit	1.5 K × 8 bit	P-QFP64-1414-0.80A	

#### **Features**

- ♦ 8-bit single chip microcomputer TLCS-870/C series
- Instruction execution time:  $0.25 \mu s$  (at 16 MHz) 122  $\mu s$  (at 32.768 kHz)
- ◆ 132 types & 731 basic instructions
- 19 interrupt sources (External: 5, Internal: 14)
- ◆ Input/Output ports (39 pins) (Out of which 24 pins are also used as SEG pins)
- 18-bit timer counter: 1 ch
  - Timer, Event counter, Pulse width measurement, Frequencymeasurement modes
- 8-bit timer counter: 4 ch
  - Timer, Event counter, PWM output, Programmable divider output, PPG output modes
- Time Base Timer
- Divider output function
- Watchdog Timer
  - Interrupt source/reset output (programmable)

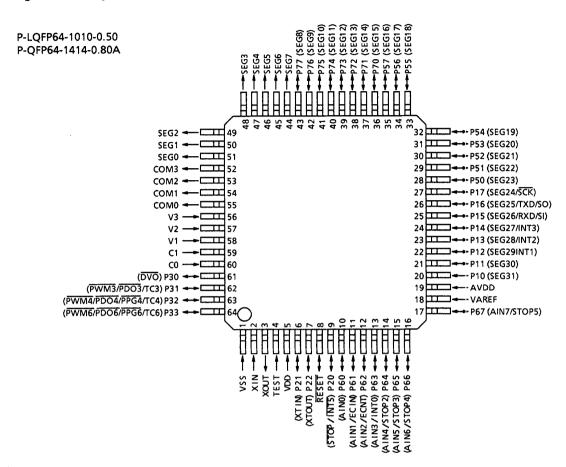


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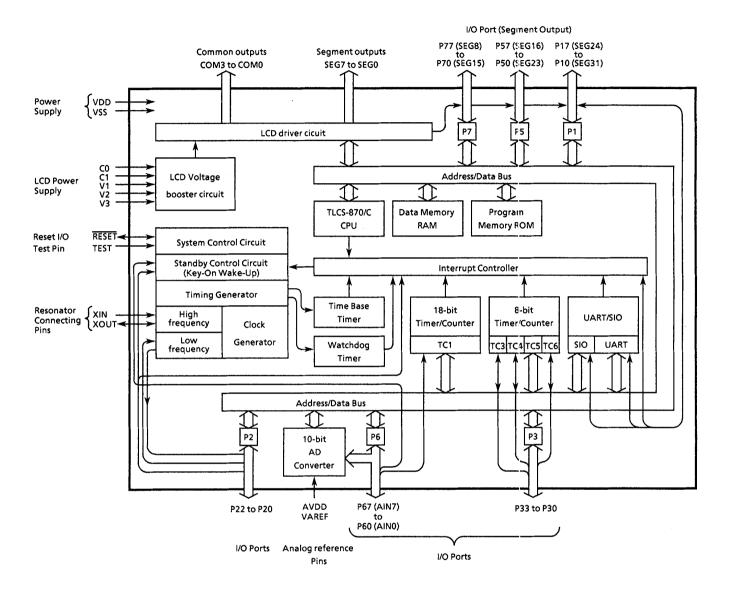
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- Serial interface
  - 8-bit UART/SIO: 1ch
- ♦ 10-bit successive approximation type AD converter
  - Analog input: 8 ch
- ◆ Four Key-On Wake-Up pins
- ◆ LCD driver/controller
  - Built-in voltage booster for LCD driver
  - With displaymemory
  - LCD direct drive capability (Max 32 seg × 4 com)
  - 1/4, 1/3, 1/2duties or static drive are programmably selectable
- Dual clock operation
  - Single/Dual-clock mode
- ♦ Nine power saving operating modes
  - STOP mode: Oscillation stops. Battery/Capacitor back-up. Port output hold / High-impedance.
  - SLOW 1, 2 mode: Low power consumption operation using low-frequency clock (32.768 kHz)
  - IDLE 0 mode: CPU stops, and peripherals operate using high-frequency clock of Time-Base-Timer. Release by falling edge of TBTCR < TBTCK > setting.
  - IDLE 1 mode: CPU stops, and peripherals operate using high-frequency clock. Release by interruputs.
  - IDLE 2 mode: CPU stops, and peripherals operate using high and low frequency clock. Release by interruputs.
  - SLEEP 0 mode: CPU stops, and peripherals operate using low-frequency clock of Time-Base-Timer. Release by falling edge of TBTCR < TBTCK > setting.
  - SLEEP 1 mode: CPU stops, and peripherals operate using low-frequency clock. Release by interrupts.
  - SLEEP 2 mode: CPU stops, and peripherals operate using high and low frequency clock. Release by interrupts.
- Wide operating voltage: 1.8 to 5.5 V at 4.2 MHz/32.768 kHz,
   2.7 to 5.5 V at 8 MHz/32.768 kHz,
   4.5 to 5.5 V at 16 MHz/32.768 kHz

# Pin Assignments (Top View)



### **Block Diagram**



# **Pin Function**

Pin Name	Input / Output		Function			
P17 (SEG24, SCK)	1/0 (1/0)		Serial clock input/output			
P16 (SEG25, TxD, SO)	I/O (Output)	8-bit input/output port with latch.	UART data output Serial data output			
P15 (SEG26, RxD, SI)	1/0 (1/0)	When used as input port, an external interrupt input, serial interface input/output and UART data input/	UART data input Serial data input	LCD segment		
P14 (SEG27, INT3)	1/0 (1/0)	output, the P1LCR must be set to "0"	External interrupt 3 input	outputs.		
P13 (SEG28, INT2)	1/0 (1/0)	after setting output latch to "1".	External interrupt 2 input			
P12 (SEG29, INT1)	1/0 (1/0)	When used as a LCD segment output, the P1LCR must be set to "1".	External interrupt 1 input			
P11 (SEG30)	I/O (Output)					
P10 (SEG31)	I/O (Output)					
P22 (XTOUT)	I/O (Output)		Resonator connecting pins (32.			
P21 (XTIN)	I/O (Input)	3-bit input/output port with latch. When used as an input port, the	For inputting external clock, XT XOUT is opened.			
P20 (INT5, STOP)	I/O (Input)	output latch must be set to "1".	External interrupt input 5 or ST signal input	OP mode release		
P33 (PWM6, PDO6, PPG6, TC6)	1/0(1/0)	4-bit programmable input/output port (Nch high current output).	Timer counter 6 input/output			
P32 (PWM4, PDO4, PPG4, TC4)	1/0(1/0)	When used as a timer/counter output or divider output, the output latch must be set to "1". When used as an	Timer counter 4 input/output			
P31 (PWM3, PDO3, TC3)	1/0(1/0)	input port or timer/counter input, the P3OUTCR must be set to "0" after	Timer counter 3 input/output			
P30 ( <del>DVO</del> )	I/O(Output)	P3DR is set to "1".	Divider output			
P57 (SEG16) to P50 (SEG23)	I/O (Output)	8-bit input/output port with latch. When used as a LCD segment output, the P5LCR must be set to "1".	LCD segment outputs			
P67 (AIN7, STOP5)	I/O (Input)	8-bit programmable input/output port (tri-state). Each bit of this port	STOP 5 input			
P66 (AIN6, STOP4)	I/O (Input)	can be individually configured as an	STOP 4 input			
P65 (AIN5, STOP3)	I/O (Input)	input or an output under software	STOP 3 input			
P64 (AIN4, STOP2)	I/O (Input)	control. When used as an analog input, the P6CR must be set to "0"	STOP 2 input	AD converter analog inputs		
P63 (AIN3, <u>INTO</u> )	I/O (Input)	after setting output latch to "0".	External interrupt 0 input	unalog inputs		
P62 (AIN2, ECNT)	I/O (Input)	When used as an input port, a key on wake up input, an external interrupt	Timer / counter 1 input			
P61 (AIN1, ECIN)	I/O (Input)	input and timer/counter input, the	Timer / counter 1 input			
P60 (AIN0)	i/O (input)	P6CR must be set to "0" after setting output latch to "1".				
P77 (SEG8) to P70 (SEG15)	I/O (Output)	8-bit input/output port with latch. When used as a LCD segment output, the P7LCR must be set to "1".	LCD segment outputs			
SEG7 to SEG0	Outroit	LCD segment outputs				
COM3 to COM0	Output	LCD common outputs				
V 3 to V 1	LCD voltage	LCD voltage booster pin. Capacitors a	re required between C0 and C1	pin and V1/V2/V3		
C1 to C0	booster pin	pin and GND.				
XIN, XOUT	Input Output	Resonator connecting pins for high-fre used and XOUT is opened.	equency clock. For inputting ext	ernal clock, XIN is		
RESET	1/0	Reset signal input or watchdog timer or	utput / address-trap-reset output			
TEST	Input	Test pin for out-going test. Be fixed to	low.			
VDD, VSS		+ 5 V, 0 (GND)				
VAREF	Power Supply	Analog reference voltage inputs (High)				
AVDD		AD circuit power supply				

# **Operational Description**

#### 1. CPU Core Functions

The CPU core consists of a CPU, a system clock controller, and an interrupt controller.

This section provides a description of the CPU core, the program memory, the data memory, the external memory interface, and the reset circuit.

### 1.1 Memory Address Map

The TMP86C829A/H29A/M29A memory consist of 4 blocks: ROM, RAM, DBR (Data Buffer Register) and SFR (Special Function Register). They are all mapped in 64 Kbyte address space. Figure 1-1 shows the TMP86C829A/H29A/M29A memory address map. The general-purpose registers are not assigned to the RAM address space.

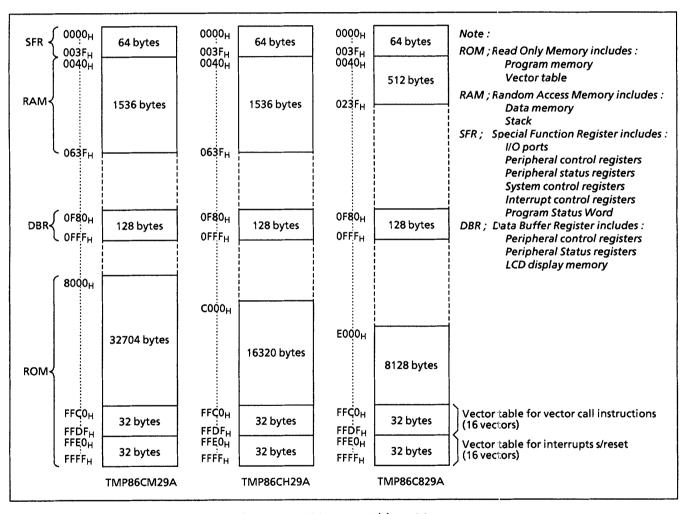


Figure 1-1. Memory Address Maps

# 1.2 Program Memory (ROM)

The TMP86C829A has a 8 K×8-bit (address  $E000_H$  to FFFF<sub>H</sub>), TMP86CH29A has a 16 K×8-bit (address  $C000_H$  to FFFF<sub>H</sub>), and the TMP87CM29A has a 32 K×8-bit (address  $8000_H$  to FFFF<sub>H</sub>) of program memory (mask programmed ROM). However, placing program memory on the internal RAM is deregulated if a certain procedure is executed (See 2.4.5 Address trap).

# 1.3 Data Memory (RAM)

The TLCS-870/C is available up to 64 Kbytes of data memory area. Data memory consists of internal data memory (internal ROM or RAM). The TMP86C829A has 512 bytes, the TMP86CH29A/M29A have 1.5 Kbytes of internal RAM. The first 192 bytes (0040H to 00FFH) of the internal RAM are located in the direct area; instructions with shorten operations are available against such an area. The data memory contents become unstable when the power supply is turned on; therefore, the data memory should be initialized by an initialization routine.

```
Clears RAM to "00H". (TMP86C829A)
Example 1:
                                            ; Start address setup
                           LD
                                 HL, 0040H
                                             ; Initial value (00H) setup
                          LD
                                 A, H
                           LD
                                 BC, 01FFH ;
             SRAMCLR:
                           LD
                                 (HL), A
                          INC
                                 HL
                           DEC
                                 BC
                                 F, SRAMCLR
                           JRS
             Clears RAM to "00H". (TMP86CH29A/CM29A, TMP86PM29A)
Example 2:
                                            ; Start address setup
                           LD
                                 HL,0040H
                                             ; Initial value (00H) setup
                           LD
                                 A, H
                           LD
                                 BC, 05FFH
             SRAMCLR:
                           LD
                                 (HL), A
                           INC
                                 HL
                           DEC
                                 BC
                           JRS
                                 F, SRAMCLR
```

# 1.4 System Clock Controller

The system clock controller consists of a clock generator, a timing generator, and a stand-by controller.

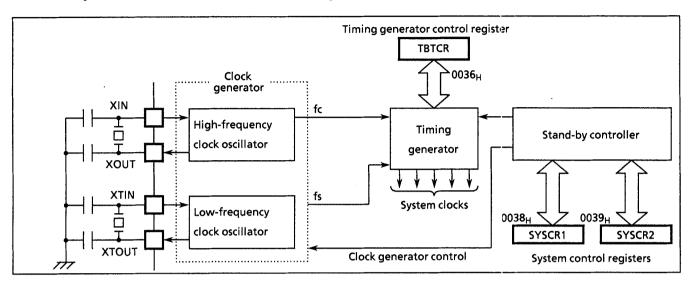


Figure 1-2. System Clock Control

# 1.4.1 Clock generator

The Clock generator generates the basic clock which provides the system clocks supplied to the CPU core and peripheral hardware. It contains two oscillation circuits: one for the high-frequency clock and one for the low-frequency clock. Power consumption can be reduced by switching of the standby controller to low-power operation based on the low-frequency clock.

The high-frequency (fc) and low-frequency (fs) clocks can easily be obtained by connecting a resonator between the XIN/XOUT and XTIN/XTOUT pins respectively. Clock input from an external oscillator is also possible. In this case, external clock is applied to XIN/XTIN pin with XOUT/XTOUT pin not connected.

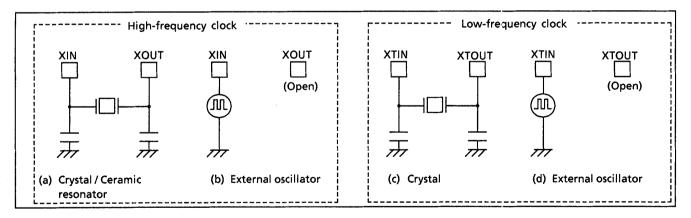


Figure 1-3. Examples of Resonator Connection

Note: The function to monitor the basic clock directly at external is not provided for hardware, however, with disabling all interrupts and watchdog timers, the oscillation frequency can be adjusted by monitoring the pulse which the fixed frequency is outputted to the port by the program.

The system to require the adjustment of the oscillation frequency should create the program for the adjustment in advance.

# 1.4.2 Timing generator

The timing generator generates the various system clocks supplied to the CPU core and peripheral hardware from the basic clock (fc or fs). The timing generator provides the following functions.

- (1) Generation of main system clock
- ② Generation of divider output ( $\overline{DVO}$ ) pulses
- (3) Generation of source clocks for time base timer
- (4) Generation of source clocks for watchdog timer
- (5) Generation of internal source clocks for timer/counters
- 6 Generation of warm-up clocks for releasing STOP mode
- (7) Generation of base clocks for LCD driver/controller

# (1) Configuration of timing generator

The timing generator consists of a 2-stage prescaler, a 21-stage divider, a main system clock generator, and machine cycle counters.

An input clock to the 7th stage of the divider depends on the operating mode, DV7CK (bit 4 in TBTCR), that is shown in Figure 1-5. As reset and STOP mode started/canceled, the prescaler and the divider are cleared to "0".

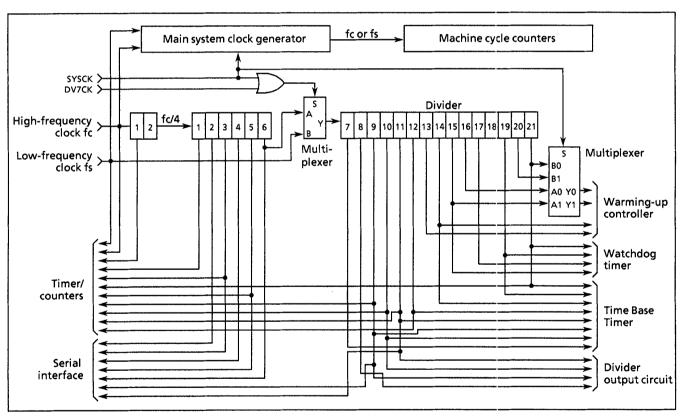


Figure 1-4. Configuration of Timing Generator

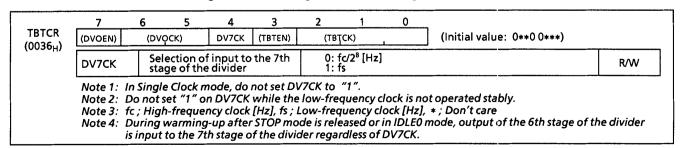


Figure 1-5. Timing Generator Control Register

# (2) Machine cycle

Instruction execution and peripheral hardware operation are synchronized with the main system clock. The minimum instruction execution unit is called an "machine cycle". There are a total of 10 different types of instructions for the TLCS-870/C Series: ranging from 1-cycle instructions which require one machine cycle for execution to 10-cycle instructions which require 10 machine cycles for execution. A machine cycle consists of 4 states (S0 to S3), and each state consists of one main system clock.

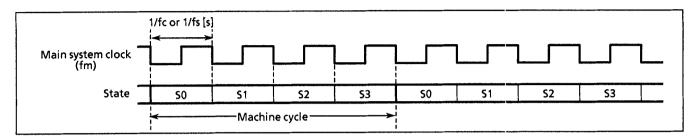


Figure 1-6. Machine Cycle

# 1.4.3 Operation mode control circuit

The operation mode control circuit starts and stops the oscillation circuits for the high-frequency and low-frequency clocks, and switches the main system clock. There are two operating modes: single-clock and dual-clock. These modes are controlled by the system control registers (SYSCR1 and SYSCR2). Figure 1-7 shows the operating mode transition diagram and Figure 1-8 shows the system control registers.

# (1) Single-clock mode

Only the oscillation circuit for the high-frequency clock is used, and P21 (XTIN) and P22 (XTOUT) pins are used as input/output ports. The main-system clock is obtained from the high-frequency clock. In the single-clock mode, the machine cycle time is 4/fc [s].

# ① NORMAL1 mode

In this mode, both the CPU core and on-chip peripherals operate using the high-frequency clock. The TMP86C829A/H29A/M29A are placed in this mode after reset.

#### ② IDLE1 mode

In this mode, the internal oscillation circuit remains active. The CPU and the watchdog timer are halted; however on-chip peripherals remain active (operate using the high-frequency clock). IDLE1 mode is started by SYSCR2<IDLE>, and IDLE1 mode is released to NORMAL1 mode by an interrupt request from the on-chip peripherals or external interrupt inputs. When the IMF (interrupt master enable flag) is "1" (interrupt enable), the execution will resume with the acceptance of the interrupt, and the operation will return to normal after the interrupt service is completed. When the IMF is "0" (interrupt disable), the execution will resume with the instruction which follows the IDLE1 mode start instruction.

#### ③ IDLE0 mode

In this mode, all the circuit, except oscillator and the Timer-Base-Timer, stops operation. This mode is enabled by setting "1" on bit TGHALT on the system control register 2 (SYSCR2). When IDLE0 mode starts, the CPU stops and the timing generator stops feeding the clock to the peripheral circuits other than TBT. Then, upon detecting the falling edge of the source clock selected with TBTCR < TBTCK >, the timing generator starts feeding the clock to all peripheral circuits. When returned from IDLE0 mode, the CPU restarts operating, entering NORMAL1 mode back again. IDLE0 mode is entered and returned regardless of how TBTCR < TBTEN > is set. When IMF = "1", EF<sub>6</sub> (TBT interrupt individual enable flag) = "1", and TBTCR < TBTEN > := "1", interrupt processing is performed. When IDLE0 mode is entered while TBTCR < TBTEN > = "1", the INTTBT interrupt latch is set after returning to NORMAL1 mode.

# (2) Dual-clock mode

Both the high-frequency and low-frequency oscillation circuits are used in this mode. P21 (XTIN) and P22 (XTOUT) pins cannot be used as input / output ports. The main system clock is obtained from the high-frequency clock in NORMAL2 and IDLE2 modes, and is obtained from the low-frequency clock in SLOW and SLEEP modes. The machine cycle time is 4/fc [s] in the NORMAL2 and IDLE2 modes, and 4/fs [s] (122  $\mu$ s at fs=32.768 kHz) in the SLOW and SLEEP modes.

The TLCS-870/C is placed in the signal-clock mode during reset. To use the dual-clock mode, the low-frequency oscillator should be turned on at the start of a program.

#### (1) NORMAL2 mode

In this mode, the CPU core operates with the high-frequency clock. On-chip peripherals operate using the high-frequency clock and / or low-frequency clock.

# ② SLOW2 mode

In this mode, the CPU core operates with the low-frequency clock, while both the high-frequency clock and the low-frequency clock are operated. On-chip peripherals are triggered by the low-frequency clock. As the SYSCK on SYSCR2 becomes "0", the hardware changes into NORMAL2 mode. As the XEN on SYSCR2 becomes "0", the hardware changes into SLOW1 mode. Do not clear XTEN to "0" during SLOW2 mode.

### ③ SLOW1 mode

This mode can be used to reduce power-consumption by turning off oscillation of the high-frequency clock. The CPU core and on-chip peripherals operate using the low-frequency clock. Switching back and forth between SLOW1 and SLOW2 modes are performed by XEN bit on the system control register 2 (SYSCR2). In SLOW1 and SLEEP mode, the input clock to the 1st stage of the divider is stopped; output from the 1st to 6th stages is also stopped.

### 4 IDLE2 mode

In this mode, the internal oscillation circuit remain active. The CPU and the watchdog timer are halted; however, on-chip peripherals remain active (operate using the high-frequency clock and / or the low-frequency clock). Starting and releasing of IDLE2 mode are the same as for IDLE1 mode, except that operation returns to NORMAL2 mode.

#### (5) SLEEP1 mode

In this mode, the internal oscillation circuit of the low-frequency clock remains active. The CPU, the watchdog timer, and the internal oscillation circuit of the high-frequency clock are halted; however, on-chip peripherals remain active (operate using the low-frequency clock). Starting and releasing of SLEEP mode are the same as for IDLE1 mode, except that operation returns to SLOW mode. In SLOW and SLEEP mode, the input clock to the 1st stage of the divider is stopped; output from the 1st to 6th stages is also stopped.

#### 6 SLEEP2 mode

The SLEEP2 mode is the idle mode corresponding to the SLOW2 mode. The status under the SLEEP2 mode is same as that under the SLEEP1 mode, except for the oscillation circuit of the high-frequency clock.

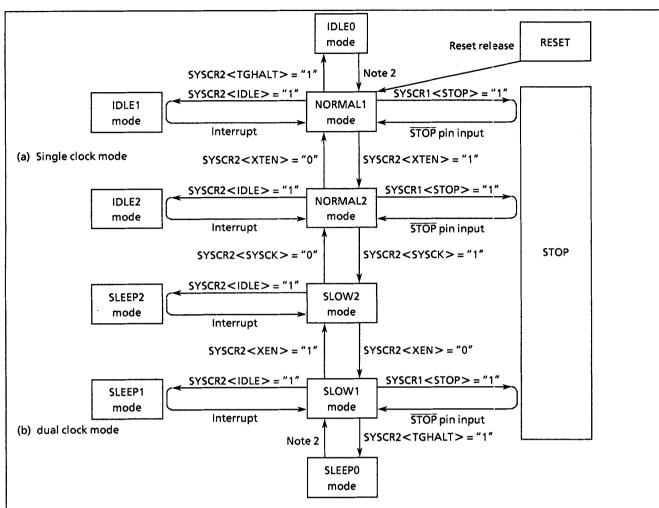
#### ⑦ SLEEP0 mode

In this mode, all the circuit, except oscillator and the Timer-Base-Timer, stops operation. This mode is enabled by setting "1" on bit TGHALT on the system control register 2 (SYSCR2). When SLEEP0 mode starts, the CPU stops and the timing generator stops feeding the clock to the peripheral circuits other than TBT. Then, upon detecting the falling edge of the source clock selected with TBTCR < TBTCK >, the timing generator starts feeding the clock to all peripheral circuits. When returned from SLEEP0 mode, the CPU restarts operating, entering SLOW1 mode back again. SLEEP0 mode is entered and returned regardless of how TBTCR < TBTEN > is set. When IMF = "1", EF<sub>6</sub> (TBT interrupt individual enable flag) = "1", and TBTCR < TBTEN > := "1", interrupt processing is performed. When SLEEP0 mode is entered while TBTCR < TBTEN > := "1", the INTTBT interrupt latch is set after returning to SLOW1 mode.

#### (3) STOP mode

In this mode, the internal oscillation circuit is turned off, causing all system operations to be halted. The internal status immediately prior to the halt is held with a lowest power consumption during STOP mode.

STOP mode is started by the system control register 1 (SYSCR1), and STOP mode is released by a inputting (either level-sensitive or edge-sensitive can be programmably selected) to the STOP pin. After the warming-up period is completed, the execution resumes with the instruction which follows the STOP mode start instruction.



Note 1: NORMAL1 and NORMAL2 modes are generically called NORMAL; SLOW1 and SLOW? are called SLOW; IDLE0, IDLE1 and IDLE2 are called IDLE; SLEEP0, SLEEP1 and SLEEP2 are called SLEEP.

Note 2: The mode is released by falling edge of TBTCR < TBTCK > setting.

0	. A.! B. Ø al	Oscil	lator	CPU core	ТВТ	Other	Machine	
Operating Mode		High-freq.	Low-freq.	Cru core	101	Peripherals	Cycle Time	
	RESET		Rese		Reset	Reset		
Single Clock	NORMAL1	Oscilla-	]	Operate		Operate	4/fc [s]	
	IDLE1	tion	Stop		Operate	Operate		
	IDLE0	]		Halt		Halt	_	
	STOP	Stop			Halt	Пац		
	NORMAL2			Operate with				
		<u> </u>		High Freq.			4/fc [s]	
	IDLE2	Oscilla-		Halt				
	SLOW2	tion		Operate with				
Dural		ļ	Oscilla-	Low Freq.	Operate	Operate		
Dual Clock	SLEEP2		tion	Halt			4/fs [s]	
CIOCK	SLOW1			Operate with			4/15 [5]	
		C+on		Low Freq.				
	SLEEP1	Stop						
	SLEEP0	}		Halt		Halt		
	STOP	1	Stop		Halt	ndit		

Figure 1-7. Operating Mode Transition Diagram

26/fs

# **System Control Register 1**

6

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2 1

SYSCR1  $(0038_{H})$ 

STOP REL	M RETM OUTEN WUT	(Initial value: 0000 ()0**)				
STOP	STOP mode start	0: CPU core and peripherals remain active 1: CPU core and peripherals are halted (start STOP mode)				
RELM	Release method for STOP mode	Edge-sensitive release     Level-sensitive release				
RETM	Operating mode after STOP mode	0: Return to NORMAL1/2 mode 1: return to SLOW1 mode				
OUTEN	Port output during STOP mode	0: High Impedance 1: Output Kept	R/W			
WUT	Warming-up time at releasing STOP mode	Return to NORMAL mode   Return to SLOW mode				

0

Note 1: Always set RETM to "0" when transiting from NORMAL mode to STOP mode. Always set RETM to "1" when transiting from SLOW mode to STOP mode.

Note 2: When STOP mode is released with RESET pin input, a return is made to NORMAL1 regardless of

214/fc

- the RETM contents.
- Note 3: fc; High-frequency clock [Hz], fs; Low-frequency clock [Hz], \*; Don't care

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- Note 4: Bits 1 and 0 in SYSCR1 are read as undefined data when a read instruction is executed.

  Note 5: As the hardware becomes STOP mode under OUTEN = "0", input value is fixed to "0"; therefore it may cause interrupt request on account of falling edge.
- Note 6: When the Key on wake-up is used, the edge release can not function according to some conditions. It is recommended to set the level release (RELM = "1").
- Note 7: Port P20 is used as STOP pin. Therefore, when stop mode is started, OUTEN does not affect to P20, and P20 becomes High-Z mode.

### **System Control Register 2**

SYSCR2  $(0039_{H})$ 

XEN	XTEN	SYSCK	IDLE	TGHALT	(Initial value: 1000 *0**)	
XEI	N	High-fre control	equenc	y oscillator	Turn off oscillation     Turn on oscillation	
XTE	N	Low-fre control	quency	oscillator	O: Turn off oscillation     Turn on oscillation	
SYSC	СК	Main sy (write) / monitor	main s	ock select system clock	0: High-frequency clock 1: Low-frequency clock	R/W
IDL		control		ndog timer P1/2 mode)	0: CPU and watchdog timer remain active 1: CPU and watchdog timer are stopped (start IDLE1/2, SLEEP1/2 mode)	
TGHA	ALT	TG cont (IDLE0,		mode)	0: Feeding clock to all peripherals from TG 1: Stop feeding clock to peripherals except TBT from TG. (Start IDLE0, SLEEP0 mode)	

Note 1: XEN and SYSCK are automatically overwritten in accordance with the contents of RETM (bit 5 in SYSCR1) when STOP mode is released. But XTEN is not change.

RETM	operating mode after STOP mode	XEN	SYSCK
0	NORMAL1/2 mode	1	0
1	SLOW1 mode	0	1

- Note 2: A reset is applied (RESET pin output goes low) if both XEN and XTEN are cleared to "0", XEN is cleared to "0" when SYSCK = "0", or XTEN is cleared to "0" when SYSCK = "0".
- Note 3: \*; Don't care, TG; Timing generator
- Note 4: Bits 3, 1 and 0 in SYSCR2 are always read as undefined value.
- Note 5: Do not set IDLE and TGHALT to "1" simultaneously.

7 6 5 4 3 2 1 0

- Note 6: Because returning from IDLEO/SLEEPO to NORMAL1/SLOW1 is executed by the asynchronous internal clock, the period of IDLE0/SLEEPO mode might be shorter than the period setting by TBTCR < TBTCK >.
- Note 7: When IDLE1/2 or SLEEP1/2 mode is released, IDLE is automatically cleared to "0".
- Note 8: When IDLEO or SLEEPO mode is released, TGHALT is automatically cleared to "O".

Figure 1-8. System Control Registers

# 1.4.4 Operating mode control

### (1) STOP mode

STOP mode is controlled by the system control register 1, the STOP pin input and key wake-up input (STOP2 to STOP5) which is controlled by the STOP mode release control register (STOPCR). The STOP pin is also used both as a port P20 and an INT5 (external interrupt input 5) pin.

STOP mode is started by setting STOP (bit 7 in SYSCR1) to "1". During STOP mode, the following

- STOP mode is started by setting STOP (bit 7 in SYSCR1) to "1". During STOP mode, the following status is maintained.
- (1) Oscillations are turned off, and all internal operations are halted.
- ② The data memory, registers, the program status word and port output latches are all held in the status in effect before STOP mode was entered.
- 3) The prescaler and the divider of the timing generator are cleared to "0".
- 4 The program counter holds the address 2 ahead of the instruction (e.g. [SET (SYSCR1).7]) which started STOP mode.

STOP mode includes a level-sensitive mode and an edge-sensitive mode, either of which can be selected with the RELM (bit 6 in SYSCR1). Do not use any STOPx (x; 2to 5) pin input for releasing STOP mode in edge-sensitive mode.

- Note 1: STOP pin doesn't have the control register such as STOPCR, so when STOP mode is relesed by STOPx (x; 2 to 5), P20 pin should be used as STOP function.
- Note 2: During STOP period (from start of STOP mode to end of warming-up), due to changes in the external interrupt pin signal, interrupt latches may be set to "1" and interrupts may be accepted immediately after STOP mode is released. Before starting STOP mode, therefore, disable interrupts. Also, before enabling interrupts after STOP mode is released, clear unnecessary interrupt latches.

### a. Level-sensitive release mode (RELM="1")

In this mode, STOP mode is released by setting the  $\overline{STOP}$  pin high or setting the STOPx (x; 2 to 5) pin input which is enabled by STOPCR. This mode is used for capacitor back-up when the main power supply is cut off and long term battery back-up.

When the STOP pin input is high or STOPx (x; 2 to 5) pin input which is enabled by STOPCR is low, executing an instruction which starts STOP mode will not place in STOP mode but instead will immediately start the release sequence (warm-up). Thus, to start STOP mode in the level-sensitive release mode, it is necessary for the program to first confirm that the STOP pin input is low and STOPx (x; 2 to 5) pin input which is enabled by STOPCR is high. The following two methods can be used for confirmation.

- ① Testing a port P20.
- ② Using an external interrupt input INT5 (INT5 is a falling edge-sensitive input).

Example 1: Starting STOP mode from NORMAL mode by testing a port P20.

LD (SYSCR1), 01010000B; Sets up the level-sensitive release mode

SSTOPH: TEST (P2PRD). 0 ; Wait until the STOP pin input goes low level

JRS F, SSTOPH

SET (SYSCR1). 7; Starts STOP mode

Example 2: Starting STOP mode from NORMAL mode with an INT5 interrupt.

PINT5: TEST (P2PRD). 0 ; To reject noise, STOP mode does not start if

JRS F, SINT5 port P20 is at high

LD (SYSCR1), 01010000B; Sets up the level-sensitive release mode.

SET (SYSCR1). 7 ; Starts STOP mode

SINT5: RETI

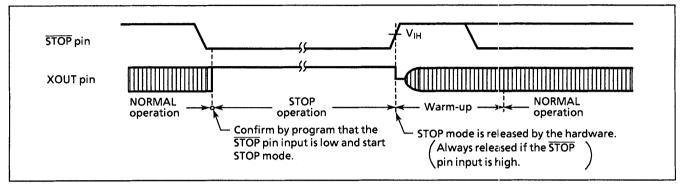


Figure 1-9. Level-sensitive release Mode

Note 1: Even if the STOP pin input is low or STOPx (x; 2 to 5) pin input which is enabled by STOPCR is high after warming up start, the STOP mode is not restarted.

Note 2: In this case of changing to the level-sensitive mode from the edge-sensitive mode, the release mode is not switched until a rising edge of the STOP pin input is detected.

# b. Edge-sensitive release mode (RELM="0")

In this mode, STOP mode is released by a rising edge of the  $\overline{STOP}$  pin input. This is used in applications where a relatively short program is executed repeatedly at periodic intervals. This periodic signal (for example, a clock from a low-power consumption oscillator) is input to the  $\overline{STOP}$  pin. In the edge-sensitive release mode, STOP mode is started even when the  $\overline{STOP}$  pin input is high level. Do not use any STOPx (x; 2 to 5) pin input for releasing STOP mode in edge-sensitive release mode.

Example: Starting STOP mode from NORMAL mode

LD (SYSCR1), 10010000B; Starts after specified to the edge-sensitive release mode

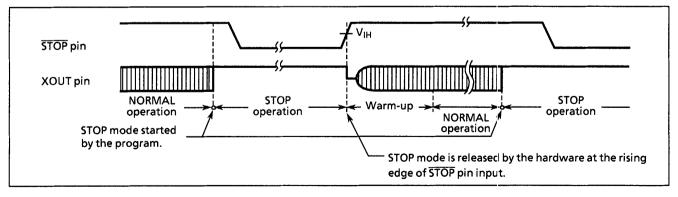


Figure 1-10. Edge-sensitive release Mode

STOP mode is released by the following sequence.

- ① In the dual-clock mode, when returning to NORMAL2 or SLOW2, both the high-frequency and low-frequency clock oscillators are turned on; when returning to SLOW1 mode, only the low-frequency clock oscillator is turned on. In the signal-clock mode, only the high-frequency clock oscillator is turned on.
- ② A warm-up period is inserted to allow oscillation time to stabilize. During warm-up, all internal operations remain halted. Four different warm-up times can be selected with the WUT (bits 2 and 3 in SYSCR1) in accordance with the resonator characteristics.
- ③ When the warm-up time has elapsed, normal operation resumes with the instruction following the STOP mode start instruction. The start is made after the prescaler and the divider of the timing generator are cleared to "0".

WUT -	Warm-up Time [ms]					
WUI	Return to NORMAL mode	Return to SLOW mode				
00	12.288	750				
01	4.096	250				
10	3.072	5.85				
11	1 024	1 95				

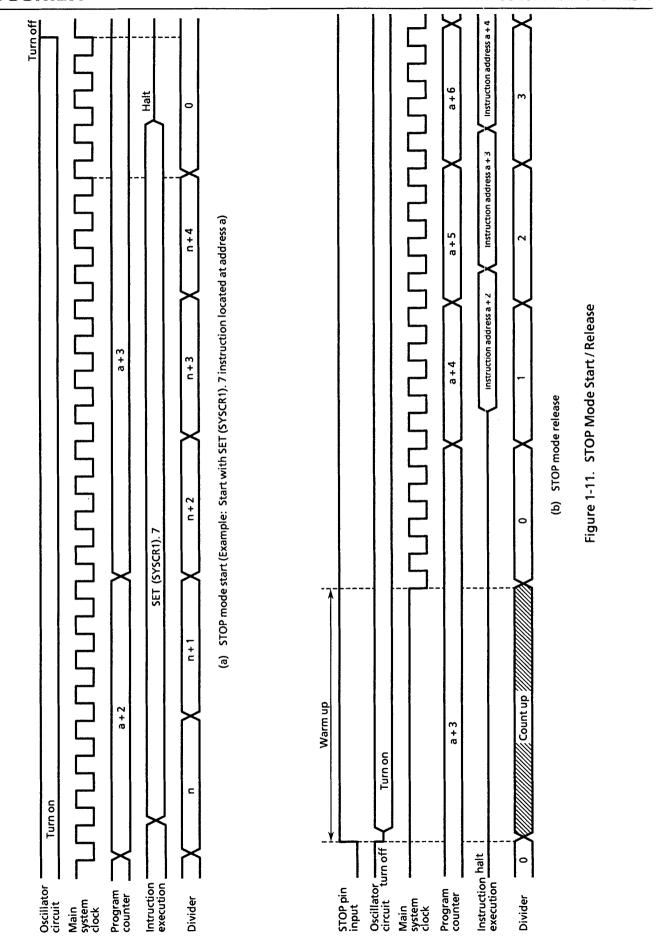
Table 1-1. Warm-up Time Example (at fc = 16.0 MHz, fs = 32.768 kHz)

Note: The warm-up time is obtained by dividing the basic clock by the divider: therefore, the warm-up time may include a certain amount of error if there is any fluctuation of the oscillation frequency when STOP mode is released. Thus, the warm-up time must be considered an approximate value.

STOP mode can also be released by inputting low level on the  $\overline{RESET}$  pin, which immediately performs the normal reset operation.

Note: When STOP mode is released with a low hold voltage, the following cautions must be observed.

The power supply voltage must be at the operating voltage level before releasing STOP mode. The RESET pin input must also be "H" level, rising together with the power supply voltage. In this case, if an external time constant circuit has been connected, the RESET pin input voltage will increase at a slower pace than the power supply voltage. At this time, there is a danger that a reset may occur if input voltage level of the RESET pin drops below the non-inverting high-level input voltage (hysteresis input).



### (2) IDLE1/2 mode, SLEEP1/2 mode

IDLE1/2 and SLEEP1/2 modes are controlled by the system control register 2 (SYSCR2) and maskable interrupts. The following status is maintained during these modes.

- ① Operation of the CPU and watchdog timer (WDT) is halted. On-chip peripherals continue to operate.
- ② The data memory, CPU registers, program status word and port output latches are all held in the status in effect before these modes were entered.
- 3 The program counter holds the address 2 ahead of the instruction which starts these modes.

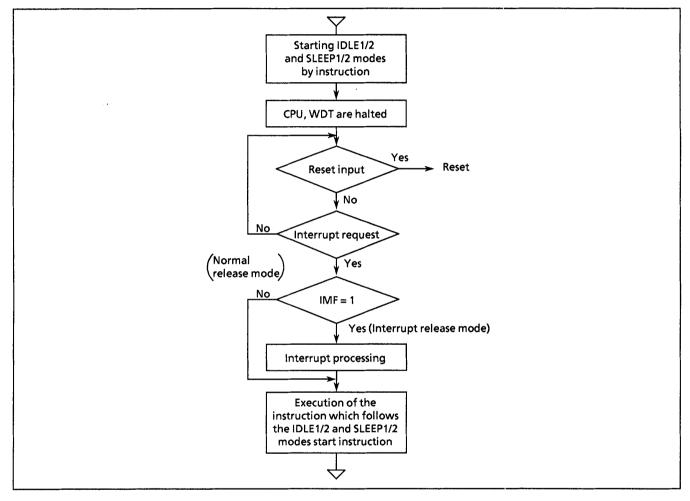


Figure 1-12. IDLE1/2, SLEEP1/2 Modes

• Start the IDLE1/2 and SLEEP1/2 modes

When IDLE1/2 and SLEEP1/2 modes start, set SYSCR2<IDLE> to "1".

Release the IDLE1/2 and SLEEP1/2 modes

IDLE1/2 and SLEEP1/2 modes include a normal release mode and an interrupt release mode. These modes are selected by interrupt master enable flag (IMF).

After releasing IDLE1/2 and SLEEP1/2 modes, the SYSCR2<IDLE> is automatically cleared to "0" and the operation mode is returned to the mode preceding IDLE1/2 and SLEEP1/2 modes. IDLE1/2 and SLEEP1/2 modes can also be released by inputting low level on the  $\overline{\text{RESET}}$  pin. After releasing reset, the operation mode is started from NORMAL1 mode.

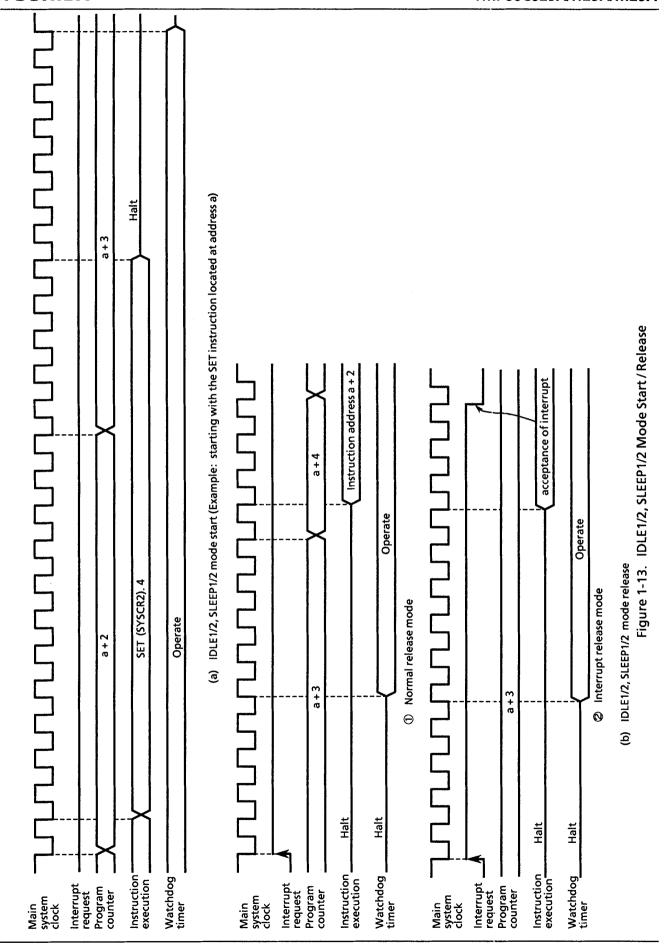
# a. Normal release mode (IMF="0")

IDLE1/2 and SLEEP1/2 modes are released by any interrupt source enabled by the individual interrupt enable flag (EF). After the interrupt is generated, the program operation is resumed from the instruction following the IDLE1/2 and SLEEP1/2 modes start instruction. Normally, the interrupt latches (IL) of the interrupt source used for releasing must be cleared to "0" by load instructions.

### b. Interrupt release mode (IMF="1")

IDLE 1/2 and SLEEP 1/2 modes are released by any interrupt source enabled with the individual interrupt enable flag (EF) and INTTBT interrupt processing is started. After the interrupt is processed, the program operation is resumed from the instruction following the instruction, which starts IDLE 1/2 and SLEEP 1/2 modes.

Note: When a watchdog timer interrupts is generated immediately before IDLE1/2 and SLEEP1/2 mode are started, the watchdog timer interrupt will be processed but IDLE1/2 and SLEEP1/2 mode will not be started.



### (3) IDLEO, SLEEPO mode (IDLEO, SLEEPO)

IDLE0 and SLEEP0 modes are controlled by the system control register 2 (SYSCR2) and the time base timer control register (TBTCR). The following status is maintained during IDLE0 and SLEEP0 modes.

- ① Timing generator stops feeding clock to peripherals except TBT.
- ② The data memory, CPU registers, program status word and port output latches are all held in the status in effect before IDLE0 and SLEEP0 modes were entered.
- 3 The program counter holds the address 2 ahead of the instruction which starts IDLE0 and SLEEP0 modes.

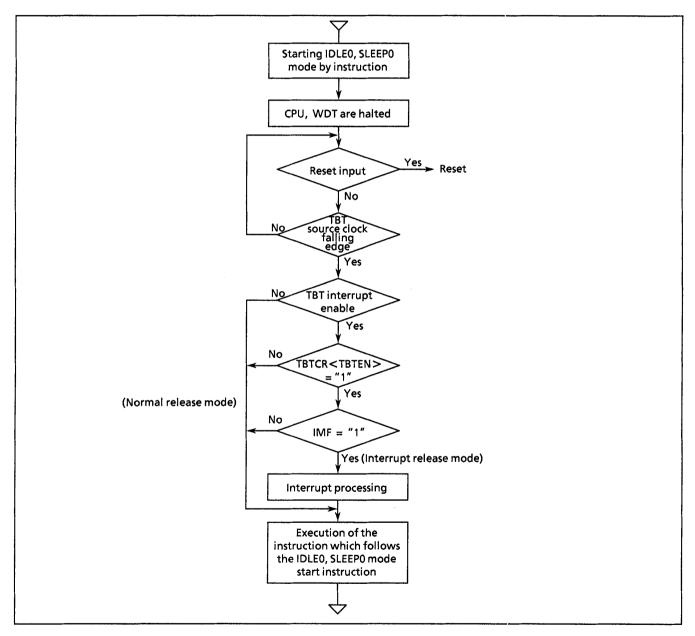


Figure 1-14. IDLEO, SLEEPO mode

• Start the IDLE0 and SLEEP0 modes

When IDLE0 and SLEEP0 modes start, set SYSCR2<TGHALT> to "1".

• Release the IDLE0 and SLEEP modes

IDLE0 and SLEEP0 modes include a normal release mode and an interrupt release mode. These modes are selected by interrupt master flag (IMF).

After releasing IDLE0 and SLEEP0 modes, the SYSCR2 < TGHALT > is automatically cleared to "0" and the operation mode is returned to the mode preceding IDLE0 and SLEEP0 modes. Before starting the IDLE0 or SLEEP0 mode, when the TBTCR < TBTEN > is set to "1", INTTBT interrupt latch is set to "1".

IDLE0 and SLEEP0 modes can also be released by inputting low level on the  $\overline{RESET}$  pin. After releasing reset, the operation mode is started from NORMAL1 mode.

Note: IDLEO and SLEEPO modes start/release without reference to TBTCR < TBTEN > setting.

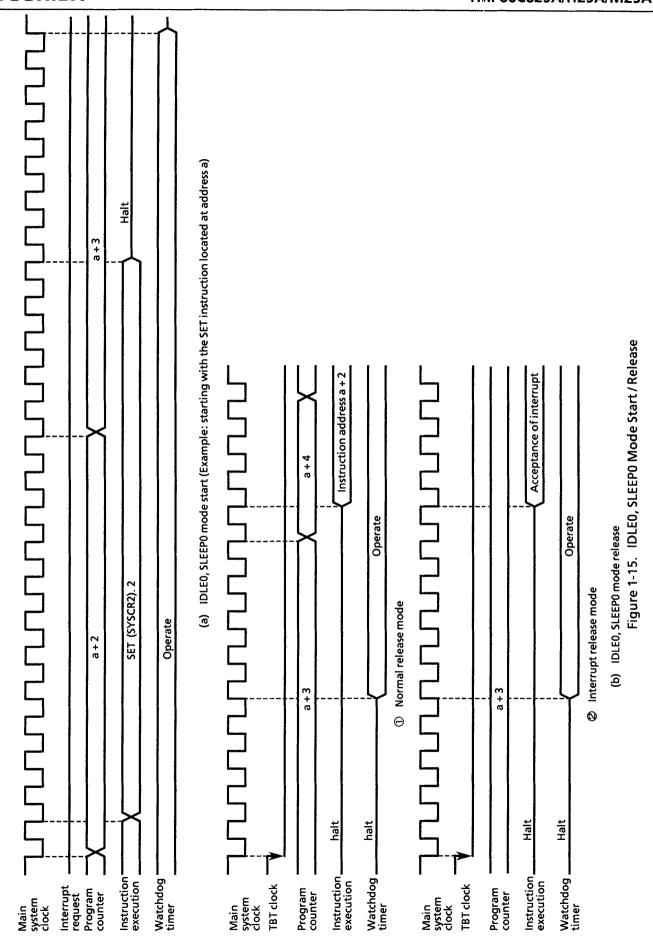
# a. Normal release mode (IMF="0")

IDLE0 and SLEEP0 modes are released by the source clock falling edge, which is setting by the TBTCR<TBTCK> without reference to individual interrupt enable flag (EF). After the falling edge is detected, the program operation is resumed from the instruction following the IDLE0 and SLEEP0 modes start instruction.

b. Interrupt release mode (IMF="1", TBTCR < TBTEN > = "1")

IDLE0 and SLEEP0 modes are released by the source clock falling edge, which is setting by the TBTCR<TBTCK> at INTTBT interrupt source enabled with the individual interrupt enable flag (EF) and INTTBT interrupt processing is started.

- Note 1: Because returning from IDLEO, SLEEPO to NORMAL1, SLOW1 is executed by the asynchronous internal clock, the period of IDLEO, SLEEPO mode might be the shorter than the period setting by TBTCR<TBTCK>.
- Note 2: When a watchdog timer interrupt is generated immediately before IDLEO / SLEEPO mode is started, the watchdog timer interrupt will be processed but IDLEO / SLEEPO mode will not be started.



#### (4) SLOW mode

SLOW mode is controlled by the system control register 2 (SYSCR2).

The following is the methods to switch the mode with the warming-up counter (TC4, 3).

# a. Switching from NORMAL2 mode to SLOW1 mode

First, set SYSCK (bit 5 in SYSCR2) to switch the main system clock to the low-frequency clock for SLOW2 mode.

Next, clear XEN (bit 7 in SYSCR2) to turn off high-frequency oscillation.

Note: The high-frequency clock oscillation can be continued to return quickly to NORMAL2 mode.

When the low-frequency clock oscillation is unstable, wait until oscillation stabilizes before performing the above operations. The timer / counter 4, 3 (TC4, TC3) can conveniently be used to confirm that lowfrequency clock oscillation has stabilized.

Example1: Switching from NORMAL2 mode to SLOW1 mode.

SET (SYSCR2).5

 $SYSCR2 < SYSCK > \leftarrow 1$ 

(switches the main system clock to the low-frequency

clock for SLOW2)

CLR (SYSCR2). 7

 $SYSCR2 < XEN > \leftarrow 0$ 

(turns off high-frequency oscillation)

Example 2: Switching to the SLOW1 mode after low-frequency clock has stabilized.

SET (SYSCR2).6

 $SYSCR2 < XTEN > \leftarrow 1$ 

LD(TC3CR), 43H Sets mode for TC4, TC3 (16-bit TC, fs for source)

LD(TC4CR), 05H

LDW (TTREG3), 8000H ;

Sets warming-up time

(depend on oscillator accompanied)

DI

 $IMF \leftarrow 0$ 

SET (EIRH), 3 **Enables INTTC4** 

EI

 $IMF \leftarrow 1$ 

SET (TC4CR). 3

Starts TC4, 3

PINTTC4: CLR (TC4CR). 3

Stops TC4, 3

SET (SYSCR2). 5 SYSCR2<SYSCK> ←1 (Switches the main system clock

to the low-frequency clock)

CLR (SYSCR2). 7

 $SYSCR2 < XEN > \leftarrow 0$ 

(Turns off high-frequency oscillation)

RETI

VINTTC4: DW PINTTC4

INTTC4 vector table

# b. Switching from SLOW1 mode to NORMAL2 mode

First, set XEN (bit 7 in SYSCR2) to turn on the high-frequency oscillation. When time for stabilization (warm-up) has been taken by the timer / counter 4, 3 (TC4, 3), clear SYSCK (bit 5 in SYSCR2) to switch the main system clock to the high-frequency clock.

Note 1: After SYSCK is cleared to "0", executing the instructions is continued by the low-frequency clock for the period synchronized with low-frequency and high-frequency clocks.

High-frequency clock Low-frequency clock Main system clock SYSCK Note 2: SLOW mode can also be released by inputting low level on the RESET pin, which immediately performs the reset operation. After reset, the TMP86C829A/H29A/M29A are placed in NORMAL1 mode.

Example: Switching from the SLOW1 mode to the NORMAL2 mode (fc=16 MHz, warm-up time is 4.0 ms).

SET (SYSCR2), 7

; SYSCR2<XEN $> \leftarrow 1$  (Starts high-frequency oscillation)

LD (TC3CR), 63H

; Sets mode for TC4, TC3 (16-bit TC, fc for source)

LD (TC4CR), 05H

LD (TTREG4), 0F8H; Sets warming-up time

DI ;  $IMF \leftarrow 0$ 

SET (EIRH), 3 : Enables INTTC4

EI :  $IMF \leftarrow 1$ 

SET (TC4CR). 3 ; Starts TC4, 3

:

PINTTC4: CLR (TC4CR). 3 ; Stops TC4, 3

CLR (SYSCR2).5 ; SYSCR2<SYSCK $>\leftarrow$ 0

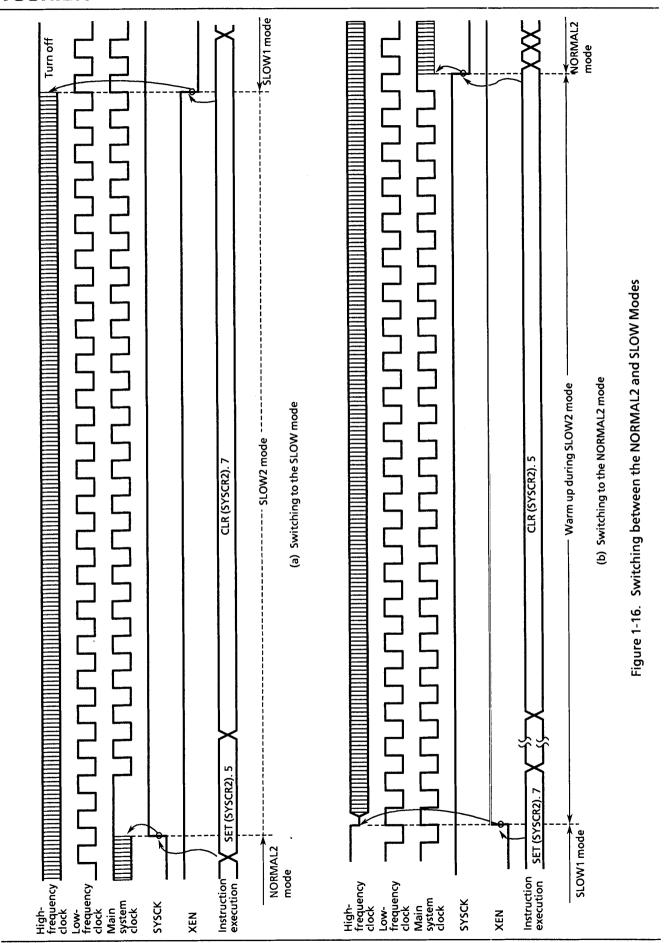
(Switches the main system clock to the high-frequency

clock)

RETI

:

VINTTC4: DW PINTTC4 ; INTTC4 vector table



# 1.5 Interrupt Control Circuit

The TMP86C829A/H29A/M29A are a total (Reset is excluded) of 15 interrupt sources for 19 interrupt factors; 3 of the sources are multiplexed. Multiple interrupt with priorities is available. 4 of the internal factors are non-maskable interrupts, and the rest of them are maskable interrupts.

Interrupt sources are provided with interrupt latches (IL), which hold interrupt requests, and independent vectors. The interrupt latch is set to "1" by the generation of its interrupt request which requests the CPU to accept its interrupts. Interrupts are enabled or disabled by software using the interrupt master enable flag (IMF) and interrupt enable flag (EF). If more than one interrupts are generated simultaneously, interrupts are accepted in order which is dominated by hardware. However, there are no prioritized interrupt factors among non-maskable interrupts.

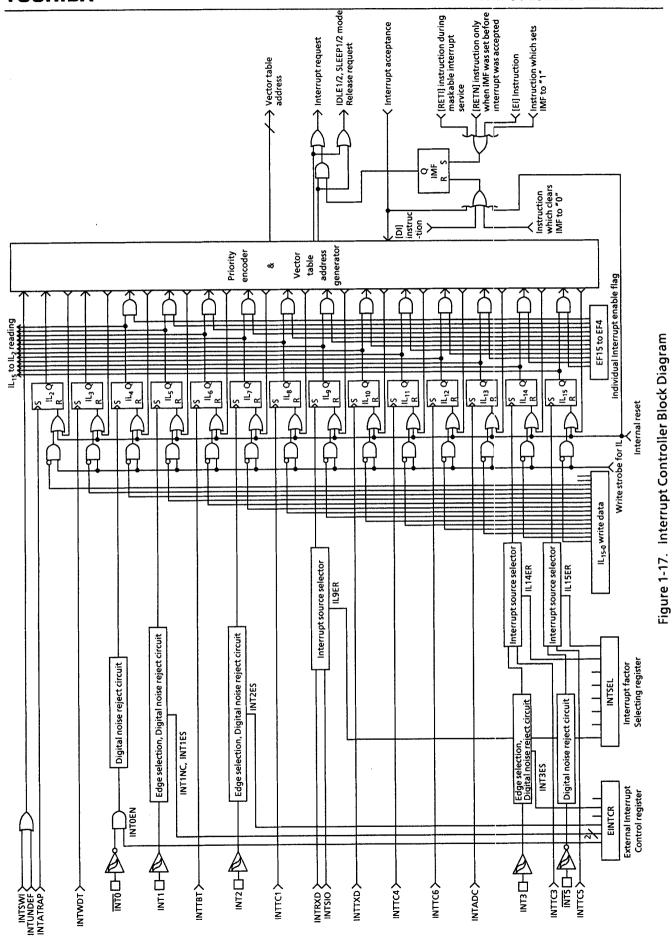
	Interrupt Factors	Enable Condition	Interrupt Latch	Vector Address	Priority
Internal / External	(Reset)	Non-maskable		FFFE <sub>H</sub>	High 1
Internal	INTSWI (Software interrupt)	Non-maskable		FFFC <sub>H</sub>	2
Internal	INTUNDEF (Executed the Undefined Instruction interrupt)	Non-maskable		FFFC <sub>H</sub>	2
Internal	INTATRAP (Address Trap interrupt)	Non-maskable	IL <sub>2</sub>	FFFA <sub>H</sub>	2
Internal	INTWDT (Watchdog Timer interrupt)	Non-maskable	IL <sub>3</sub>	FFF8 <sub>H</sub>	2
External	INTO (External interrupt 0)	IMF = 1, EF <sub>4</sub> = 1	IL <sub>4</sub>	FFF6 <sub>H</sub>	5
External	INT1 (External interrupt 1)	IMF = 1, EF <sub>5</sub> = 1	IL <sub>5</sub>	FFF4 <sub>H</sub>	6
Internal	INTTBT (Time Base Timer interrupt)	$IMF = 1, EF_6 = 1$	1L <sub>6</sub>	FFF2 <sub>H</sub>	7
External	INT2 (External interrupt2)	IMF = 1, EF <sub>7</sub> = 1	IL <sub>7</sub>	FFF0 <sub>H</sub>	8
Internal	INTTC1 (18-bit TC1 interrupt)	IMF = 1, EF <sub>8</sub> = 1	IL <sub>8</sub>	FFEE <sub>H</sub>	9
Internal	INTRxD (UART received interrupt)	IMF = 1, EF <sub>9</sub> = 1	IL9	FFEC <sub>H</sub>	10
Internal	INTSIO (SIO interrupt)				
Internal	INTTxD (UART transmitted interrupt)	$IMF = 1, EF_{10} = 1$	IL <sub>10</sub>	FFEA <sub>H</sub>	11
Internal	INTTC4 (TC4 interrupt)	$IMF = 1, EF_{11} = 1$	IL <sub>11</sub>	FFE8 <sub>H</sub>	12
Internal	INTTC6 (TC6 interrupt)	$IMF = 1, EF_{12} = 1$	IL <sub>12</sub>	FFE6 <sub>H</sub>	13
Internal	INTADC (AD converter interrupt)	IMF = 1, $EF_{13} = 1$	IL <sub>13</sub>	FFE4 <sub>H</sub>	14
External Internal	INT3 (External interrupt 3) INTTC3 (TC3 interrupt)	IMF = 1, EF <sub>14</sub> = 1	IL <sub>14</sub>	FFE2 <sub>H</sub>	15
External Internal	INT5 (External interrupt 5) INTTC5 (TC5 interrupt)	IMF = 1, EF <sub>15</sub> = 1	IL <sub>15</sub>	FFEO <sub>H</sub>	Low 16

Table 1-2. Interrupt Sources

Note 1: The following interrupt factors share their interrupt source; the factor is selected on the register INTSEL.

- 1) INTRXD and INTSIO share the source whose priority is 10.
- 2) INT3 and INTTC3 share the source whose priority is 15.
- 3) INT5 and INTTC5 share the source whose priority is 16.

Note 2: 2 alternatives are to be chosen in case INTATRAP (address trap interrupt) is executed: interrupt or reset. (for detail, see 2.4.5 address trap interrupt (INTATRAP)



2001-09-04

# (1) Interrupt Latches (IL<sub>15</sub> to IL<sub>2</sub>)

An interrupt latch is provided for each interrupt source, except for a software interrupt. When interrupt request is generated, the latch is set to "1", and the CPU is requested to accept the interrupt if its interrupt is enabled. All interrupt latches are initialized to "0" during reset.

The interrupt latches are located on address  $003C_H$  and  $003D_H$  in SFR area. Except for IL<sub>3</sub> and IL<sub>2</sub>, each latch can be cleared to "0" individually by instruction (However, the read-modify-write instructions such as bit manipulation or operation instructions cannot be used. Interrupt request would be cleared inadequately if interrupt is requested while such instructions are executed.). Thus interrupt request can be canceled /initialized by software.

Interrupt latches are not set to "1" by an instruction. Since interrupt latches can be read, the status for interrupt requests can be monitored by software.

Note: When manipulating IL, clear IMF (to disable interrupts) beforehand.

Example 1: Clears interrupt latches

DI ;  $IMF \leftarrow 0$ 

LDW (ILL), 11101000001111111B ;  $IL_{10}$  to  $IL_{6} \leftarrow 0$ 

EI ;  $IMF \leftarrow 1$ 

Example 2: Reads interrupt latches

LD WA, (ILL) ;  $W \leftarrow IL_H$ ,  $A \leftarrow IL_L$ 

Example 3: Tests an interrupt latches

TEST (ILL). 7 ; if  $IL_7=1$  then jump

JR F, SSET

# (2) Interrupt Enable Register (EIR)

The interrupt enable register (EIR) enables and disables the acceptance of interrupts, except for the non-maskable interrupts (software interrupt, undefined instruction interrupt, address trap interrupt and watchdog interrupt). Non-maskable interrupt is accepted regardless of the contents of the EIR. The EIR consists of an interrupt master enable flag (IMF) and the individual interrupt enable flags (EF). These registers are located on address 003AH and 003BH in SFR area, and they can be read and written by an instructions (including read-modify-write instructions such as bit manipulation or operation instructions).

### a) Interrupt master enable flag (IMF)

The interrupt enable register (IMF) enables and disables the acceptance of the whole maskable-interrupt. While IMF="0", all maskable interrupts are not accepted regardless of the status on each individual interrupt enable flag (EF). By setting IMF to "1", the interrupt becomes acceptable if the individuals are enabled. When an interrupt is accepted, IMF is cleared to "0" after the latest status on IMF is stacked. Thus the maskable interrupts which follow are disabled. By executing return interrupt instruction [RETI/RETN], the stacked data, which was the status before interrupt acceptance, is loaded on IMF again.

The IMF is located on bit0 in EIRL (address: 003A<sub>H</sub> in SFR), and can be read and written by an instruction. The IMF is normally set and cleared by [EI] and [DI] instruction respectively. During reset, the IMF is initialized to "0", and maskable interrupts are not accepted until it is set to "1".

# b) Individual interrupt enable flags (EF<sub>15</sub> to EF<sub>4</sub>)

Each of these flags enables and disables the acceptance of its maskable interrupt. Setting the corresponding bit of an individual interrupt enable flag to "1" enables acceptance of its interrupt, and setting the bit to "0" disables acceptance. The individual interrupt enable flags ( $EF_{15}$  to  $EF_4$ ) are located on EIRL to EIRH (address:  $003A_H$  to  $003B_H$  in SFR), and can be read and written by an instruction. During reset, all the individual interrupt enable flags ( $EF_{15}$  to  $EF_4$ ) are initialized to "0" and all maskable interrupts are not accepted until they are set to "1".

Note: Before manipulating EF, be sure to clear IMF (interrupt disabled). Then set IMF newly again after operating on the interrupt enables flag (EF). Normally, IMF is clear to "0" automatically on service routine. When IMF is set to "1" for using a multiple interrupt on service routine, be sure to process as is the case with EF.

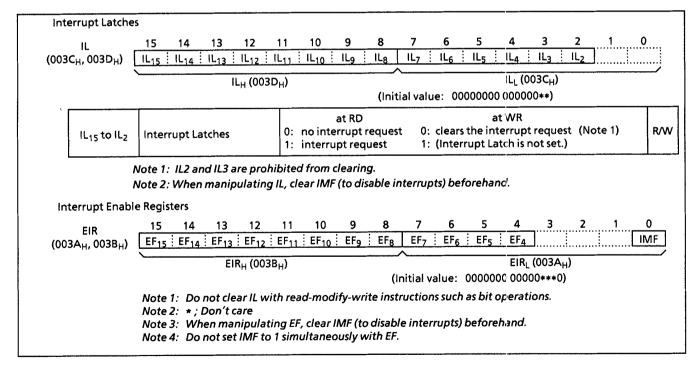


Figure 1-18. Interrupt Latch (IL), Interrupt Enable Registers (EIR)

# (3) Selecting interrupt factor (INTSEL)

Each interrupt factor, that shares its interrupt source with other factors, enables its interrupt latch (IL) only if it is selected on INTSEL. The interrupt controller does not hold the interrupt request, while the factor generates the interrupt request is not selected on INTSEL. Therefore, set INTSEL appropriately before interrupt factors arises.

	7	6	5	4	3	2	1	0	_	
INTSEL (003E <sub>H</sub> )	<u> </u>	IL9ER	- :	<del>-</del>	 -		IL14ER	IL15ER	(Initial value: *0** **00)	
	IL9ER		ative of D or INTSI	0		INTRXD INTSIO				
	IL14ER		ative of r INTTC3			INT3 INTTC3				R/W
	IL15ER		ative of			INT5 INTTC5				

Figure 1-19. Interrupt Source Selector

**Execute RETI instruction** 

#### 1.5.1 Interrupt Sequence

An interrupt request, which raised interrupt latch, is held, until interrupt is accepted or interrupt latch is cleared to "0" by resetting or an instruction. Interrupt acceptance sequence requires 8 machine cycles (4  $\mu$ s at 8.0 MHz) after the completion of the current instruction. The interrupt service task terminates upon execution of an interrupt return instruction [RETI] (for maskable interrupts) or [RETN] (for non-maskable interrupts). Figure 1-20 shows the timing chart of interrupt acceptance processing.

- (1) Interrupt acceptance processing is packaged as follows.
  - a) The interrupt latch (IL) for the interrupt source accepted is cleared to "0".
  - b) The contents of the program counter (PC) and the program status word, including the interrupt master enable flag (IMF), are saved (pushed) on the stack in sequence of PSW+IMF, PCH,PCL. Meanwhile, the stack pointer (SP) is decremented by 3.
  - c) The interrupt master enable flag (IMF) is cleared to "0" in order to disable the acceptance of any following interrupt.
  - d) The entry address (interrupt vector) of the corresponding interrupt service program, loaded on the vector table, is transferred to the program counter.
  - e) The instruction stored at the entry address of the interrupt service program is executed.

Interrupt acceptance

Note: When the contents of PSW are saved on the stack, the contents of IMF are also saved.

Interrupt service task

Interrupt request

Note 1: a; return address entry address b; entry address c; address which RETI instruction is stored

Note 2: On condition that interrupt is enabled, it takes 38/fc [s] or 38/fs [s] at maximum (If the interrupt latch is set at the first machine cycle on 10 cycle instruction) to start interrupt acceptance processing since its interrupt latch

Figure 1-20. Timing chart of Interrupt Acceptance/Return Interrupt instruction

Interrupt latch (IL)

IMF

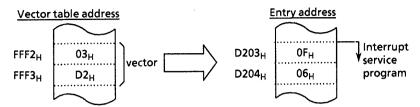
PC

SP

Execute

Instructio

Execute Instruction Example: Correspondence between vector table address for INTTBT and the entry address of the interrupt service program



A maskable interrupt is not accepted until the IMF is set to "1" even if the maskable interrupt higher than the level of current servicing interrupt is requested.

In order to utilize nested interrupt service, the IMF is set to "1" in the interrupt service program. In this case, acceptable interrupt sources are selectively enabled by the individual interrupt enable flags. To avoid overloaded nesting, clear the individual interrupt enable flag whose interrupt is currently serviced, before setting IMF to "1". As for non-maskable interrupt, keep interrupt service shorten compared with length between interrupt requests; otherwise the status cannot be recovered as non-maskable interrupt would simply nested.

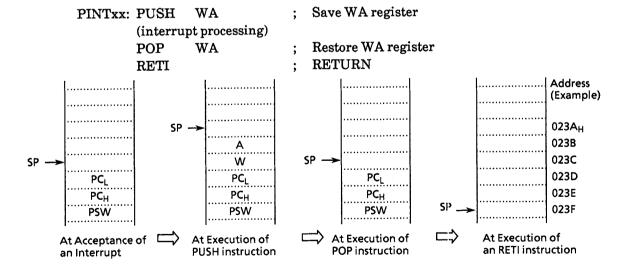
# (2) Saving/Restoring general -purpose registers

During interrupt acceptance processing, the program counter (PC) and the program status word (PSW, includes IMF) are automatically saved on the stack, but the accumulator and others are not. These registers are saved by software if necessary. When multiple interrupt services are nested, it is also necessary to avoid using the same data memory area for saving registers. The following methods are used to save/restore the general-purpose registers.

# a) using PUSH and POP instructions

To save only a specific register, PUSH and POP instructions are available.

Example: save/store register using PUSH and POP instructions



# b) using data transfer instructions

To save only a specific register without nested interrupts, data transfer instructions are available.

Example: save/store register using data transfer instructions

PINTxx: LD (GSAVA), A ; Save A register

(interrupt processing)

LD A, (GSAVA) ; Restore A register

RETI ; RETURN

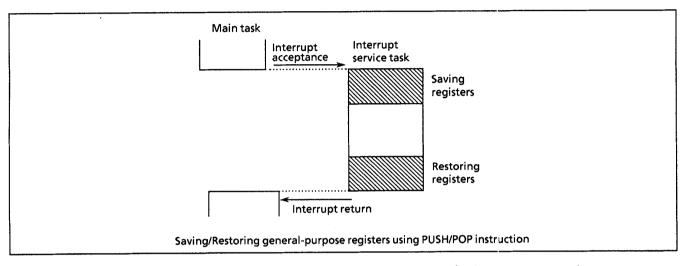


Figure 1-21. Saving/Restoring general-purpose registers under interrupt processing

# (3) Interrupt return

Interrupt return instructions [RETI] / [RETN] perform as follows.

[RETI] / [RETN] Interrupt Return
 Program Counter (PC) and program status word (PSW, includes IMF) are restored from the stack.
 Stack pointer (SP) is incremented by 3.

As for Address Trap interrupt (INTARTAP), it is required to alter stacked data for program counter (PC) to restarting address, during interrupt service program. Otherwise returning interrupt causes INTATRAP again. When interrupt acceptance processing has completed, stacked data for PC<sub>L</sub> and PC<sub>H</sub> are located on address (SP+1) and (SP+2) respectively.

Note: If [RETN] is executed with the above data unaltered, the program returns to the address trap area and INTATRAP occurs again.

Example 1: returning from address trap interrupt (INTATRAP) service program

PINTxx: POP WA ; Recover SP by 2

LD WA, Return Address;

PUSH WA ; Alter stacked data

(interrupt processing)

RETN ; RETURN

Example 2: restarting without returning interrupt

(In this case, PSW (includes IMF) before interrupt acceptance is discarded.)

PINTxx: INC SP ; Recover SP by 3

INC SP

(interrupt processing)

LD EIRL, data ; Set IMF to "1" or clear it to "0" JP Restart Address ; Jump into restarting address

Note: It is recommended that stack pointer be return to rate before INTATRAP (increment 3 times), if return interrupt instruction [RETN] is not utilized during interrupt service program under INTATRAP (such as Example 2).

Interrupt requests are sampled during the final cycle of the instruction being executed. Thus, the next interrupt can be accepted immediately after the interrupt return instruction is executed.

Note: When the interrupt processing time is longer than the interrupt request generation time, the interrupt service task is performed but not the main task.

### 1.5.2 Software interrupt (INTSW)

Executing the [SWI] instruction generates a software interrupt and immediately starts interrupt processing (INTSW is highest prioritized interrupt).

Use the [SWI] instruction only for detection of the address error or for debugging.

#### (1) Address error detection

 $FF_H$  is read if for some cause such as noise the CPU attempts to fetch an instruction from a non-existent memory address during single chip mode. Code  $FF_H$  is the SWI instruction, so a software interrupt is generated and an address error is detected. The address error detection range can be further expanded by writing  $FF_H$  to unused areas of the program memory. Address-trap reset is generated in case that an instruction is fetched from RAM or SFR areas.

### ② Debugging

Debugging efficiency can be increased by placing the SWI instruction at the software break point setting address.

### 1.5.3 Undefined instruction interrupt (INTUNDEF)

Taking code which is not defined as authorized instruction for instruction causes INTUNDEF. INTUNDEF is generated when the CPU fetches such a code and tries to execute it. INTUNDEF is accepted even if non-maskable interrupt is in process. Contemporary process is broken and INTUNDEF interrupt process starts, soon after it is requested.

Note: The undefined instruction interrupt (INTUNDEF) forces CPU to jump into vector address, as software interrupt (SWI) does.

## 1.5.4 Address trap interrupt (INTATRAP)

Fetching instruction from unauthorized area for instructions (address trapped area) causes reset-output or address trap interrupt (INTATRAP). INTATRAP is accepted even if non-maskable interrupt is in process. Contemporary process is broken and INTATRAP interrupt process starts, soon after it is requested.

Note: The operating mode under address trapped, whether to be reset-output or interrupt processing, is selected on watchdog timer control register (WDTCR).

### 1.5.5 External Interrupts

The TMP86C829A/H29A/M29A have five external interrupt inputs. These inputs are equipped with digital noise reject circuits (pulse inputs of less than a certain time are eliminated as noise). Edge selection is also possible with INT1 to INT3. The  $\overline{\text{INT0}}$  / P63 pin can be configured as either an external interrupt input pin or an input / output port, and is configured as an input port during reset. Edge selection, noise reject control and  $\overline{\text{INT0}}$  / P63 pin function selection are performed by the external interrupt control register (EINTCR).

Source	Pin	Secondary function pin	Enable conditions	Edge	Digital noise reject
INT0	īNTO	P63/AIN3	IMF = 1, EF <sub>4</sub> = 1, INTOEN = 1	Falling edge	Pulses of less than 2/fc [s] are eliminated as noise. Pulses of 6/fc [s] or more are considered to be signals. In the SLOW or the SLEEP mode, pulses of less than 1/fs [s] are eliminated as noise. Pulses of 3/fs [s] or more are considered to be signals.
INT1	INT1	P12/SEG29	IMF · EF <sub>5</sub> = 1		Pulses of less than 15/fc or 63/fc [s] are eliminated as noise. Pulses of 48/fc or 192/fc [s] or more are considered to be signals. In the SLOW or the SLEEP mode, pulses of less
INT2	INT2	P13/SEG28	IMF • EF <sub>7</sub> = 1	Falling edge or Rising edge	than 1/fs [s] are eliminated as noise. Pulses of 3/fs [s] or more are considered to be signals.  Pulses of less than 7/fc [s] are eliminated as noise. Pulses of 24/fc [s] or more are
INT3	INT3	P14/SEG27	IMF · EF <sub>14</sub> = 1 IL14ER = 0		considered to be signals.  In the SLOW or the SLEEP mode, pulses of less than 1/fs [s] are eliminated as noise. Pulses of 3/fs [s] or more are considered to be signals.
INT5	ĪNT5	P20/STOP	IMF · EF <sub>15</sub> = 1 IL15ER = 0	Falling edge	Pulses of less than 2/fc [s] are eliminated as noise. Pulses of 6/fc [s] or more are considered to be signals. In the SLOW or the SLEEP mode, pulses of less than 1/fs [s] are eliminated as noise. Pulses of 3/fs [s] or more are considered to be signals.

Table 1-3. External interrupts

- Note 1: If a noiseless signal is input to the external interrupt pin in the NORMAL 1/2 or IDLE 1/2 mode, the maximum time from the edge of input signal until the IL is set is as follows:
  - ① INT1 pin
- 49/fc[s] (INT1NC = 1), 193/fc[s] (INT1NC = 0)
- ② INT2, INT3 pin 25/fc [s]
- Note 2: Even if the falling edge of INTO pin input is detected at INTOEN = 0, the interrupt latch IL<sub>4</sub> is not set.
- Note 3: When data changed and did a change of I/O when used external interrupt ports as a normal ports, interrupt request signal occurs incorrectly. Handling of prohibition of interrupt enable register (EIR) is necessary.

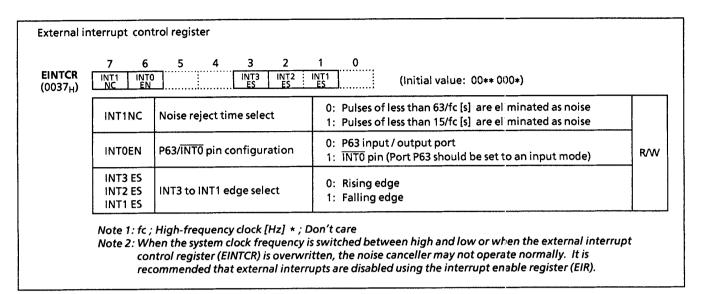


Figure 1-22. External Interrupt Control Register

#### 1.6 Reset Circuit

The TMP86C829A/H29A/M29A have four types of reset generation procedures: an external reset input, an address trap reset output, a watchdog timer reset output and a system clock reset output. Table 1-7 shows on-chip hardware initialization by reset action.

The malfunction reset output circuit such as watchdog timer reset, address trap reset and system clock reset is not initialized when power is turned on. The  $\overline{\text{RESET}}$  pin can output level "L" at the maximum 24/fc[s] (1.5  $\mu$ s at 16.0 MHz) when power is turned on.

On-chip hardware		Initial value	On-chip hardware	Initial value	
Program counter	(PC)	(FFFE <sub>H</sub> )			
Stack pointer	(SP)	Not initialized	Prescaler and Divider of timing	0	
General-purpose registers		Not initialized	generator		
(W, A, B, C, D, E, H, L	, IX, IY)				
Jump status flag	(JF)	Not initialized	Watchdog timer	Enable	
Zero flag	(ZF)	Not initialized			
Carry flag	(CF)	Not initialized			
Half carry flag	(HF)	Not initialized	Output latches of I/O ports	Refer to I/O port	
Sign flag	(SF)	Not initialized	Output lateries of 1/O ports	circuitry	
Overflow flag	(VF)	Not initialized			
Interrupt master enable flag	(IMF)	0			
Interrupt individual enable fla	ags	0		Refer to each of	
	(EF)		Control registers		
Interrupt latches	(IL)	0	1	control register	
			RAM	Not initialized	

Table 1-4. Initializing Internal Status by Reset Action

### 1.6.1 External Reset Input

The RESET pin contains a Schmitt trigger (hysteresis) with an internal pull-up resistor.

When the RESET pin is held at "L" level for at least 3 machine cycles (12/fc [s]) with the power supply voltage within the operating voltage range and oscillation stable, a reset is applied and the internal state is initialized.

When the  $\overline{RESET}$  pin input goes high, the reset operation is released and the program execution starts at the vector address stored at addresses FFFE to FFFF<sub>H</sub>.

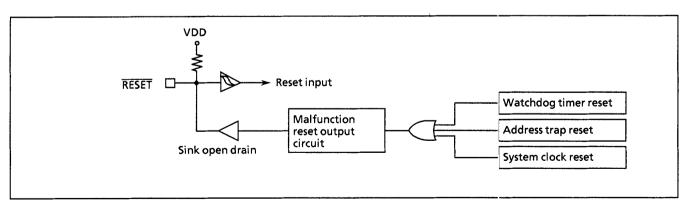


Figure 1-23. Reset Circuit

### 1.6.2 Address-trap-reset

If the CPU should start looping for some cause such as noise and an attempt be made to fetch an instruction from the on-chip RAM (when WDTCR1<ATAS> is set to "1") or the SFR area, address-trap-reset will be generated. Then, the  $\overline{RESET}$  pin output will go low. The reset time is about 8/fc to 24/fc [s] (0.5 to 1.5  $\mu$ s at 16.0 MHz).

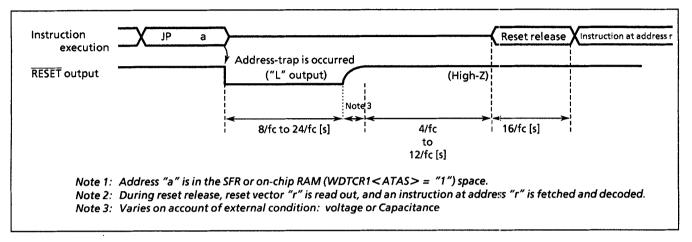


Figure 1-24. Address-Trap-Reset

Note: The operating mode under address trapped is alternative of reset or interrupt. The address trap area is alternative.

### 1.6.3 Watchdog timer reset

Refer to Section "2.4 Watchdog Timer".

### 1.6.4 System-clock-reset

Clearing both XEN and XTEN (bits 7 and 6 in SYSCR2) to "0", clearing XEN to "0" when SYSCK="0", or clearing XTEN to "0" when SYSCK="1" stops system clock, and causes the microcomputer to deadlock. This can be prevented by automatically generating a reset signal whenever XEN = XTEN = "0", XEN = SYSCK = "0", or XTEN = "0" / SYSCK = "1" is detected to continue the oscillation. The, the  $\overline{RESET}$  pin output goes low from high-impedance. The reset time is about 8/fc to 24/fc [s] (0.5 to 1.5  $\mu$ s at 16.0 MHz).

### 2. On-Chip Peripherals Functions

# 2.1 Special Function Register (SFR)

The TMP86C829A/H29A/M29A adopt the memory mapped I/O system, and all peripheral control and data transfers are performed through the special function register (SFR). The SFR is mapped on address 0000H to 003FH, DBR is mapped on address 0F80H to 0FFFH.

Figure 2-1 (a) to 2-1 (c) indicate the special function register (SFR) and data buffer register (DBR) for TMP86C829A/H29A/M29A.

Address	Read	Write	Address	Read	Write
0000 <sub>H</sub>	reser	ved	0020 <sub>H</sub>	ADCDR1 (AD converter register 1)	-
01	P1DR (P1 Port o	output latch)	21	ADCDR2 (AD converter register 2)	_
02	P2DR (P2 Port o	output latch)	22	res	erved
03	P3DR (P3 Port o	output latch)	23	rese	erved
04	P3OUTCR (P3 Port ou	tput circuit control)	24		erved
05	P5DR (P5 Port o	output latch)	25	UARTSR (UART Status register)	
06	P6DR (P6 Port o	output latch)	26		UARTCR2 (UART control register 2)
07	P7DR (P7 Port o	output latch)	27		erved
08	P1PRD (P1 Terminal input)	<del>-</del>	28		Control register)
09	P2PRD (P2 Terminal input)	<del>_</del>	29		gment output control)
0A	P3PRD (P3 Terminal input)	<del>_</del>	2A		gment output control)
OB	P5PRD (P5 Terminal input)		2B	l	gment output control)
0C	P6CR (P6 Port inpu	t/output control)	2C		ner register 3)
0D	P7PRD (P7 Terminal input)	<del>-</del>	2D	PWREG4 (Tin	
0E	ADCCR1 (AD control register 1)				ner register 5)
OF	ADCCR2 (AD control register 2)				ner register 6)
10	TREG1AL				erved
11		ner register 1 A)	31		erved
12	TREG1A <sub>H</sub>		32		erved
13	TREG18 (Time		33	rese	erved
14	[	r Counter 1 control 1)	34		WDTCR1 (watch dog timer control)
15		er Counter 1 control 2)	35		WDTCR2 (watch dog timer control)
16	TC1SR (TC1 Status)	<del></del>	36	1	G/DVO control)
17	reser		37		rnal interrupt control)
18		Counter 3 control)	38	SYSCR1 (Syst	
19		Counter 4 control)	39	SYSCR2 (Syst	
1A		Counter 5 control)	3A	**************************************	ot enable register)
18	TC6CR (Timer Counter 6 control)				ot enable register)
1C	TTREG3 (Timer register 3)			IL <sub>L</sub> (Interrupt	
1D	TTREG4 (Time		3D	IL <sub>H</sub> (Interrupt	
1E	TTREG5 (Time	er register 5)	3E		rupt source selector)
1F	TTREG6 (Time	er register 6)	3F	PSW (Progra	m Status word)

Note 1: Do not access reserved areas by the program.

Note 2: - ; Cannot be accessed.

Note 3: Write-only registers and interrupt latches cannot use the read-modify-write instructions (bit manipulation instructions such as SET, CLR, etc. and logical operation instructions such as AND, OR, etc.).

Figure 2-1 (a). The Special Function Register (SFR) for TMP86C829A/H29A/M29A

Address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0	Address	Read Write					
0F80 <sub>H</sub>		SEC	51			SE	G0		0F90 <sub>H</sub>	SIOBR0	(SIO Buffer 0)				
81		SEC	3			SE	G2		91	SIOBR1	(SIO Buffer 1)				
82		SEG	5			SE	G4		92	SIOBR2	(SiO Buffer 2)				
83		SEC	7			SE	G6		93	SIOBR3	(SIO Buffer 3)				
84		SEG	9			SE	G8		94						
85	SEG11		SEG11		SEG10				95	95 SIOBR5 (SIO Buffer 5)					
86		SEG13		SEG12				96	6 SIOBR6 (SIO Buffer 6)						
87		SEG	15		SEG14				97	SIOBR7 (SIO Buffer 7)					
88		SEG	17			SE	G16		98	98 - SIOCR1 (SIO Control register 1)					
89		SEC	19		l	SE	G18		99	99 SIOSR (SIO Status register) SIOCR2 (SIO Control register 2)					
8A	SEG21		SEG21			SEG20			9A	STOPCR (Key On Wake Up Control regis					
8B		SEG	23			SE	G22		9В	B RDBUF (uart received data buffer) TDBUF (uart transmited data buffe					
8C		SEG25 SEG24		SEG24			9C	reserved							
8D		SEG27		SEG27		SEG27		SEG26				9D	D reserved		
8E			29		SEG18				9E		reserved				
8F		SEG	31			SE	G30		0FFF		reserved				

- Note 1: Do not access reserved areas by the program.
- Note 2: -; Cannot be accessed.
- Note 3: Write-only registers and interrupt latches cannot use the read-modify-write instructions (bit manipulation instructions such as SET, CLR, etc. and logical operation instructions such as AND, OR, etc.).

Figure 2-1 (c). The Data Buffer Register (DBR) for TMP86C829A/H29A/M29A

#### 2.2 I/O Ports

The TMP86C829A/H29A/M29A have 6 parallel input/output ports (39 pins) as follows.

	Primary Function	Secondary Functions
Port P1	8-bit I/O port	External interrupt input, serial interface input / output, UART input/output and segment output.
Port P2	3-bit I/O port	Low-frequency resonator connections, external interrupt input, STOP mode release signal input.
Port P3	4-bit I/O port	Timer / counter input / output and divider output.
Port P5	8-bit I/O port	Segment output.
Port P6	8-bit I/O port	Analog input, external interrupt input, timer/counter input and STOP mode release signal input.
Port P7	8-bit I/O port	Segment output.

Each output port contains a latch, which holds the output data. All input ports do not have latches, so the external input data should be externally held until the input data is read from outside or reading should be performed several timer before processing. Figure 2-2 shows input/output timing examples. External data is read from an I/O port in the S1 state of the read cycle during execution of the read instruction. This timing cannot be recognized from outside, so that transient input such as chattering must be processed by the program.

Output data changes in the S2 state of the write cycle during execution of the instruction which writes to an I/O port.

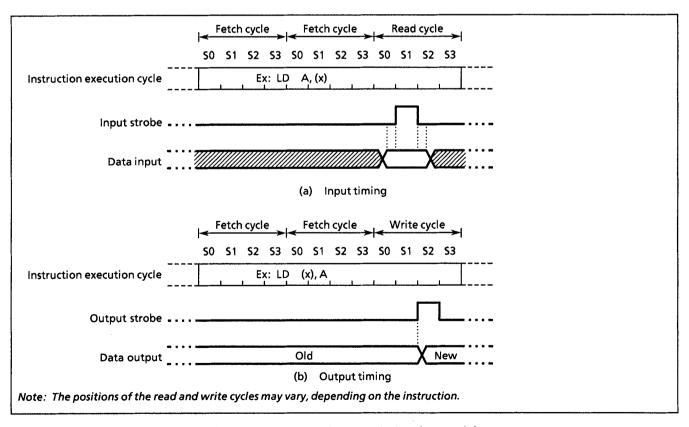


Figure 2-2. Input/Output Timing (Example)

### 2.2.1 Port P1 (P17 to P10)

Port P1 is an 8-bit input/output port which is also used as an external interrupt input, serial interface input/output, UART input/output and segment output of LCD. When used as a segment pins of LCD, the respective bit of P1LCR should be set to "1".

When used as an input port or a secondary function (except for segment) pins, the respective output latch (P1DR) should be set to "1" and its corresponding P1LCR bit should be set to "0". When used as an output port, the respective P1LCR bit should be set to "0". During reset, the output latch is initialized to "1".

P1 port output latch (P1DR) and P1 port terminal input (P1PRD) are located on their respective address.

When read the output latch data, the P1DR should be read and when read the terminal input data, the P1PRD register should be read.

If the terminal input data which is configured as LCD segment output is read, unstable data is read.

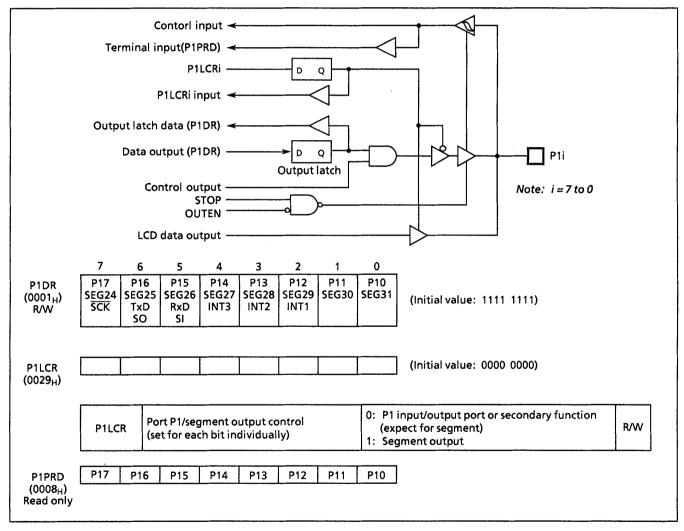


Figure 2-3. Port 1

#### 2.2.2 Port P2 (P22 to P20)

Port P2 is a 3-bit input/output port.

It is also used as an external interrupt, a STOP mode release signal input, and low-frequency crystal oscillator connection pins. When used as an input port or a secondary function pins, respective output latch (P2DR) should be set to "1".

During reset, the P2DR is initialized to "1".

A low-frequency crystal oscillator (32.768 kHz) is connected to pins P21 (XTIN) and P22 (XTOUT) in the dual-clock mode. In the single-clock mode, pins P21 and P22 can be used as normal input/output ports.

It is recommended that pin P20 should be used as an external interrupt input, a STOP mode release signal input, or an input port. If it is used as an output port, the interrupt latch is set on the falling edge of the output pulse.

P2 port output latch (P2DR) and P2 port terminal input (P2PRD) are located on their respective address.

When read the output latch data, the P2DR should be read and when read the terminal input data, the P2PRD register should be read. If a read instruction is executed for port P2, read data of bits 7 to 3 are unstable.

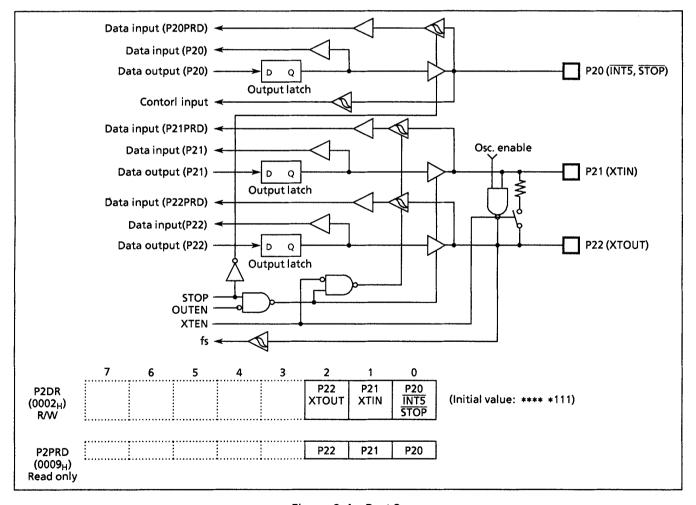


Figure 2-4. Port 2

Note: Port P20 is used as STOP pin. Therefore, when stop mode is started, OUTEN does not affect to P20, and P20 becomes Hi-Z mode.

### 2.2.3 Port P3 (P33 to P30)

Port P3 is a 4-bit input/output port.

It is also used as a timer/counter input/output, divider output.

When used as a timer/counter output or divider output, respective output latch (P3DR) should be set to "1".

It can be selected whether output circuit of P3 port is C-MOS output or a sink open drain individually, by setting P3OUTCR. When a corresponding bit of P3OUTCR is "0", the output circuit is selected to a sink open drain and when a corresponding bit of P3OUTCR is "1", the output circuit is selected to a C-MOS output. When used as an input port or timer/counter input, respective output control (P3OUTCR) should be set to "0" after P3DR is set to "1". During reset, the P3DR is initialized to "1", and the P3OUTCR is initialized to "0".

P3 port output latch (P3DR) and P3 port terminal input (P3PRD) are located on their respective address.

When read the output latch data, the P3DR should be read and when read the terminal input data, the P3PRD register should be read. If a read instruction is executed for port P3, read data of bits 7 to 4 are unstable.

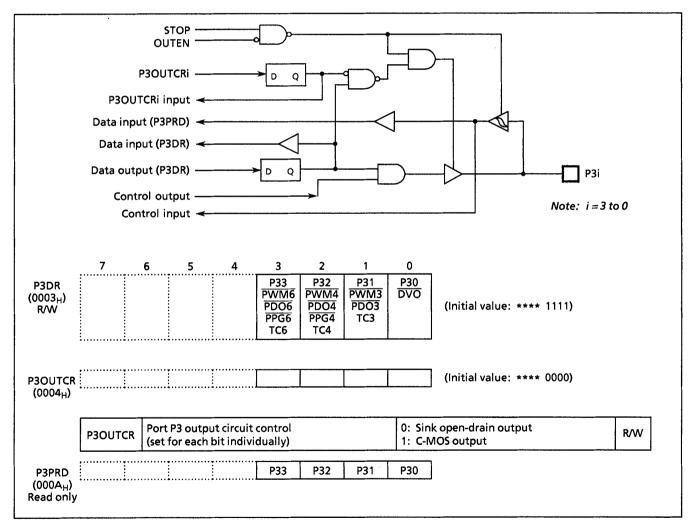


Figure 2-5. Port 3

### 2.2.4 Port P5 (P57 to P50)

Port P5 is an 8-bit input/output port which is also used as a segment pins of LCD.

When used as input port, the respective output latch (P5DR) should be set to "1".

During reset, the P5DR is initialized to "1".

When used as a segment pins of LCD, the respective bit of P5LCR should be set to "1". When used as an output port, the respective P5LCR bit should be set to "0".

P5 port output latch (P5DR) and P5 port terminal input (P5PRD) are located on their respective address.

When read the output latch data, the P5DR should be read and when read the terminal input data, the P5PRD register should be read. If the terminal input data which is configured as LCD segment output is read, unstable data is read.

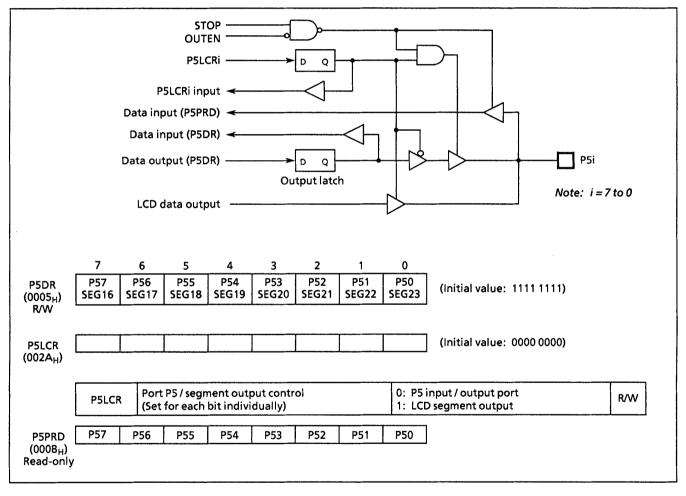


Figure 2-6. Port 5

#### 2.2.5 Port P6 (P67 to P60)

Port P6 is an 8-bit input/output port which can be configured as an input or an output in one-bit unit. Port P6 is also used as an analog input, Key on Wake up input, timer/counter input and external interrupt input. Input/output mode is specified by the P6 control register (P6CR), the P6 output latch (P6DR), and AINDS (bit 4 in ADCCR1). During reset, P6CR and P6DR are initialized to "0" and AINDS is set to "1". At the same time, the input data of pins P67 to P60 are fixed to "0". To use port P6 as an input port, external interrupt input, timer/counter input or key on wake up input, set data of P6DR to "1" and P6CR to "0". To use it as an output port, set data of P6CR to "1". To use it as an analog input, set data of P6DR to "0" and P6CR to "0", and start the AD. It is the penetration electric current measures by the analog voltage.

Pins not used for analog input can be used as I/O ports. During AD conversion, output instructions should not be executed to keep a precision. In addition, a variable signal should not be input to a port adjacent to the analog input during AD conversion.

When the AD converter is in use (P6DR=0), bits mentioned above are read as "0" by executing input instructions.

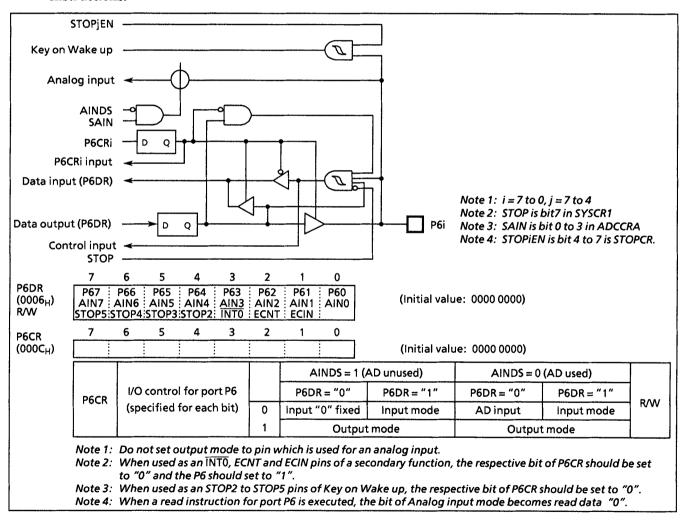


Figure 2-7. Port 6 and P6CR

Note: Although P6DR is a read / writer register, because it is also used as an input mode control function, read-modify-write instructions such as bit manipulate instructions cannot be used.

Read-modify-write instruction writes the all data of 8-bit after data is read and modified. Because a bit setting Input mode read data of terminal, the output latch is changed by these instruction. So P6 port can not input data.

#### 2.2.6 Port P7 (P77 to P70)

Port P7 is an 8-bit input / output port which is also used as a segment pins of LCD.

When used as input port, the respective output latch (P7DR) should be set to "1".

During reset, the P7DR is initialized to "1".

When used as a segment pins of LCD, the respective bit of P7LCR should be set to "1". When used as an output port, the respective P7LCR bit should be set to "0".

P7 port output latch (P7DR) and P7 port terminal input (P7PRD) are located on their respective address.

When read the output latch data, the P7DR should be read and when read the terminal input data, the P7PRD register should be read. If the terminal input data which is configured as LCD segment output is read, unstable data is read.

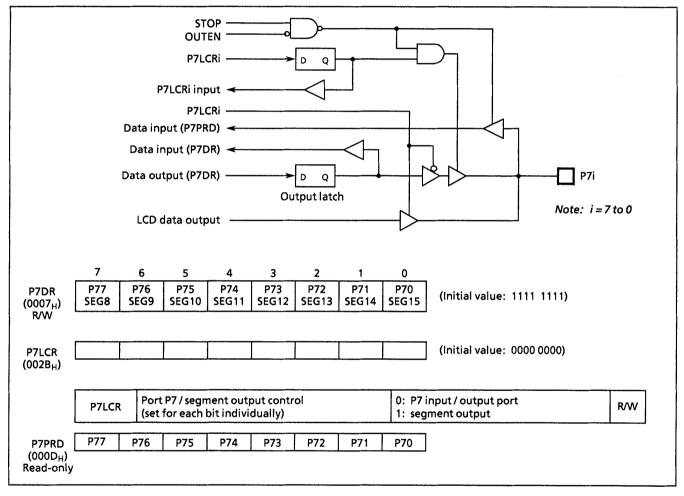


Figure 2-8. Port 7

#### 2.3 Time Base timer (TBT)

The time base timer generates time base for key scanning, dynamic displaying, etc. It also provides a time base timer interrupt (INTTBT).

An INTTBT is generated on the first falling edge of source clock (the divider output of the timing generator) after the time base timer has been enabled. The divider is not cleared by the program; therefore, only the first interrupt may be generated ahead of the set interrupt period (Figure 2-9.(b)). The interrupt frequency (TBTCK) must be selected with the time base timer disabled (the interrupt frequency must not be changed with the disable from the enable state). Both frequency selection and enabling can be performed simultaneously.

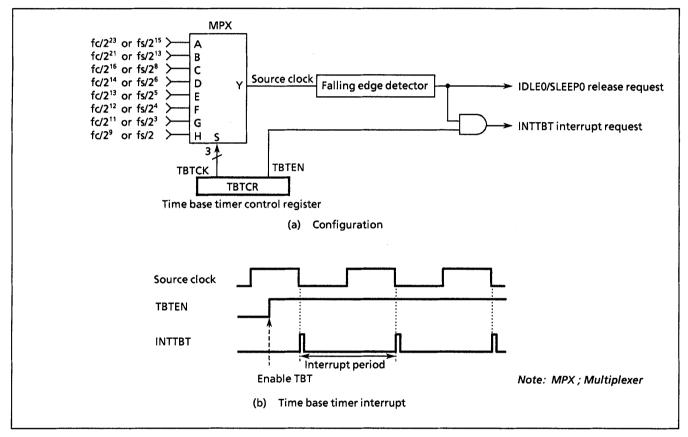


Figure 2-9. Time Base Timer

Example: Sets the time base timer frequency to fc/216 [Hz] and enables an INTTBT interrupt.

LD (TBTCR), 00000010B ; TBTEN  $\leftarrow 1$ LD (TBTCR), 00001010B ; TBTCK  $\leftarrow 010$ 

SET (EIRL). 6

	7	6	5	4	3 2	11	0			
BTCR 0036 <sub>H</sub> )	(DVOEN)	EN) (DVOCK) (DV7CK) TE				TBTCK	(Initial value	(Initial value: 0**0 0***)		
	TBTEN	Time bas	e timer	enable /	0: Disal					
-			***************************************				1/2, IDLE1/2 mode	SLOW, SLEEP mode	1	
į						DV7CK = 0	DV7CK = 1	SEOW, SEEE! IIIOGE		
					000	fc/2 <sup>23</sup>	fs/2 <sup>15</sup>	fs/2 <sup>15</sup>	1	
		Time bas	e timer	interrupt	001	fc/2 <sup>21</sup>	fs/2 <sup>13</sup>	fs/2 <sup>13</sup>	R/W	
	TBTCK	frequenc	y select	[Hz]	010	fc/2 <sup>16</sup>	fs/2 <sup>8</sup>			
					011	fc/2 <sup>14</sup>	fs/2 <sup>6</sup>	<u> </u>		
					100	fc/2 <sup>13</sup>	fs/2 <sup>5</sup>	_		
ļ					101	fc/2 <sup>12</sup>	fs/2⁴	_		
					110	fc/2 <sup>11</sup>	fs/2 <sup>3</sup>	_		
					111	fc/2 <sup>9</sup>	fs/2	_	1	

Figure 2-10. Time Base Timer Control Register

Table 2-1. Time Base Timer Interrupt Frequency (Example: fc = 16.0 MHz, fs = 32.768 kHz)

	Time base	timer interrupt frequency [Hz]	
ТВТСК	NORMAL1/2,	IDLE1/2 mode	SLOW, SLEEP
	DV7CK = 0	DV7CK = 1	mode
000	1.91	1	1
001	7.63	4	4
010	244.14	128	_
011	976.56	512	_
100	1953.13	1024	<del>-</del>
101	3906.25	2048	-
110	7812.5	4096	-
111	31250	16384	_

### 2.4 Watchdog Timer (WDT)

The watchdog timer is a fail-safe system to rapidly detect the CPU malfunctions such as endless looping caused by noise or the like, or deadlock and resume the CPU to the normal state.

The watchdog timer signal for detecting malfunction can be selected either a reset output or a non-maskable interrupt request. However, selection is possible only once after reset. At first the reset output is selected.

When the watchdog timer is not being used for malfunction detection, it can be used as a timer to generate an interrupt at fixed intervals.

Note: Care must be given in system design so as to protect the Watchdog timer from disturbing noise. Otherwise the Watchdog Timer may not fully exhibit its functionality.

# 2.4.1 Watchdog Timer Configuration

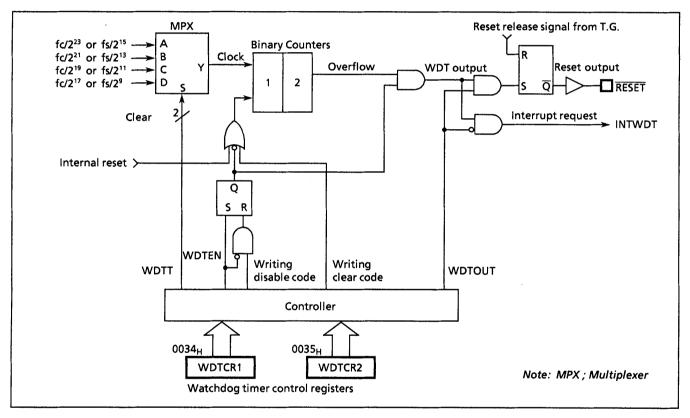


Figure 2-11. Watchdog Timer Configuration

## 2.4.2 Watchdog timer control

Figure 2-12 shows the watchdog timer control registers (WDTCR1, WDTCR2). The watchdog timer is automatically enabled after reset.

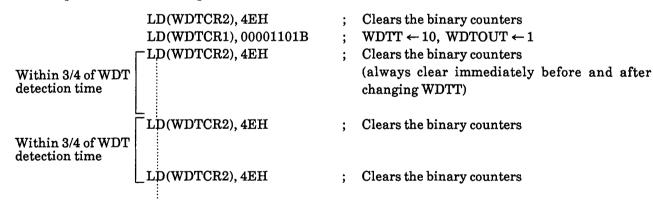
- (1) Malfunction detection methods using the watchdog timer
  - The CPU malfunction is detected as follows.
  - ① Setting the detection time, selecting output, and clearing the binary counter.
  - ② Repeatedly clearing the binary counter within the setting detection time

If the CPU malfunctions such as endless looping or deadlock occur for any cause, the watchdog timer output will become active at the rising of an overflow from the binary counters unless the binary counters are cleared. At this time, when WDTOUT=1 a reset is generated, which drivers the RESET pin low to reset the internal hardware and the external circuit. When WDTOUT=0, a watchdog timer interrupt (INTWDT) is generated.

The watchdog timer temporarily stops counting in STOP mode including warm-up or IDLE mode, and automatically restarts (continues counting) when the STOP / IDLE mode is released.

Note: The watchdog timer consists of an internal divider and a two-stage binary counter. When clear code 4E<sub>H</sub> is written, only the binary counter is cleared, not the internal divider. Depending on the timing at which clear code 4E<sub>H</sub> is written on the WDTCR2 register, the overflow time of the binary counter may be at minimum 3/4 of the time set in WDTCR1 <WDTT>. Thus, write the clear code using a shorter cycle than 3/4 of the time set in WDTCR1 <WDTT>.

Example: Sets the watchdog timer detection time to 2<sup>21</sup>/fc [s] and resets the CPU malfunction.



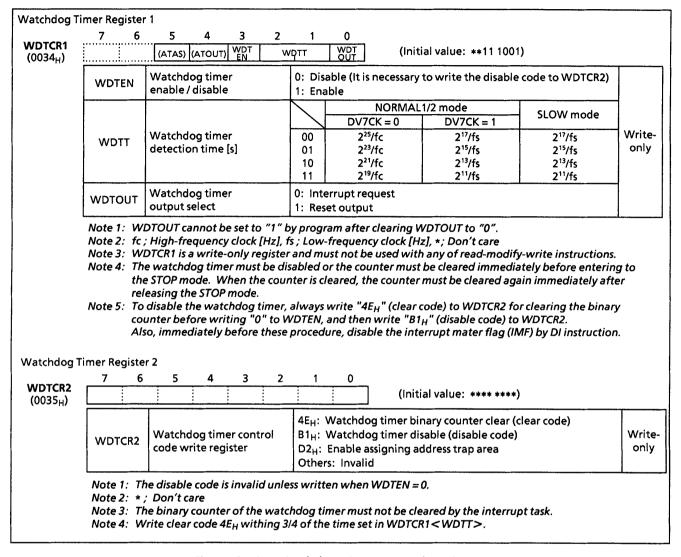


Figure 2-12. Watchdog Timer Control Registers

## (2) Watchdog timer enable

The watchdog timer is enabled by setting WDTEN (bit 3 in WDTCR1) to "1". WDTEN is initialized to "1" during reset, so the watchdog timer operates immediately after reset is released.

### (3) Watchdog timer disable

To disable the watchdog time, write "4EH" (clear code) to WDTCR2 for clearing the binary counter before writing "0" to WDTEN, and then write "B1H" (disable code) to WDTCR2. The watchdog timer is not disabled if this procedure is reversed and the disable code is written to WDTCR2 before WDTEN is cleared to "0". Also, immediately before these procedure, disable the interrupt master flag (IMF) by DI instruction. During disabling the watchdog timer, the binary counters are cleared to "0".

Example: Disables watchdog timer

DI ;  $IMF \leftarrow 0$ 

LD (WDTCR2), 04EH; Clear the binary counter

LDW (WDTCR1), 0B101H ; WDTEN  $\leftarrow 0$ , WDTCR2  $\leftarrow$  Disable code

Table 2-2. Watchdog Timer Detection Time (Example: fc = 16.0 MHz, fs = 32.768 kHz)

	Watchdo	og timer detection time [s]	
WDTT	NORMAL1/	2 mode	SI OW I
	DV7CK = 0	DV7CK = 1	SLOW mode
00	2.097	4	4
01	254.288 m	1	1
10	131.072 m	250 m	250 m
11	32.768 m	62.5 m	62.5 m

# 2.4.3 Watchdog timer interrupt (INTWDT)

This is a pseudo non-maskable interrupt which can be accepted regardless of the contents of the EIR. If a watchdog timer interrupt or a software interrupt is already accepted, however, the new watchdog timer interrupt waits until the previous interrupt processing is completed (the end of the [RETN] instruction execution).

The stack pointer (SP) should be initialized before using the watchdog timer output as an interrupt source with WDTOUT.

Example: Watchdog timer interrupt setting up

LD SP, 023FH ; Sets the stack pointer

LD (WDTCR1), 00001000B; WDTOUT  $\leftarrow 0$ 

### 2.4.4 Watchdog timer reset

If the watchdog timer output becomes active, a reset is generated, which drivers the  $\overline{RESET}$  pin (sink open drain input / output with pull-up) low to reset the internal hardware. The reset output time is about 8/fc to 24/fc [s] (0.5 to 1.5  $\mu$ s at fc = 16.0 MHz).

Note: The high-frequency clock oscillator also turns on when a watchdog timer reset is generated in SLOW mode. The reset output time is 8/fc to 24/fc [s]. Therefore, the reset time may include a certain amount of error if there is any fluctuation of the oscillation frequency at starting the high-frequency clock oscillation. Thus, the reset time must be considered an approximated value.

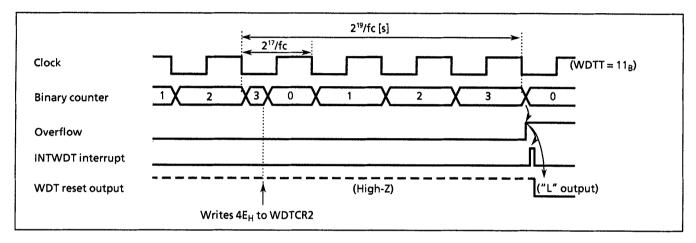


Figure 2-13. Watchdog Timer Interrupt / Reset

### 2.4.5 Address trap

The Watchdog Timer Control Register 1, 2 shares its addresses with the control registers in case of address trap. These control registers for address trap are shown on Figure 2-14.

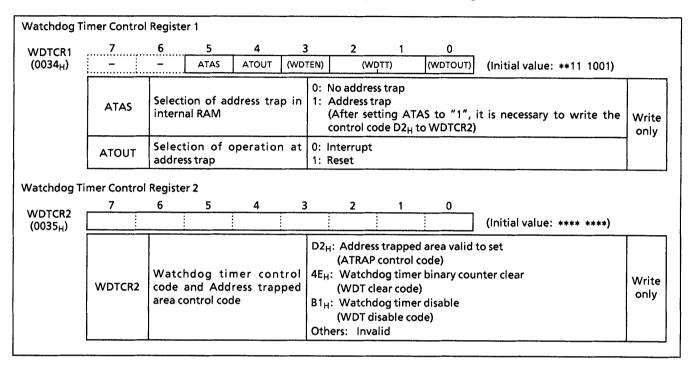


Figure 2-14. Watchdog Timer Control Registers

## (1) Selection of address trap in internal RAM (ATAS)

Using WDTCR1 <ATAS>, address trap or no address trap can be selected for the internal RAM area. To execute an instruction in the internal RAM area, set "0" in WDTCR1 <ATAS>. Setting in WDTCR1 <ATAS> becomes valid after control code D2H is written in WDTCR2. Executing an instruction in the SFR/DBR area generates an address trap unconditionally regardless of the setting in WDTCR1 <ATAS>.

# (2) Selection of operation at address trap (ATOUT)

As the operation at address trap either interrupt generation or reset output can be selected by WDTCR1<ATOUT>.

### 2.5 Divider Output (DVO)

Approximately 50% duty pulse can be output using the divider output circuit, which is useful for piezoelectric buzzer drive. Divider output is from pin P30 ( $\overline{DVO}$ ). The P30 output latch should be set to "1".

Note: Selection of divider output frequency must be made while divideroutput is disabled.

Also, in other words, when changing the state of the divider output frequency from enabled to disable, do not change the setting of the divider output frequency.

TCR	/	6	5	4	(77,751)	2	(7777014)		# 1.1 L	
)36 <sub>H</sub> )	DVOEN	DVÇ	CK	DV7CK)	(TBTEN)	<u> </u>	(TBTCK)		(Initial value: 0000	0000)
	DVOEN	Divider disable	output	enable /	0: Disab 1: Enabl					
						NOF	MAL1/2 n	node	SLOW, SLEEP mode	
	1					DV7CK = 0	)	DV7CK = 1	JLOW, SLEEP Mode	R/W
	DVOCK	Divider	output (D	VO)	00	fc/2 <sup>13</sup>		fs/2 <sup>5</sup>	fs/2 <sup>5</sup>	.,
	DVOCK	frequen	cy selecti	on [Hz]	01	fc/2 <sup>12</sup>		fs/2 <sup>4</sup>	fs/2⁴	
	1				10	fc/2 <sup>11</sup>		fs/2³	fs/2 <sup>3</sup>	
	İ	1			11	fc/2 <sup>10</sup>	1	fs/2 <sup>2</sup>	fs/2 <sup>2</sup>	

Figure 2-15. Divider Output Control Register

Example: 1.95 kHz pulse output (at fc = 16 MHz)

SET (P3DR). 0 ; P30 output latch  $\leftarrow$  "1"

LD (TBTCR), 00000000B ; DVOCK ← "00" LD (TBTCR), 10000000B ; DVOEN ← "1"

Table 2-3. Divider Output Frequency (Example: at fc = 16.0 MHz, fs = 32.768 kHz)

	Divid	der output frequency [Hz]	
DVOCK	NORMAL1/2,	SLOW, SLEEP	
	DV7CK = 0	DV7CK = 1	mode
00	1.953 k	1.024 k	1.024 k
01	3.906 k	2.048 k	2.048 k
10	7.813 k	4.096 k	4.096 k
11	15.625 k	8.192 k	8.192 k

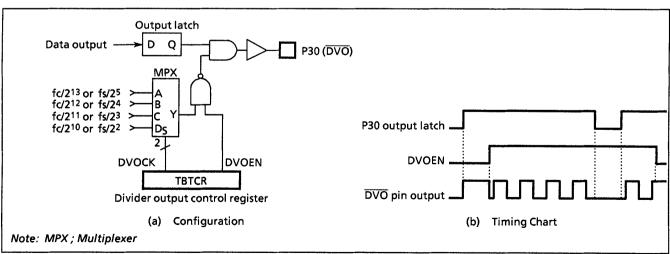
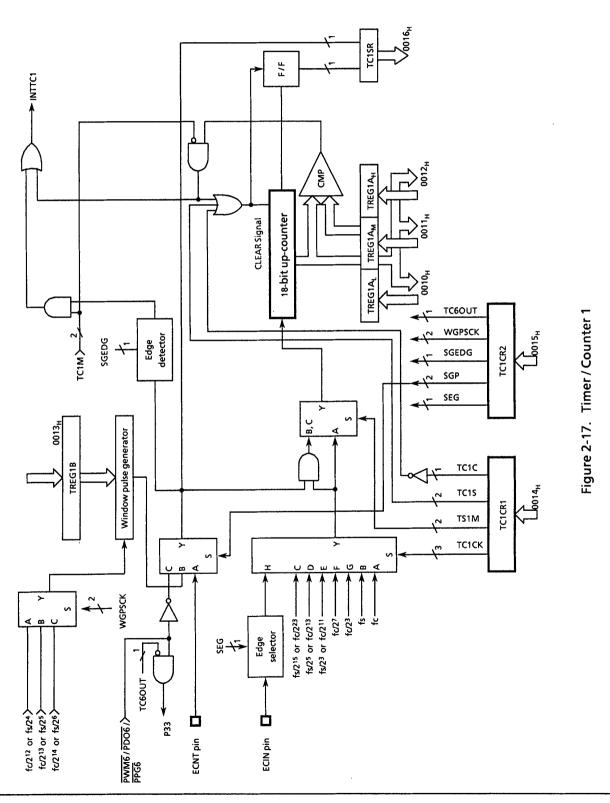


Figure 2-16. Divider Output

# 2.6 18-bit Timer / Counter (TC1)

# 2.6.1 Configuration



86CM29A-59

#### 2.6.2 Control

The Timer/counter 1 is controlled by a timer / counter 1 control registers (TC1CR1 / TC1CR2), an 18-bit timer register (TREG1A), and an 8-bit internal window gate pulse setting register (TREG1B).

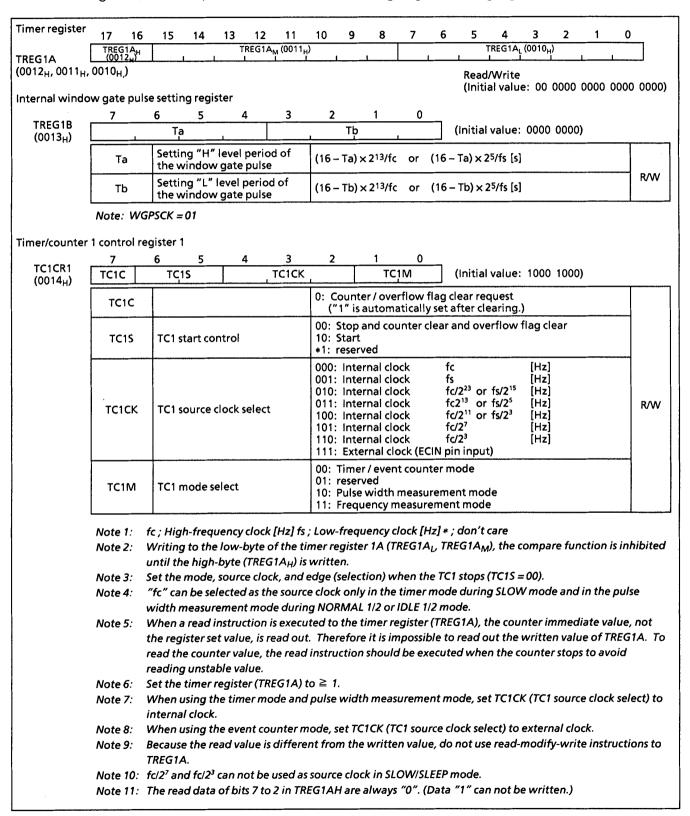


Figure 2-18. Timer Register / Window Gate Pulse Setting Register / Control Register of the TC1

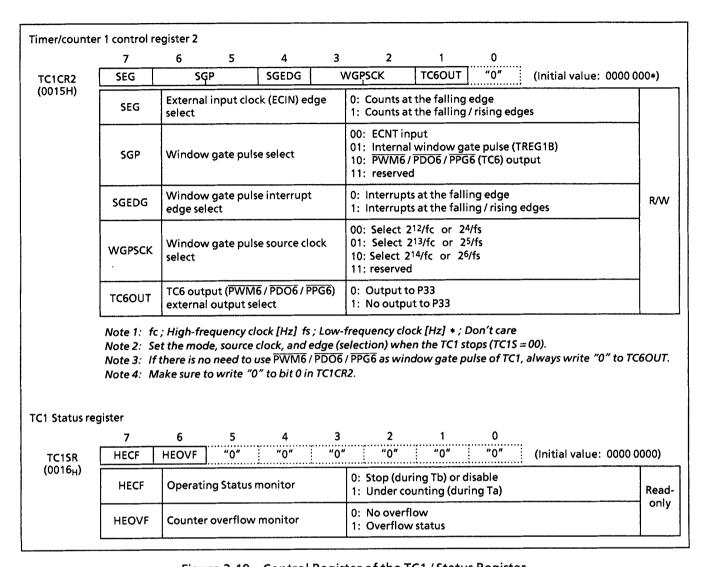


Figure 2-19. Control Register of the TC1 / Status Register

#### 2.6.3 Function

TC1 has four operating modes. The timer mode of the TC1 is used at warm-up when switching form SLOW mode to NORMAL2 mode.

#### (1) Timer mode

In this mode, counting up is performed using the internal clock. The contents of TREGIA are compared with the contents of up-counter. If a match is found, an INTTC1 interrupt is generated, and the counter is cleared. Counting up resumes after the counter is cleared.

	Source	clock		Reso	olution	Maximum time setting		
NORMAL1/2, I		SLOW mode	SLEEP mode	fc = 16 MHz	fs = 32.768 kHz	fc = 16 MHz	fs = 32.768 kHz	
DV7CK = 0	DV7CK = 1							
fc/2 <sup>23</sup> [Hz]	fs/2 <sup>15</sup> [Hz]	fs/2 <sup>15</sup> [Hz]	fs/2 <sup>15</sup> [Hz]	0.52 s	1 s	38.2 h	72.8 h	
fc/2 <sup>13</sup>	fs/2 <sup>5</sup>	fs/2 <sup>5</sup>	fs/2 <sup>5</sup>	512 μs	0.98 ms	2.2 min	4.3 min	
fc/2 <sup>11</sup>	fs/2 <sup>3</sup>	fs/2 <sup>3</sup>	fs/2 <sup>3</sup>	128 <i>μ</i> s	244 μs	0.6 min	1.07 min	
fc/2 <sup>7</sup>	fc/2 <sup>7</sup>			8 <i>μ</i> s		2.1 s		
fc/2³	fc/2³			0.5 <i>μ</i> s		131.1 ms		
fc	fc	fc (Note)		62.5 ns	<del></del>	16.4 ms		
fs	fs	<del></del>	<del></del>		30.5 μs		8 s	

Table 2-4. Source Clock (internal clock) of Timer / Counter 1

Note: When fc is selected for the source clock in SLOW mode, the lower bits 11 of TREG1A is invalid, and a match of the upper bits 7 makes interrupts.

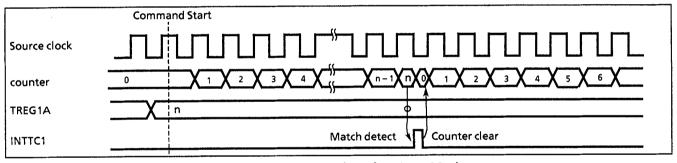


Figure 2-20. Timing Chart for Timer Mode

#### (2) Event Counter mode

It is a mode to count up at the falling edge of the ECIN pin input. Both edges can not be used. The countents of TREG1A are compared with the contents of up-counter. If a match is found, an INTTC1 interrupt is generated, and the counter is cleared. Counting up resums for ECIN pin input edge each after the counter is cleared. The maximum applied frequency is  $fc/2^4$  [Hz] in NORMAL 1/2 or IDLE 1/2 mode and  $fs/2^4$  [Hz] in SLOW or SLEEP mode. Two or more machine cycles are required for both the "H" and "L" levels of the pulse width.

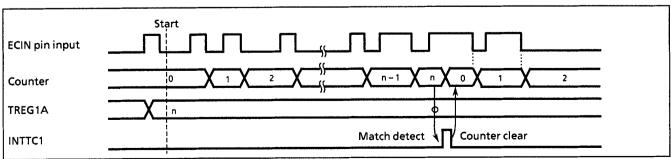


Figure 2-21. Event Counter Mode Timing Chart

#### (3) Pulse Width Measurement mode

In this mode, pulse widths are counted on the rising edge of logical AND-ed product between ECIN pin input (window pulse) and the internal clock. The internal clock is selected by TC1CK (bit 2, 3 and 4 in TC1CR1). An INTTC1 interrupt is generated at the falling edge of the window pulse or both rising and falling edges of the window pulse, that can be selected by SGEDG (bit 4 in TC1CR2). In the interrupt service program, read the contents of TREG1A while the count is stopped (ECIN pin is low), then clear the counter using TC1C (bit 7 in TC1CR1). When the counter is not cleared, counting up resumes by starting count-up. When TREG1A is counted up from 3FFFFH to 00000H, an overflow occurs. HEOVF (bit 6 in TC1SR) of the status register can monitor whether the overflows or not. HEOVF remains the old data until the counter is required to be cleared by TC1C.

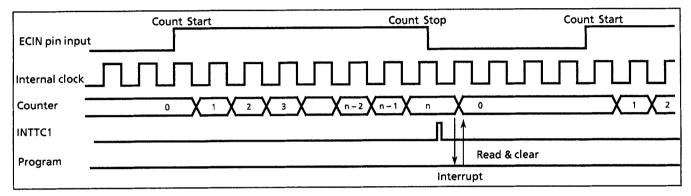


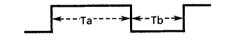
Figure 2-22. Pulse Width Measurement Mode Timing Chart

```
Note 1: INTTC1 interrupt occurs when ECIN input is "1" and TC1S of TC1CR1 is written to "00".
         According to the following step, when timer counter is stopped, INTTC1 interrupt latch
         should be cleared to "0".
   TC1STOP:
                                                ; Clear IMF
             DI
             CLR
                   (EIRH). EF8
                                                ; Clear EF8
                                                ; Stop timer counter 1
             LD
                   (TC1CR1), 00011010B
                   (ILH), 11111110B
                                                ; Clear IL8
             LD
                                                ; SET EF8
             SET
                   (EIRH). EF8
                                                ; SET IMF
         When SGEDG (window gate pulse interrupt edge select) is set to both edges and ECIN pin
Note 2:
         input is "1" in the pulse width measurement mode, an INTTC1 interrupt is generated by
         setting TC1S (TC1 start control) to "10" (start).
         In the pulse width measurement mode, HECF (operating status monitor) cannot used.
Note 3:
```

### (4) Frequency Measurement mode

In this mode, the frequency of ECIN pin input pulse is measured. TC1CK is required to be set to the external clock. The edge of the input pulse is counted during "H" level of the window gate pulse selected by SGP (bit 5 and 6 in TC1CR2). Whether the input pulse is counted on the falling edge. An INTTC1 interrupt is generated on the falling edge or both the rising / falling edges of the window gate pulse, that can be selected by SGEDG (bit 4 in TC1CR2). To use ECNT terminal input as a window gate pulse, SGP (bit 5 and 6 in TC1CR2) should be set to "00". In the interrupt service program, read the contents of TREG1A while the count is stopped (window gate pulse is low), then clear the counter using TC1C. When the counter is not cleared, counting up resumes by stating count-up. The window pulse status can be monitored by HECF of the status register. HEOVF of the status register can monitor whether the binary counter overflows or not. In the overflow flag status, a new data is not input until the counter clear requests.

- Using TC6 output (PWM6/PD06/PPG6) for the window gate pulse, external output of PWM6/PD06/PPG6 to P33 can be controlled using TC6OUT (bit 1 in TC1CR2). Zero-clearing TC6OUT outputs PWM6/PD06/PPG6 to P33; setting 1 in TC6OUT does not output PWM6/PD06/PPG6 to P33. (TC6OUT is used to control output to P33 only. Thus, use the timer counter 6 control register to operate/stop PWM6/PD06/PPG6.)
- When the internal window gate pulse is selected, the window gate pulse is set as follows. The internal window gate pulse consists of "H" level period (Ta) that is counting time and "L" level period (Tb) that is counting stop time. Ta or Tb can be individually set by TREG1B. One cycle contains Ta + Tb.
- Note 1: Because the internal window gate pulse is generated in synchronization with the internal divider, it may be delayed for a maximum of one cycle of the source clock (WGPSCK) immediately after start of the timer.
- Note 2: Set the internal window gate pulse when the timer counter is not operating or during the Tb period. When Tb is overwritten during the Tb period, the update is valid from the next Tb period.



The setting time fo Ta or Tb is shown as the following format. at (WGPSCK = 10).

 $(16-n) \times 2^{14}/fc$  [s] or

 $(16 - n) \times 2^{6}/fs$  [s]

The setting time at fs = 32.768 kHz is listed in a table menitioned right.

Ta set by the upper side (bits 7 to 4), and Tb is set by the lower side (bits 3 to 0) in TREG1B.

Figure 2-23. Window Gate Pulse Format

Setting I a and I b
(WGPSCK = 10, fs = 32.768 kHz)

Setting value	Setting time	Setting value	Setting time		
0	31.25 ms	8	15.63 ms		
1	29.30 ms	9	13.67 ms		
2	27.34 ms	Α	11.72 ms		
3	25.39 ms	В	9.77 ms		
4	23.44 ms	С	7.81 ms		
5	21.48 ms	D	5.86 ms		
6	19.53 ms	E	3.91 ms		
7	17.58 ms	F	1.95 ms		

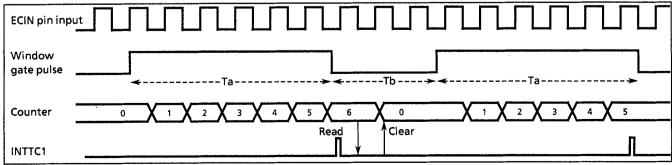


Figure 2-24. Timing Chart for the Frequency Measurement Mode (ECIN falling edge count, window gate pulse falling interrupt)

### 2.7 8-bit Timer / Counter (TC3, 4, 5, 6)

The TMP86C829A/H29A/M29A have four channels of 8-bit timer/counter (TC3, 4, 5, 6). These timer/counter are used as timer, event counter, PWM, PPG and PDO. These are also available as a 16-bit timer/counter by cascade connection.

# 2.7.1 Configuration

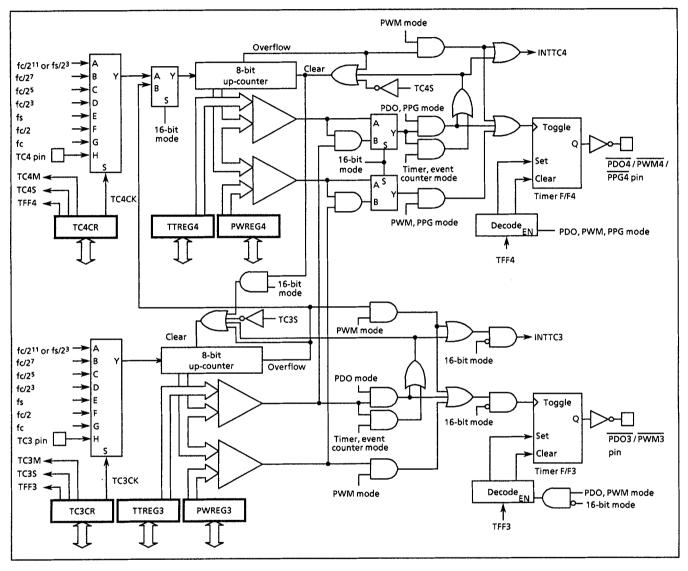


Figure 2-25. 8 bit Timer 3, 4

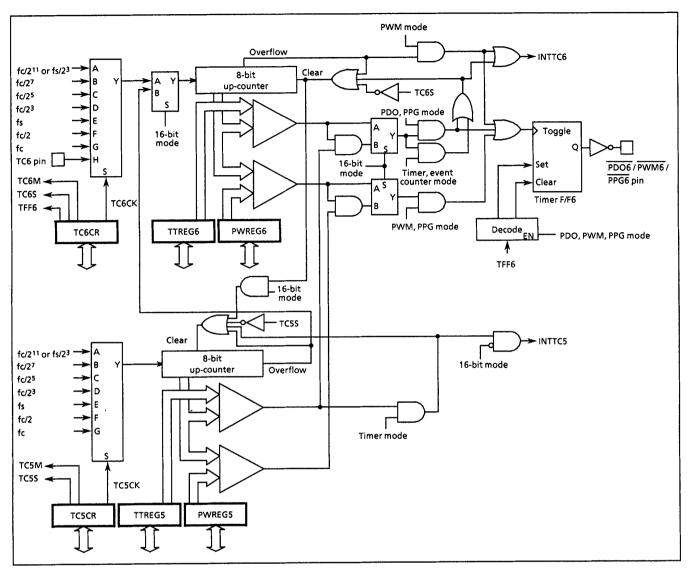


Figure 2-26. 8 bit Timer 5, 6

#### 2.7.2 Control

The timer / counter 3 is controlled by a timer / counter 3 control register (TC3CR) and two 8-bit timer registers (TTREG3 and PWREG3).

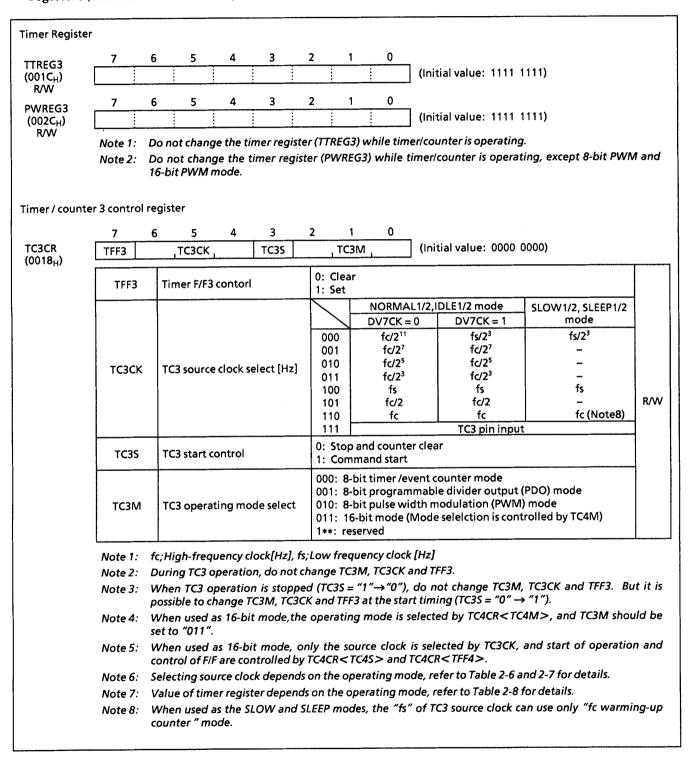


Figure 2-27. Timer 3 Register and Timer / Counter 3 Control Register

The timer / counter 4 is controlled by a timer / counter 4 control register (TC4CR) and two 8-bit timer registers (TTREG4 and PWREG4).

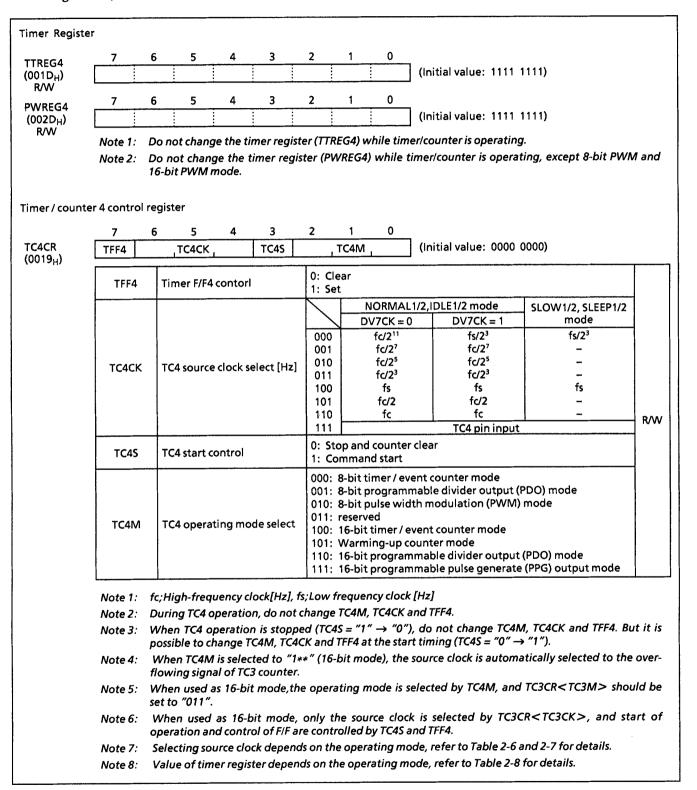


Figure 2-28. Timer 4 Register and Timer / Counter 4 Control Register

The timer / counter 5 is controlled by a timer / counter 5 control register (TC5CR) and two 8-bit timer registers (TTREG5 and PWREG5).

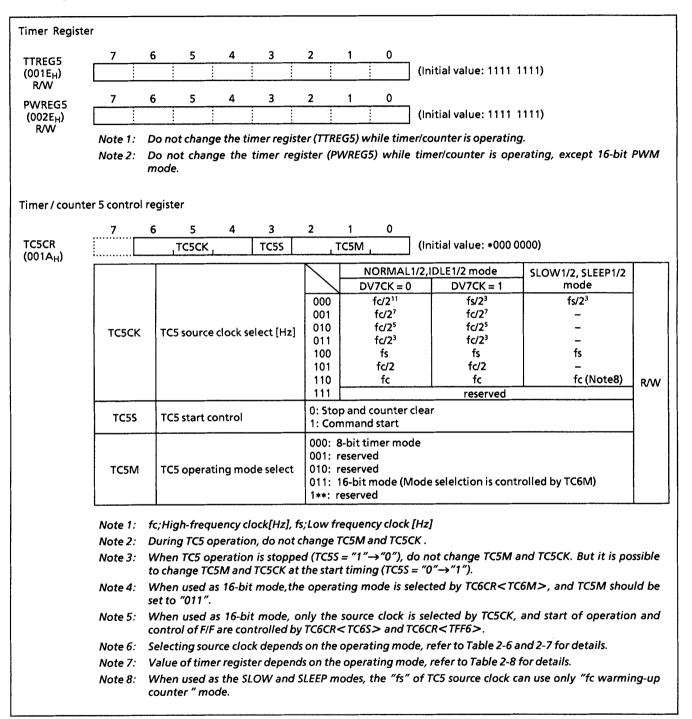


Figure 2-29. Timer 5 Register and Timer / Counter 5 Control Register

The timer / counter 6 is controlled by a timer / counter 6 control register (TC6CR) and two 8-bit timer registers (TTREG6 and PWREG6).

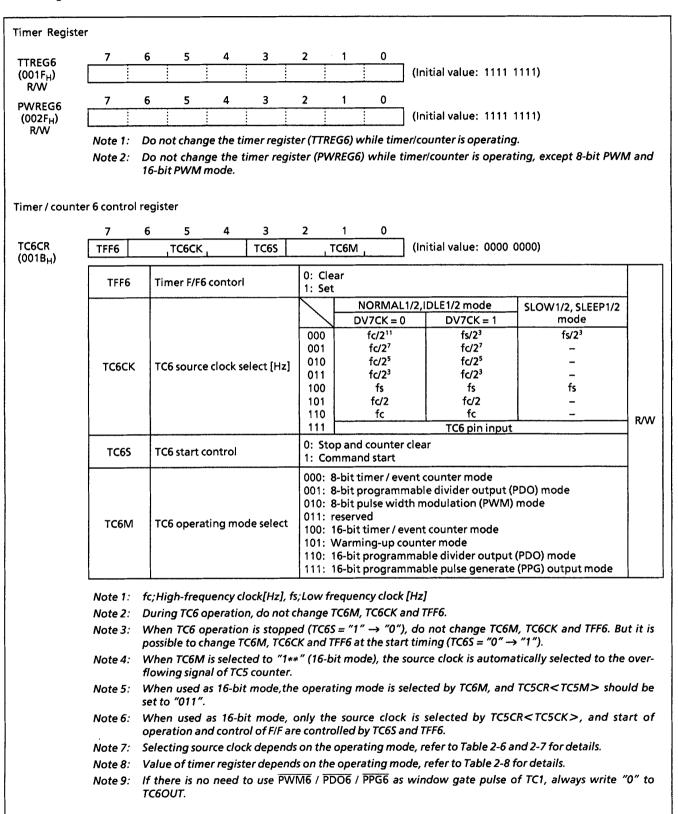


Figure 2-30. Timer 6 Register and Timer / Counter 6 Control Register

Table 2-6. Operating mode and available source clock (NORMAL1/2, IDLE1/2 mode)

Operating Mode	fc/2 <sup>11</sup> or fs/2 <sup>3</sup>	fc/2 <sup>7</sup>	fc/2 <sup>5</sup>	fc/2 <sup>3</sup>	fs	fc/2	fc	TCi pin input
8-bit Timer	0	0	0	0	_	_	_	_
8-bit Event Counter	-	-	_	_	_	_	_	0
8-bit PDO	0	0	0	0	_	_	_	
8-bit PWM	0	0	0	0	0	0	0	_
16-bit Timer	0	0	0	0	_	_	_	
16-bit Event Counter	_	_	_	_	_	_	_	0
Warming-up Counter	-	_	_	_	0	_	_	
16-bit PWM	0	0	0	0	0	0	0	0
16-bit PPG	0	0	0	0	_	_	_	0

Note 1: For 16-bit operation (16-bit Timer/Event Counter, Warming-up Counter, 16-bit PWM and 16-bit PPG), set

its source clock on lower bits (TC3CK, TC5CK).

Note 2: i = 3, 4, 6, (8-bit mode)i = 3 (16-bit mode)

Table 2-7. Operating mode and available source clock (Under SLOW1/2 mode, SLEEP1/2 mode)

Operating Mode	fc/2 <sup>11</sup> or fs/2 <sup>3</sup>	fc/2 <sup>7</sup>	fc/2 <sup>5</sup>	fc/2 <sup>3</sup>	fs	fc/2	fc	TCi pin input
8-bit Timer	0		_	_	_	_		-
8-bit Event Counter		_	_	_	_	_	_	0
8-bit PDO	0	_	_	_	_	_	_	_
8-bit PWM	0	_	_		0		_	_
16-bit Timer	0	_	_	_	_	_	_	
16-bit Event Counter	-	_	_	_	_	_	_	0
Warming-up Counter	_	-	_	_	<del>-</del>		0	_
16-bit PWM	0	_	_	_	0	_	_	0
16-bit PPG	0	_		_	_	_		0

Note 1: For 16-bit operation (16-bit Timer/Event Counter, Warming-up Counter, 16-bit PWM and 16-bit PPG), set its source clock on lower bits (TC3CK, TC5CK).

Note 2: i = 3, 4, 6, (8-bit mode)i = 3 (16-bit mode)

Table 2-8. Restriction against the Rate for Comparing Registers

Operating Mode	Authorized Rate for Register				
8-bit Timer/Event Counter	1 ≤ (TTREGn) ≤ 255				
8-bit PDO	1 ≦ (TTREGn) ≦ 255				
8-bit PWM	2 ≤ (PWREGn) ≤ 254				
16-bit Timer/Event Counter	$1 \le (TTREG4, 3) \le 65535, 1 \le (TTREG6, 5) \le 65535$				
fc Warming-up Counter	256≤ (TTREG4, 3) ≤ 65535, 256 ≤ (TTREG6, 5) ≤ 65535				
16-bit PWM	$2 \le (PWREG4, 3) \le 65534, 2 \le (PWREG6, 5) \le 65534$				
16-bit PPG	$1 \le (PWREG4, 3) < (TTREG4, 3) \le 65535$ and $(PWREG4, 3) + 1 < (TTREG4, 3)$ $1 \le (PWREG6, 5) < (TTREG6, 5) \le 65535$ and $(PWREG6, 5) + 1 < (TTREG6, 5)$				

Note: n = 3 to 6

#### 2.7.3 Function

Timer/Counter 3, 4, 5 and 6 have eight operating modes: 8-bit timer, 8-bit external trigger timer, 8-bit programmable divider output mode, 8-bit pulse width modulation output mode, 16-bit timer, 16-bit external trigger timer, 16-bit pulse width modulation output mode, 16-bit programmable pulse generator output mode.

16-bit timer mode can use Timer counter 3 and 4 (5, 6) by cascade connection.

(1) 8-bit Timer Mode (Timer/Counter 3, 4, 5 and 6)

In this mode, counting up is performed using the internal clock. The contents of TTREGi are compared with the contents of up-counter. If a match is found, an INTTCi interrupt is generated, and the counter is cleared to "0". Counting up resumes after the counter is cleared.

Note 1: In the timer mode, always write TCjCR<TFFj> to "0". If TFFj is set to "1", unexpected pulse may be output from PDOj / PWMj / PPGj pin.

Note 2: In the timer mode, do not change the setting of timer registers (TTREGi) while timer/counter is operating. Since TTREGi is configured as one-stage register, a newly set value is immediately reflected on the timer register.

Note 3: i = 3, 4, 6 i = 3 to 6

Table 2-9. Timer/Counter 1 Source Clock (Internal Clock)

	Source clock		Resolution			Maximum time setting		
NORMAL1/2, IDLE1/2 modes		SLOW1/2, SLEEP1/2	At fc = 16 MHz		A+ fc = 22 768 kHz	At fc = 16 MHz	At fs = 32.768 kHz	
DV7CK = 0	DV7CK = 1	modes	At it = 16 Minz		At 13 = 32.700 K112	Acic- Totaliz	AC 13 = 32.700 KHZ	
fc/2 <sup>11</sup> [Hz] fc/2 <sup>7</sup> fc/2 <sup>5</sup> fc/2 <sup>3</sup>	fs / 2 <sup>3</sup> [Hz] fc / 2 <sup>7</sup> fc / 2 <sup>5</sup> fc / 2 <sup>3</sup>	fs / 2 <sup>3</sup> [Hz] - - -	128 8 2 500	[μs] [μs] [μs] [ns]	244.14 [μs] - - -	32.6 [ms] 2.0 [ms] 510 [μs] 127.5 [μs]	62.3 [ms] - - -	

Example: Sets the timer mode with source clock fc/2<sup>7</sup> [Hz] and generates an interrupt 80  $\mu$ s later (at fc = 16 MHz).

LDW (TTREG4), 0AH

; Sets the timer register (80  $\mu$ s ÷ 2<sup>7</sup>/fc = 0A<sub>H</sub>)

 $\mathbf{DI}$ 

SET (EIRH). EF11

; Enables INTTC4 interrupt

 $\mathbf{EI}$ 

LD (TC4CR), 00010000B

Sets the 8-bit timer mode and source clock ( $fc/2^7$ )

LD (TC4CR), 00011000B; Starts TC4

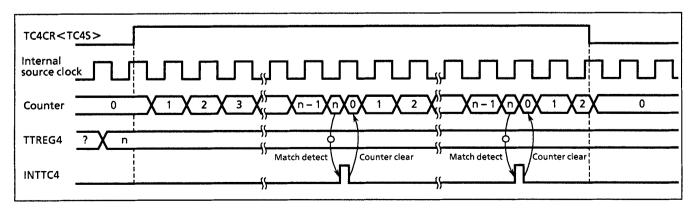


Figure 2-31. 8-bit Timer Mode Timing Chart (In Case of Timer/Counter 4)

## (2) 8-bit Event Counter Mode (Timer/Counter 3, 4 and 6)

In this mode, events are counted on the falling edge of TCj pin input. The contents of TTREGj are compared with the contents of up-counter. If a match is found, an INTTCj interrupt is generated, and the counter is cleared. The maximum applied frequency is  $fc/2^4$  [Hz] in NORMAL1/2 or IDLE1/2 mode and  $fs/2^4$  [Hz] in SLOW1/2 or SLEEP1/2 mode. Two or more machine cycles are required for both the "H" and "L" levels of the pulse width.

Note 1: In the event counter mode, always write TCjCR < TFFj > to "0". If TFFj is set to "1", unexpected pulse may be output from PDOj / PWMj / PPGj pin.

Note 2: In the event counter mode, do not change the setting of timer registers (TTREGj) while timer/counter is operating. Since TTREGj is configured as one-stage register, a newly set value is immediately reflected on the timer register.

Note 3: j = 3, 4, 6

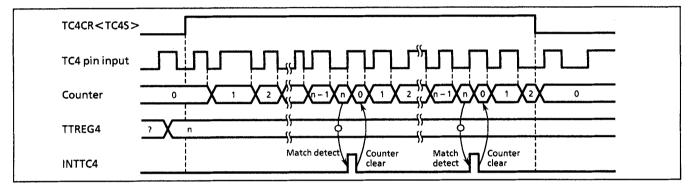


Figure 2-32. Event Counter Mode Timing Chart (In Case of Timer/Counter 4)

## (3) 8-bit Programmable Divider Output (PDO) Mode (Timer/Counter 3, 4 and 6)

The internal clock is used for counting up. The contents of TTREGj are compared with the contents of the up-counter. Timer F/Fj output is toggled and the counter is cleared each time a match is found. Timer F/Fj output is inverted and output to the  $\overline{PDOj}$  pin. When used as a this mode, respective output latch should be set to "1". This mode can be used for 50% duty pulse output. Timer F/Fj can be initialized by program, and it is initialized to "0" during reset. An INTTCj interrupt is generated each time the  $\overline{PDOj}$  output is toggled.

Example: Output a 1024 Hz pulse (at fc = 16 MHz = "0", in case of TC4)

SET (P3DR). 2 ; P32 output latch ←1

LD (TTREG4), 7AH ;  $(1/1024 \div 2^7/\text{fc}) \div 2 = 7A_\text{H}$ LD (TC4CR), 00010001B ; Sets the 8-bit PDO mode and source clock (fc/2<sup>7</sup>)

LD (TC4CR), 00011001B ; Starts TC4

Note 1: In the programmable divider output(PDO) mode, do not change the setting of timer registers (TTREGj) while timer/counter is operating. Since TTREGj is configured as one-stage register, a newly set value is immediately reflected on the timer register.

Note 2: If PDO output is stopped during output operation, the output state is maintained at the state immediately before timer/counter is stopped. For changing the level of PDOj pin, modify TCjCR<TTFj> after timer/counter has been stopped. Do not execute halt of timer/counter and modification of TFFj simultaneously.

Example: Fixes PDOj output at high level after timer/counter is stopped

CLR (TCjCR).3; Stops timer/counter.

CLR (TCjCR).7; Sets PDOj output to high level output

Note 3: j = 3, 4, 6

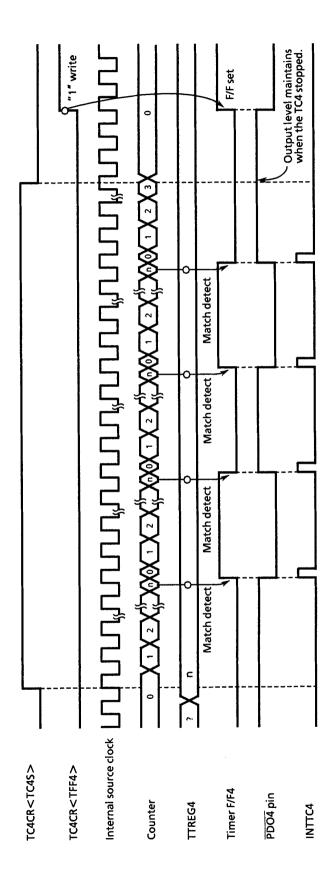


Figure 2-33. 8-bit PDO Mode Timing Chart (In Case of Tmer/Counter 4)

(4) 8-bit Pulse Width Modulation (PWM) Output Mode (Timer/Counter 3, 4 and 6)

PWM output with a resolution of 8 bits is possible. The internal clock is used for counting up. The contents of PWREGi are compared with the contents of up-counter. If a match is found, the timer F/Fi output is toggled. The counter continues counting. And, when an overflow occurs, the timer F/Fi output is again toggled and the counter is cleared. Timer F/Fi output is inverted and output to the  $\overline{PWMi}$  pin. An INTTCi interrupt is generated when an overflow occurs.

In PWM mode, because PWREGi becomes a 2-stage registers with shift register, it is possible to change the setting value of PWREGi while timer/counter is operating. Therefore, output can be altered continuously. The shift operation of PWREGi to shift register is executed at the INTTCi timing. While timer/counter is operating, the data by read instruction is not a setting value of PWREGi but a value of shift register. Thereofre, after writing to PWREGi, the reading data of PWREGi is previous value till INTTCi is generated.

While timer/counter stops, written value to PWREGi is shifted to shift register immediately.

- Note 1: In PWM mode, write to the timer register PWREGi immediately after an INTTCi interrupt is generated (normally during the INTTCi interrupt service routine). If writing to PWREGi and INTTCi interrupt occur at the same time, the unstable value being written is shifted. This may cause pulses different from the set value to be output until the next INTTCi interrupt is generated.
- Note 2: If PWM output is stopped during output operation, the output state is maintained at the state immediately before timer/counter is stopped. For changing the level of PWMi, modify TCiCR<TTFi> after timer/counter has been stopped. Do not execute halt of timer/counter and modification of TFFi simultaneously.

Example: Fixes PWMi output at high level after timer/counter is stopped

CLR (TCiCR).3; Stops timer/counter.

CLR (TCiCR).7; Sets PWMi output to high level output

Note 3: Before starting STOP mode, disable PWM output. When the timer/counter is enabled and fc, fc/2 or fs is selected as the source clock, pulse is output from PWM pin during warming-up after releasing STOP mode.

Note 4: i = 3, 4, 6

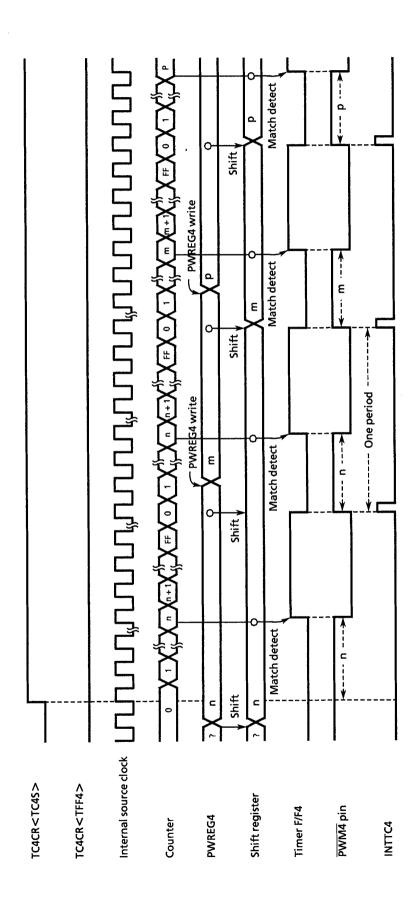


Figure 2-34. 8-bit PWM Mode Timing Chart (In Case of Timer/Counter 4)

	Source clock		Resolution		Maximum setting time	
NORMAL1/2, IDLE1/2 mode		SLOW1/2, SLEEP1/2	o fc = 16 MHz	fs = 32.768 kHz	fc = 16 MHz	fs = 32.768 kHz
DV7CK = 0	DV7CK = 1	mode			10 10 101112	
fc/2 <sup>11</sup> [Hz]	fs/2 <sup>3</sup> [Hz]	fs/2 <sup>3</sup> [Hz]	128 [μs]	244.14 [μs]	32.8 [ms]	62.5 [ms]
fc/2 <sup>7</sup>	fc/2 <sup>7</sup>	-	8 [μs]	-	2.05 [ms]	
fc/2 <sup>5</sup>	fc/2⁵	-	2 [μs]	-	512 [μs]	-
fc/2 <sup>3</sup>	fc/2³	_	500 [ns]	-	128 [μs]	-
fs	fs	fs	30.5 [μs]	30.5 [ <i>μ</i> s]	7.81 [ms]	7.81 [ms]
fc/2	fc/2	_	125 [ns]	<b>-</b> `	32 [μs]	-
fc	fc	-	62.5 [ns]	-	16 [μs]	

Table 2-10. PWM Output Mode

(5) 16-bit Timer Mode (Timer/counter 3 and 4, Timer/counter 5 and 6)

In this mode, counting up is performed using the internal clock.

- Timer/counter 3 and 4 (5 and 6) are also available as a 16-bit timer mode by cascade connection.
- a. 16 bit timer mode of Timer/counter 3 and 4

  If a match is found, the INTTC4 interrupt is generated and the counter is cleared to "0". Counting up resumes after the counter is cleared. The timer register should write to the TTREG3 more first than TTREG4. The timer register must not write only either TTREG3 or TTREG4.
- b. 16 bit timer mode of Timer/counter 5 and 6
  If a match is found, the INTTC6 interrupt is generated and the counter is cleared to "0". Counting up resumes after the counter is cleared. The timer register should write to the TTREG5 more first than TTREG6. The timer register must not write only either TTREG5 or TTREG6.
- Note 1: In the timer mode, always write TCjCR<TFFj> to "0". If TFFj is set to "1", unexpected pulse may be output from PDOj / PWMj / PPGj pin.
- Note 2: In the timer mode, do not change the setting of timer registers (TTREGI) while timer/counter is operating. Since TTREGI is configured as one-stage register, a newly set value is immediately reflected on the timer register.
- Note 3: j = 3, 4, 6 i = 3 to 6

Table 2-11. Source Clock of 16-bit Timer Mode

	Source clock		Res	solution	Maximum setting time	
NORMAL1/2, IDLE1/2 mode		SLOW1/2, SLEEP1/2	At fc = 16 MHz	At fs = 32.768 kHz	At fc = 16 MHz	At fs = 32.768 kHz
DV7CK = 0	DV7CK = 1	mode ACIC = 16 MIN2			At 10 10 10 11 12	
fc/2 <sup>11</sup>	fs/2 <sup>3</sup> [Hz]	fs/2 <sup>3</sup>	128 [μs]	244.14 [μs]	8.39 [s]	16 [s]
fc/2 <sup>7</sup>	fc/2 <sup>7</sup>	-	8 [μs]	-	524.3 [ms]	_
fc/2⁵	fc/2 <sup>5</sup>	_	2 [μs]		131.1 [ms]	-
fc/2³	fc/2 <sup>3</sup>	-	500 [ns]	-	32.8 [ms]	-

Example: Set the 16-bit timer mode with source clock fc/27 [Hz] and generates an interruput 300 [ms] later (at fc = 16 [MHz])

LDW (TTREG3), 927CH ; Sets the timer register (300 ms  $\div$  27/fc = 927C<sub>H</sub>)

 $\mathbf{DI}$ 

SET (EIRH). EF11 ; Enable INTTC4 interrupt

 $\mathbf{EI}$ 

LD (TC3CR), 13H; Sets the 16-bit timer mode (lower) and source clock

LD (TC4CR), 04H; Sets the 16-bit timer mode (upper)

LD (TC4CR), 0CH; Starts timer/counter

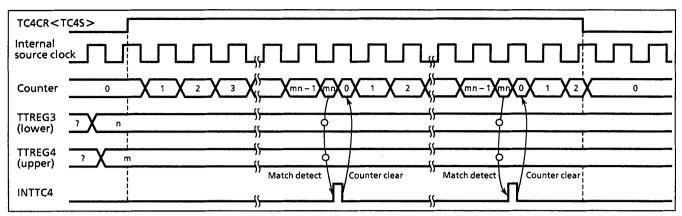


Figure 2-35. 16-bit Timer Mode Timing Chart (In Case of Timer/Counter 3 and 4)

(6) 16-bit Event Counter Mode (Timer/counter 3 and 4)

In this mode, event are counted on the falling edge of the TC3 pin input. Timer/counter 5 and 6 are can not use a 16-bit Event Counter Mode. Timer/counter 3 and 4 are also available as a 16-bit Event counter mode by cascade connection.

- a. 16 bit event counter mode of Timer/counter 3 and 4

  If a match is found, the INTTC4 interrupt is generated and the counter is cleared to "0". After the counter is cleared, counting up resumes every falling edge of TC3 input. The maximum applied frequency is fc/2<sup>4</sup> [Hz] in NORMAL1/2 or IDLE1/2 mode and fs/2<sup>4</sup> [Hz] in SLOW1/2 or SLEEP1/2 mode. Two or more machine cycles are required for both the "H" and "L" levels of the pulse width. The timer register should write to the TTREG3 more first than TTREG4. The timer register must not write only either TTREG3 or TTREG4.
- Note 1: In the event counter mode, always write TCjCR<TFFj> to "0". If TFFj is set to "1", unexpected pulse may be output from PDOj / PWMj / PPGj pin.
- Note 2: In the event counter mode, do not change the setting of timer registers (TTREGj) while timer/counter is operating. Since TTREGj is configured as one-stage register, a newly set value is immediately reflected on the timer register.

Note 3: j = 3, 4

(7) 16-bit Pulse Width Modulation (PWM) Output Mode (Timer/counter 3 and 4, Timer/counter 5 and 6)

PWM output with a resolution of 16 bits is possible. Timer/counter 3 and 4 (5 and 6) are also available as a 16-bit PWM output mode by cascade connection.

a. 16 bit PWM output mode of Timer/counter 3 and 4

The contents of PWREG3/4 are compared with the contents of up-counter. If a match is found, the timer F/F4 output is toggled. The counter continues counting. And, when an overflow occurs, the timer F/F4 output is again toggled and the counter is cleared. Timer F/F4 output is inverted and output to the \$\overline{PWM4}\$ pin. An INTTC4 interrupt is generated when an overflow occurs. When used as \$\overline{PWM4}\$ pin, respective output latch should be set to "1". In PWM mode, because PWREG4/3 each becomes a 2-stage registers with shift register, it is possible to change the setting value of PWREG4/3 while timer/counter is operating. Therefore, output can be altered continuously. The shift operation of PWREG4/3 to shift register is executed at the INTTC4 timing. While timer/counter is operating, the data by read instruction is not a setting value of PWREG4/3 but a value of shift register. Therefore, after writing to PWREG4/3, the reading data of these registers is previous value till INTTC4 is generated.

While timer/counter stops, written value to PWREG4/3 is shifted to shift register immediately. When writing to PWREG4/3, always write to the lower side (PWREG3) and then the upper side (PWREG4) in that order. Writing to only lower side (PWREG3) or the upper side (PWREG4) has no effect.

b. 16 bit PWM output mode of Timer/counter 5 and 6

The contents of PWREG5/6 are compared with the contents of up-counter. If a match is found, the timer F/F6 output is toggled. The counter continues counting. And, when an overflow occurs, the timer F/F6 output is again toggled and the counter is cleared. Timer F/F6 output is inverted and output to the PWM6 pin. An INTTC6 interrupt is generated when an overflow occurs. When used as PWM6 pin, respective output latch should be set to "1". In PWM mode, because PWREG6/5 each becomes a 2-stage registers with shift register, it is possible to change the setting value of PWREG6/5 while timer/counter is operating. Therefore, output can be altered continuously. The shift operation of PWREG6/5 to shift register is executed at the INTTC6 timing. While timer/counter is operating, the data by read instruction is not a setting value of PWREG6/5 but a value of shift register. Therefore, after writing to PWREG6/5, the reading data of these registers is previous value till INTTC6 is generated.

While timer/counter stops, written value to PWREG6/5 is shifted to shift register immediately. When writing to PWREG6/5, always write to the lower side (PWREG5) and then the upper side (PWREG6) in that order. Writing to only lower side (PWREG5) or the upper side (PWREG6) has no effect.

Note 1: In PWM mode, write to the timer register PWREGm,n immediately after an INTTCm interrupt is generated (normally during the INTTCm interrupt service routine). If writing to PWREGm, n and INTTCm interrupt occur at the same time, the unstable value being written is shifted. This may cause pulses different from the set value to be output until the next INTTCm interrupt is generated.

Note 2: If PWM output is stopped during output operation, the output state is maintained at the state immediately before timer/counter is stopped. For changing the level of PWMi, modify TCiCR<TTFi> after timer/counter has been stopped. Do not execute halt of timer/counter and modification of TFFi simultaneously.

Example: Fixes PWMi output at high level after timer/counter is stopped

CLR (TCiCR).3; Stops timer/counter

CLR (TCiCR).7; Sets PWMi output to high level output

Note 3: Before starting STOP mode, disable PWM output. When the timer/counter is enabled and fc, fc/2 or fs is selected as the source clock, pulse is output from PWM pin during warming-up after releasing STOP mode.

Note 4: m = 4 and n = 3, or m = 6 and n = 5.

Table 2-12. 16-bit PWM Output Mode

	Source clock			olution	Maximum setting time	
NORMAL1/2, IDLE1/2 mode		SLOW1/2, SLEEP1/2	At fc = 16 MHz	At fs = 32.768 kHz	At fc = 16 MHz	At fs = 32.768 kHz
DV7CK = 0	DV7CK = 1	mode	At it = 16 Minz	AL IS = 32.766 KHZ	ACICE TOTVIAZ	AL 15 = 32.700 KMZ
fc/2 <sup>11</sup>	fs/2 <sup>3</sup> [Hz]	fs/2 <sup>3</sup>	128 [μs]	244.14 [μs]	8.39 [s]	16 [s]
fc/2 <sup>7</sup>	fc/2 <sup>7</sup>	_	8 [μs]	-	524.3 [ms]	_
fc/2 <sup>5</sup>	fc/2 <sup>5</sup>	_	2 [μs]	-	131.1 [ms]	-
fc/2 <sup>3</sup>	fc/2 <sup>3</sup>	_	500 [ns]		32.8 [ms]	_
fs	fs	fs	30.5 [μs]	30.5 [ <i>μ</i> s]	2 [s]	2 [s]
fc/2	fc/2	_	125 [ns]	<del>-</del>	8.2 [ms]	-
fc	fc		62.5 [ns]	_	4.1 [ms]	<b>-</b>

Example: Extract the pulse, whose term and "high" width is 32.768 ms and 1ms respectively, from P32 width 16-bit PWM mode (at fc=16 MHz = "0", DV7CK=0)

SET (P3DR). 2 ; Sets P32 output data latch to "1"

LDW(PWREG3), 07D0H; Sets pulse width

LD (TC3CR), 33H; Sets the 16-bit PWM mode (lower) and source clock (fc/2<sup>3</sup>) LD (TC4CR), 0D6H; Sets the TFF4 to "1" and sets the 16-bit PWM mode (upper)

LD (TC4CR), 0DEH; Starts timer/counter

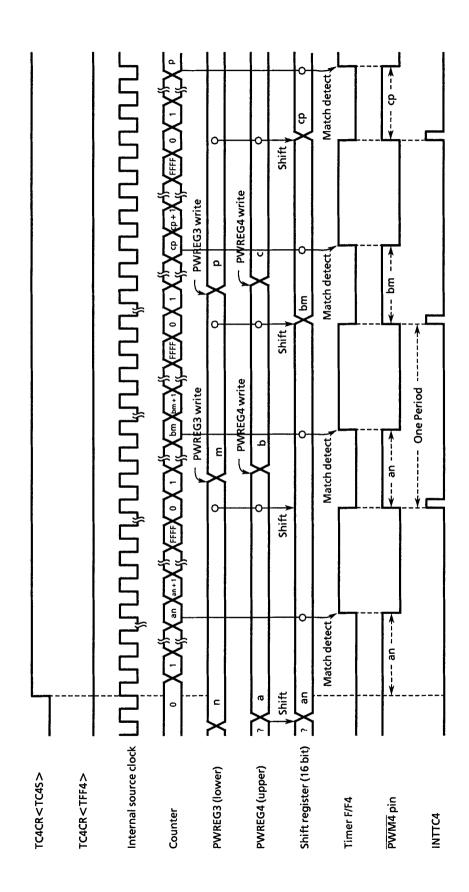


Figure 2-36. 16-bit PWM ModeTiming Chart (In Case of Timer/Counter 3 and 4)

(8) 16-bit Programmable Pulse Generate (PPG) output mode (Timer/counter 3 and 4, Timer/counter 5 and 6)

PPG output with a resolution of 16 bits is possible. Timer/counter 3 and 4 (5 and 6) are also available as a 16-bit PPG output mode by cascade connection.

a. 16 bit PPG output mode of Timer/counter 3 and 4

First, the contents of PWREG3/4 are compared with the contents of up-counter. If a match is found, the timer F/F4 output is toggled. Next, timer F/F4 is again toggled and the counter is cleared by matching with TTREG3/4. The INTTC4 interrupt is generated at this time.

When used as PPG4 pin, respective output latch should be set to "1". During reset, the F/F4 is initialized to "0".

The F/F4 output is configured by TC4CR<TFF4>. Therefore, the PPG4 can output either output high or output low at first time. The timer register should write to the PWREG3/TTREG3 more first than PWREG4/TTREG4. The timer register must not write only either PWREG3/TTREG3 or PWREG4/TTREG4.

b. 16 bit PPG output mode of Timer/counter 5 and 6

First, the contents of PWREG5/6 are compared with the contents of up-counter. If a match is found, the timer F/F6 output is toggled. Next, timer F/F6 is again toggled and the counter is cleared by matching with TTREG5/6. The INTTC6 interrupt is generated at this time.

When used as PPG6 pin, respective output latch should be set to "1". During reset, the F/F6 is initialized to "0".

The F/F6 output is configured by TC6CR<TFF6>. Therefore, the PPG6 can output either output high or output low at first time. The timer register should write to the PWREG5/TTREG5 more first than PWREG6/TTREG6. The timer register must not write only either PWREG5/TTREG5 or PWREG6/TTREG6.

Example: Extract the pulse, whose term and "high" width is 16.385 ms and 1ms respectively, from P32 with 16-bit PPG mode (at fc=16 MHz, DV7CK=0)

SET (P3DR). 2 ; Sets P32 output data latch to "1"

LDW (PWREG3), 07D0H ; Sets pulse width LDW (TTREG3), 8002H ; Sets pulse term

LD (TC3CR), 33H; Sets the 16-bit PPG mode (lower) and source clock (fc/2<sup>3</sup>) LD (TC4CR), 0D7H; Sets the TFF4 to "1" and sets the 16-bit PPG mode(upper)

LD (TC4CR), 0DFH; Starts timer/counter

Note 1: In the programmable pulse generate (PPG) mode, do not change the setting of timer registers (PWREGI, TTREGI) while timer/counter is operating. Since PWREGI, TTREGI are configured as one-stage register, a newly set value is immediately reflected on the timer register.

Note 2: If PPG output is stopped during output operation, the output state is maintained at the state immediately before timer/counter is stopped. For changing the level of PPGj, modify TCiCR<TTFi> after timer/counter has been stopped. Do not execute halt of timer/counter and modification of TFFj simultaneously.

Example: Fixes PPGj output at high level after timer/counter is stopped

CLR (TCjCR).3 ; Stops timer/counter

CLR (TCjCR).7; Sets PPGj output to high level output

Note 3: j = 4, 6 i = 3 to 6

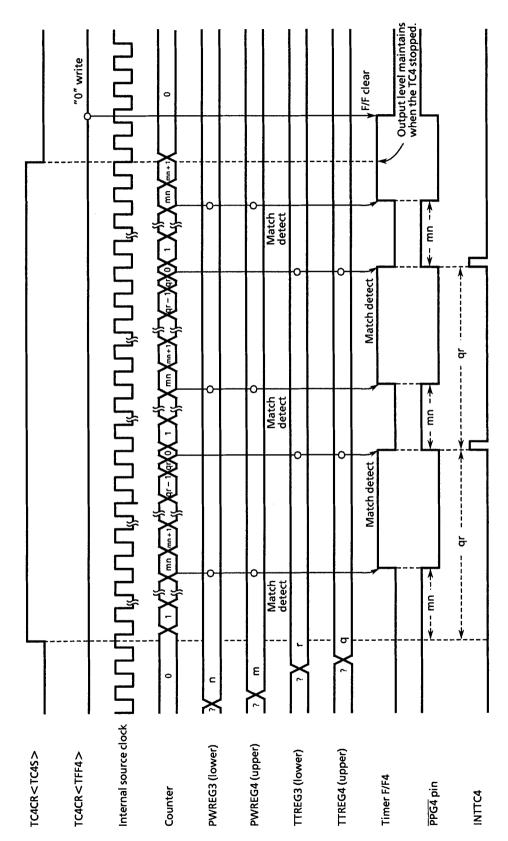


Figure 2-37. 16-bit PPG Mode Timing Chart (In Case of Timer/Counter 3 and 4)

### (9) Warming-up counter mode

In this mode, the warming-up period for switching the main system clock can be generated. Timer/counter 3 and 4 (5 and 6) are used as a 16-bit timer by cascade connection.

There are 2 modes in warming-up counter mode, one is a mode from NORMAL to SLOW and the other is a mode from SLOW to NORMAL.

- Note 1: In the warming-up mode, always write TCiCR < TFFi > to "0". If TFFi is set to "1", unexpected pulse may be output from PDOi / PWMi / PPGi pin.
- Note 2: In the warming-up mode, the lower 11 bits of TTREGm,n are ignored and an interrupt is generated by matching the upper 5 bits.
- Note 3: i = 3, 4, 6 m = 4 and n = 3, or m = 6 and n = 5

# a. Warming-up counter mode for low-frequency (NORMAL1 $\rightarrow$ NORMAL2 $\rightarrow$ SLOW2 $\rightarrow$ SLOW1)

In this mode, it can obtain the warming-up period till the oscillation for low-frequency (fs) is stabilized.

Before timer/counter is started, turn on low-frequency oscillation by setting SYSCR2<XTEN> to "1".

After timer/counter is started by setting TCmCR<TCmS>, the contents of TTREGm,n are compared with the contents of up-counter. If a match is found, an INTTCm interrupt is generated, and the counter is cleared to "0".

In the interrupt service program, stop the timer/counter and change the system clock to low-frequency clock by setting SYSCR2<SYSCK> to "1".

After that, halt the high-frequency oscillation by clearing SYSCR2 < XEN > to "0".

Table 2-13. Warming-up period for low-frequency oscillation (at fs = 32.768 kHz)

Min (at TTREGm, n = 0800H)	Max (at TTREGm, n = F800H)
62.5 ms	1.94 s

Example: Switching to the SLOW1 mode after low-frequency clock has stabilized by using TC4, 3.

	$\mathbf{SET}$	(SYSCR2).6	$; SYSCR2 < XTEN > \leftarrow "1"$
	LD	(TC3CR), 43H	; TFF3="0", fs for source clock, sets 16-bit mode
	LD	(TC4CR), 05H	;TFF4="0", sets warming-up counter mode
	LD	(TTREG3), 8000H	; sets warming-up time (depend on oscillator characteristics)
	$\mathbf{DI}$		; IMF ← "0"
	SET	(EIRH).3	; Enables INTTC4
	EI		; IMF ← "1"
	SET	(TC4CR). 3	; Starts TC4, 3
	:	:	
PINTTC4:	CLR	(TC4CR).3	; Stops TC4, 3
	SET	(SYSCR2).5	$; SYSCR2 < SYSCK > \leftarrow "1"$
			(Switches the main system clock to the low-frequency clock)
	CLR	(SYSCR2).7	; SYSCR2 < XEN > ← "0" (Turns off low-frequency oscillation)
	RETI		
	:	•	
VINTTC4:	$\mathbf{D}\mathbf{W}$	PINTTC4	; INTTC4 vector table

b. Warming-up counter mode for high-frequency(SLOW1→SLOW2→NORMAL2→NORMAL1)

In this mode, it can obtain the warming-up period till the oscillation for high-frequency (fc) is stabilized.

Before timer/counter is started, turn on high-frequency oscillation by setting SYSCR2<XEN> to "1".

After timer/counter is started by setting TCmCR<TCmS>, the contents of TTREGm,n are compared with the contents of up-counter. If a match is found, an INTTCm interrupt is generated, and the counter is cleared to "0".

In the interrupt service program, stop the timer/counter and change the system clock to high-frequency clock by clearing SYSCR2 < SYSCK > to "0".

After that, halt the low-frequency oscillation by clearing SYSCR2<XTEN> to "0".

Table 2-14. Warming-up period for high-frequency (at fc = 16 MHz)

Min (at TTREGm, n = 0800H)	Max (at TTREGm, n = F800H)
128 <i>μ</i> s	3.97 ms

Esample: Switching to the NORMAL1 mode after high-frequency clock has stabilized by using TC4, 3.

```
:SYSCR2<XEN> ←"1"
           SET
                   (SYSCR2),7
           LD
                                       ; TFF3 = "0", fc for source clock, sets 16-bit mode
                   (TC3CR), 63H
                                       ; TFF4="0", sets warming-up counter mode
           LD
                   (TC4CR), 05H
           LD
                   (TTREG3), 0F800H; Sets warming-up time (depend on oscillator characteristics)
                                       ; IMF ← "0"
           \mathbf{DI}
           SET
                  (EIRH).3
                                       ; Enables INTTC4
           \mathbf{EI}
                                       ; IMF ← "1"
           SET
                   (TC4CR).3
                                       ; Starts TC4, 3
PINTTC4: CLR
                   (TC4CR).3
                                       ; Stops TC4, 3
           CLR
                  (SYSCR2).5
                                       :SYSCR2 < SYSCK > \leftarrow "0"
                                        (Switches the main system clock to the high-frequency clock)
                                       ;SYSCR2 < XTEN > \leftarrow "0"
           CLR
                  (SYSCR2).6
                                       (Turns off high-frequency oscillation)
           RETI
VINTTC4: DW
                  PINTTC4
                                      ; INTTC4 vector table
```

# 2.8 UART (Asynchronous serial interface)

The TMP86C829A/H29A/M29A have 1 channel of UART (asynchronous serial interface). The UART is connected to external devices via RxD and TxD. RxD is also used as P15; TxD, as P16. To use P15 or P16 as the RxD or TxD pin, set P1 port output latches to 1.

# 2.8.1 Configuration

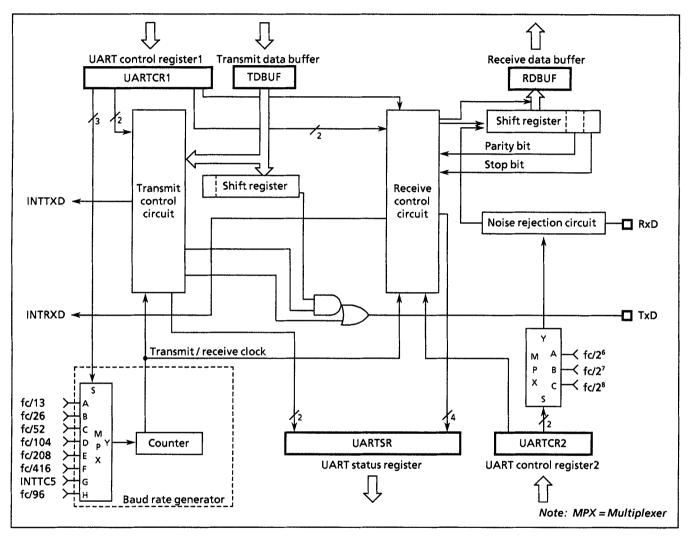


Figure 2-38. UART

#### 2.8.2 Control

UART is controlled by the UART control registers (UARTCR1, UARTCR2). The operating status can be monitored using the UART status register (UARTSR).

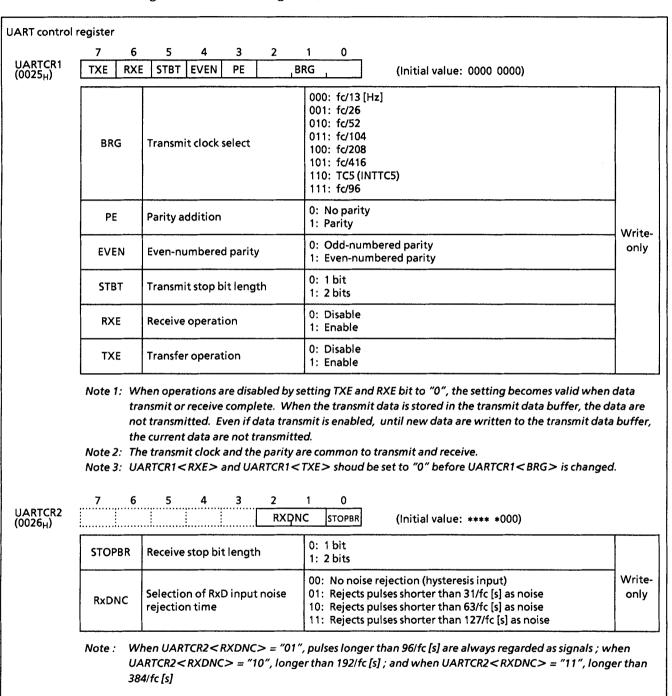


Figure 2-39. UART Control Register

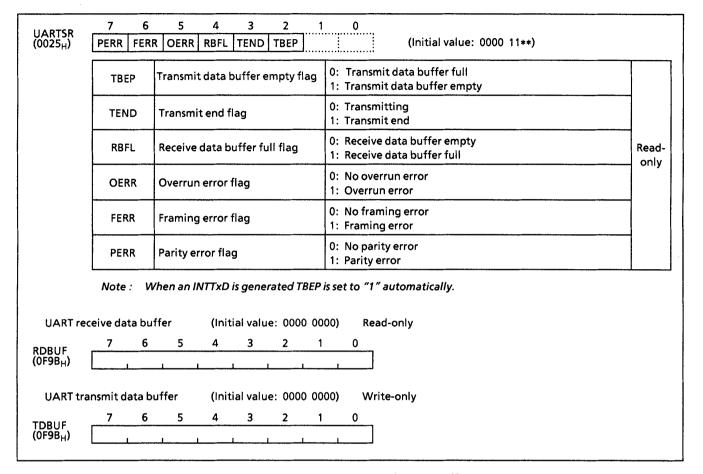


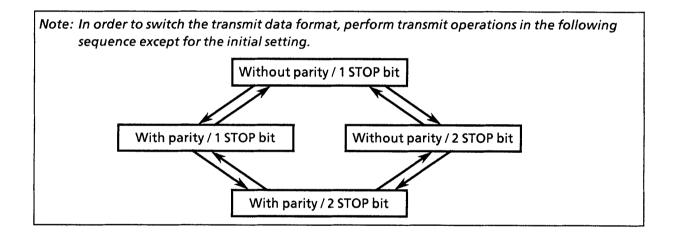
Figure 2-40. UART status register and Data Buffer Registers

#### 2.8.3 Transfer data format

In UART, a one-bit start bit (low level), stop bit (bit length selectable at high level, by UARTCR1 < STBT >), and parity (select parity in UARTCR1 < PE >; even-or odd-numbered parity by UARTCR1 < EVEN >) are added to the transfer data. The transfer data formats are shown as follow.

Frame length PΕ STBT |----| 2 1 10 12 Start Bit0 Bit6 Bit7 0 0 Stop1 1 Start Bit0 Bit6 Bit7 Stop1 Stop2 Start Bit0 Bit1 Bit6 Bit7 0 Parity Stop1 1 Start Bit0 Bit1 Bit6 Bit7 Parity ) Stop1 1 1 Stop2

Table 2-15. Transfer Data Format



#### 2.8.4 Transfer rate

The baud rate of UART is set of UARTCR1 < BRG >. The example of the baud rate shown as follows.

BRG	Sourse clock					
	16 MHz	8 MHz	4 MHz			
000	<b>768</b> 00 [baud]	38400 [baud]	19200 [baud]			
001	38400	19200	9600			
010	19200	9600	4800			
011	9600	4800	2400			
100	4800	2400	1200			
101	2400	1200	600			

Table 2-16. Transfer Rate

When TC5 is used as the UART transfer rate (when UARTCR1 < BRG > = "110"), the transfer clock and transfer rate are detarmined as follows:

# 2.8.5 Data sampling

The UART receiver keeps sampling input using the clock selected by UARTCR1 < BRG > until a start bit is detected in RxD pin input. RT clock starts at the falling edge of the RxD pin. Once a start bit is detected, the start bit, data bits, stop bit(s), and parity bit are sampled at three times of RT7, RT8, and RT9 during one receiver clock interval (RT clock). (RT0 is the position where the bit supposedly starts). Bit is determined according to majority rule (the data are the same twice or more out of three samplings).

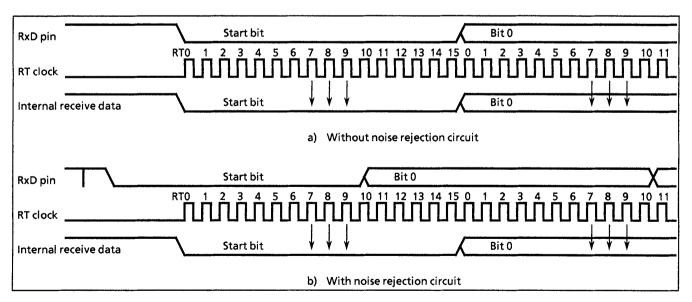


Figure 2-41. Data Samping

## 2.8.6 STOP Bit Length

Select a transmit stop bit length (1 or 2 bits) by UARTCR1<STBT>.

### 2.8.7 Parity

Set parity / no parity by UARTCR1<PE>; set parity type (odd-or even-numbered) by UARTCR1<EVEN>.

### 2.8.8 Transmit/Receive

#### (1) Data transmit

Set UARTCR1<TXE> to "1". Read UARTSR to check UARTSR<TBEP>="1", then write data in TDBUF (transmit data buffer). Writing data in TDBUF zero-clears UARTSR<TBEP>, transfers the data to the transmit shift register and the data are sequentially output from the TxD pin. The data output include a one-bit start bit, stop bits whose number is specified in UARTCR1<STBT> and a parity bit if parity addition is specified. Select the data transfer baud rate using bits 0 to 2 in UARTCR1. When data transmit starts, transmit buffer empty flag UARTSR<TBEP> is set to "1" and an INTTXD interrupt is generated.

While UARTCR1<TXE> = "0" and from when "1" is written to UARTCR1<TXE> to when send data are written to TDBUF, the TXD pin is fixed at High level. When transmitting data, first read UARTSR, then write data in TDBUF. Otherwise, UARTSR<TBEP> is not zero-cleared and transmit does not start.

## (2) Data receive

Set UARTCR1 < RXE > to "1". When data are received via the RxD pin, the receive data are transferred to RDBUF (receive data buffer). At this time, the data transmitted include a start bit and stop bit(s) and a parity bit if parity addition is specified. When stop bit(s) are received, data only are extracted and transferred to RDBUF (receive data buffer). Then the receive buffer full flag UARTSR < RBFL > is set and an INTRXD interrupt is generated. Select the data transfer baud rate using bits 0 to 2 in UARTCR1.

If an overrun error (OERR) occurs when data are received, the data are not transferred to RDBUF (receive data buffer) but discarded; data in the RDBUF are not affected.

Note: When a receive operation is disabled by setting UARTCR1<RXE> bit to "0", the setting becomes valid when data receive is completed. However, if a framing error occurs in data receive, the receive-disabling setting may not become valid. if a framing error occurs, be sure to perform a re-receive operation.

## 2.8.9 Status Flag / Interrupt Signal

### (1) Parity error

When parity determined using the receive data bits differs from the received parity bit, the parity error flag UARTSR < PERR > is set to "1". The UARTSR < PERR > is cleared to "0" when the RDBUF is read after reading the UARTSR.

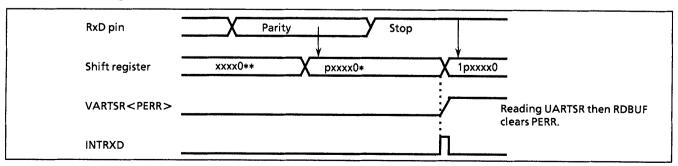


Figure 2-42. Generation of Parity Error

# (2) Framing error

When "0" is sampled as the stop bit in the receive data, framing error flag UARTSR<FERR> is set to "1". The UARTSR<FERR> is cleared to "0" when the RDBUF is read after reading the UARTSR.

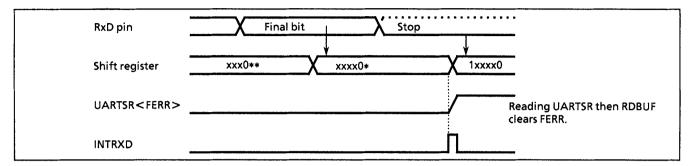


Figure 2-43. Generation of Framing Error

#### (3) Overrun error

When all bits in the next data are received while unread data are still in RDBUF, overrun error flag UARTSR < OERR > is set to "1". In this case, the receive data is discarded; data in RDBUF are not affected. The UARTSR < OERR > is cleared to "0" when the RDBUF is read after reading the UARTSR.

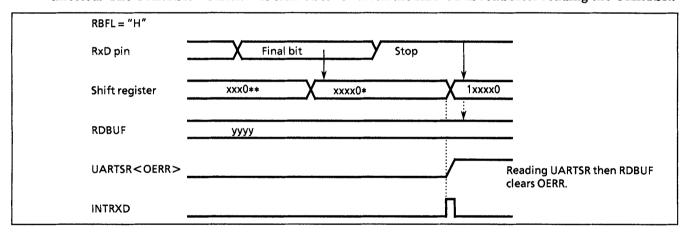


Figure 2-44. Generation of Overrun Error

## (4) Receive data buffer full

Loading the received data in RDBUF sets receive data buffer full flag UARTSR<RBFL>. The UARTSR<RBFL> is cleared to "0" when the RDBUF is read after reading the UARTSR.

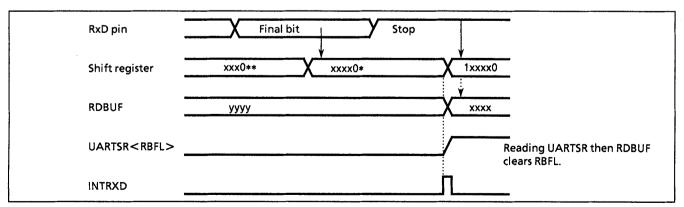


Figure 2-45. Generation of Receive Buffer Full

# (5) Transmit data buffer empty

When no data is in the transmit buffer TDBUF, UARTSR<TBEP> is set to "1", that is, when data in TDBUF are transferred to the transmit shift register and data transmit starts, transmit data buffer empty flag UARTSR<TBEP> is set to "1". The UARTSR<TBEP> is cleared to "0" when the TDBUF is written after reading the UARTSR.

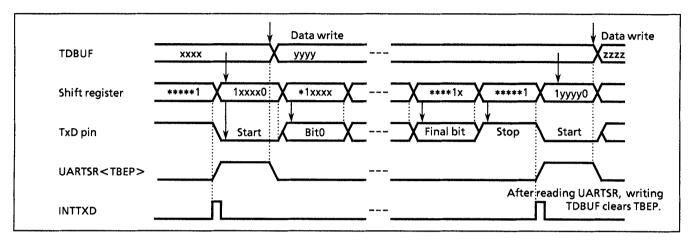


Figure 2-46. Generation of Transmit Buffer Empty

# (6) Transmit end flag

When data are transmitted and no data is in TDBUF (UARTSR<TBEP>="1"), transmit end flag UARTSR<TEND> is set to "1". The UARTSR<TEND> is cleared to "0" when the data transmit is stated after writing the TDBUF.

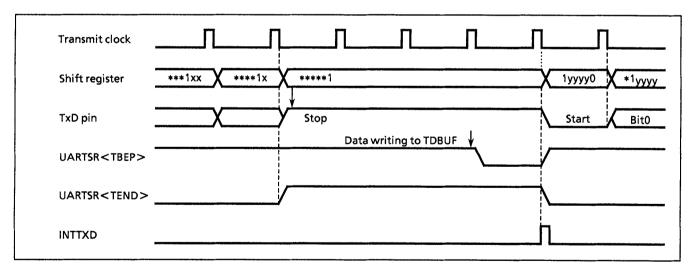


Figure 2-47. Generation of Transmit Buffer Empty

### 2.9 Serial Interface (SIO)

The TMP86C829A/H29A/M29A have one clocked-synchronous 8-bit serial interface. Serial interface has an 8-byte transmit and receive data buffer that can automatically and continuously transfer up to 64 bits of data.

The serial interface is connected to external devices via pins P16 (SO), P15 (SI), P17 ( $\overline{SCK}$ ). The serial interface pins are also used as port P1. When these pins are used as serial interface pins, the correspondence output latch should be set to "1". In the transmit mode, pin P15 can be used as normal I/O port, and in the receive mode, the pin P16 can be used as normal I/O ports.

## 2.9.1 Configuration

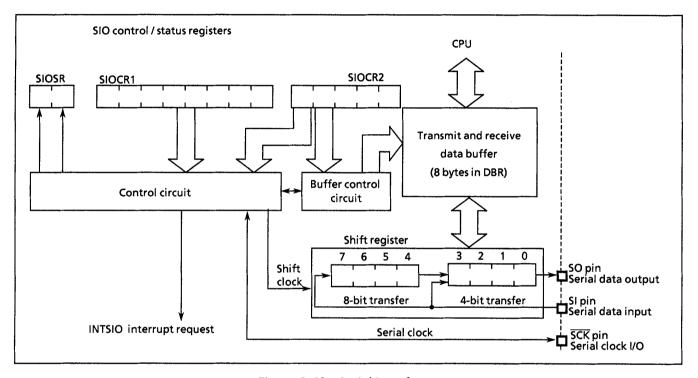


Figure 2-48. Serial Interfaces

# 2.9.2 Control

The serial interface is controlled by SIO control registers (SIOCR1/SIOCR2). The serial interface status can be determined by reading SIO status register (SIOSR).

The transmit and receive data buffer is controlled by the BUF (bits 2-0 in SIOCR2). The data buffer is assigned to address 0F90<sub>H</sub> to 0F97<sub>H</sub> for SIO in the DBR area, and can continuously transfer up to 8 words (bytes or nibbles) at one time. When the specified number of words has been transferred, a buffer empty (in the transmit mode) or a buffer full (in the receive mode or transmit/receive mode) interrupt (INTSIO) is generated.

When the internal clock is used as the serial clock in the 8-bit receive mode and the 8-bit transmit / receive mode, a fixed interval wait can be applied to the serial clock for each word transferred. Four different wait times can be selected with WAIT (bits 4 and 3 in SIOCR2).

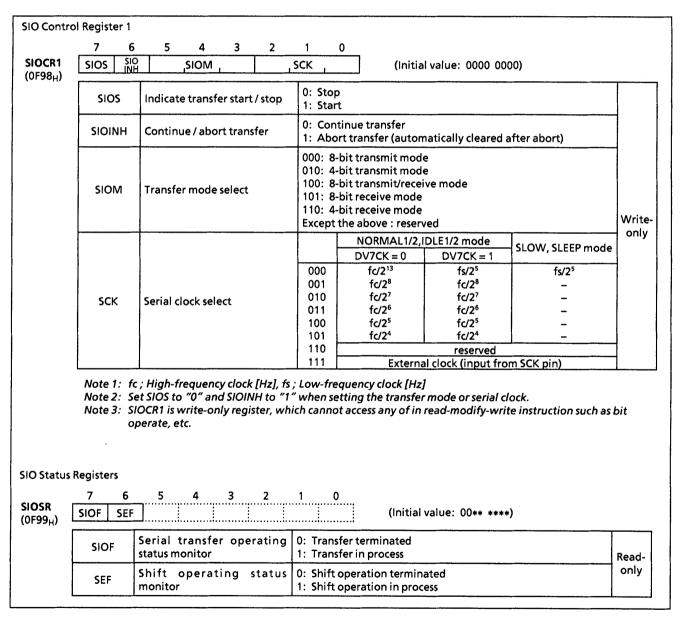


Figure 2-49. SIO Control Register and Status Register (1/2)

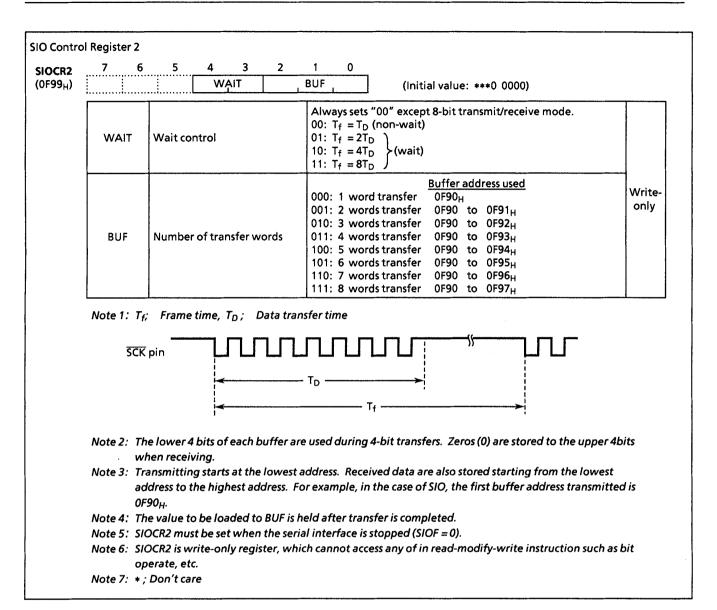


Figure 2-49. SIO Control Register and Status Register (2/2)

# (1) Serial clock

## a. Clock Source

SIOCR1 < SCK > is able to select the following:

### (1) Internal clock

Any of four frequencies can be selected. The serial clock is output to the outside on the  $\overline{SCK}$  pin. The  $\overline{SCK}$  pin goes high when transfer starts.

When data writing (in the transmit mode) or reading (in the receive mode or the transmit / receive mode) cannot keep up with the serial clock rate, there is a wait function that automatically stops the serial clock and holds the next shift operation until the read / write processing is completed.

		NORMAL1/2, II	DLE 1/2 modes	SLOW, SLEEP modes		
	DV7	CK = 0	DV7CK = 1		-11	111
SCK clock	clock	baud rate	clock	baud rate	clock	baud rate
000	fc/2 <sup>13</sup>	1.91 Kbps	fs/2 <sup>5</sup>	1024 bps	fs/2 <sup>5</sup>	1024 bps
001	fc/2 <sup>8</sup>	61.04 Kbps	fc/2 <sup>8</sup>	61.04 Kbps	-	-
010	fc/2 <sup>7</sup>	122.07 Kbps	fc/2 <sup>7</sup>	122.07 Kbps	-	
011	fc/2 <sup>6</sup>	244.14 Kbps	fc/2 <sup>6</sup>	244.14 Kbps	_	-
100	fc/2⁵	488.28 Kbps	fc/2⁵	488.28 Kbps	-	
101	fc/2 <sup>4</sup>	976.56 Kbps	fc/2⁴	976.56 Kbps	-	-
110	_	-	-	_	_	-
111	External		External		External	

Table 2-17. Serial Clock Rate

1 Kbit = 1024 bit (fc = 16 MHz, fs = 32.768 kHz)

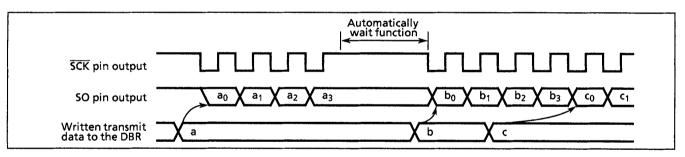
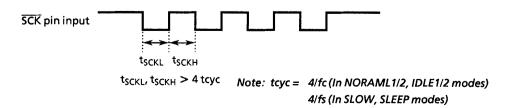


Figure 2-50. Clock Source (Internal Clock)

## ② External clock

An external clock connected to the  $\overline{SCK}$  pin is used as the serial clock. In this case, the P17 ( $\overline{SCK}$ ) must be set to the input mode. To ensure shifting, a pulse width of at least 4 machine cycles is required. This pulse is needed for the shift operation to execute certainly. Actually, there is necessary processing time for interrupting, writing, and reading. The minimum pulse is determined by setting the mode and the program.



## b. Shift edge

The leading edge is used to transmit, and the trailing edge is used to receive.

1 Leading edge

Transmitted data are shifted on the leading edge of the serial clock (falling edge of the  $\overline{SCK}$  pin input/output).

② Trailing edge

Received data are shifted on the trailing edge of the serial clock (rising edge of the  $\overline{SCK}$  pin input/output).

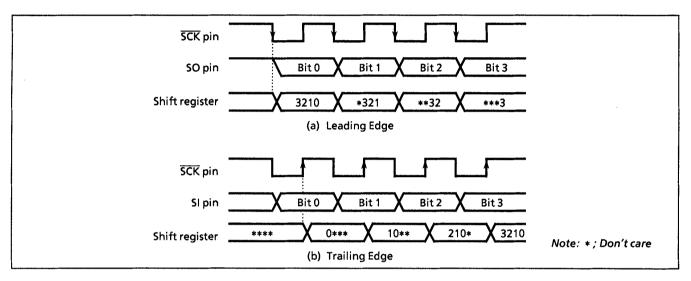


Figure 2-51. Shift Edge

## (2) Number of bits to transfer

Either 4-bit or 8-bit serial transfer can be selected. When 4-bit serial transfer is selected, only the lower 4 bits of the transmit/receive data buffer register are used. The upper 4 bits are cleared to "0" when receiving.

The data is transferred in sequence starting at the least significant bit (LSB).

### (3) Number of words to transfer

Up to 8 words consisting of 4 bits of data (4-bit serial transfer) or 8 bits (8-bit serial transfer) of data can be transferred continuously. The number of words to be transferred is loaded to SIOCR2<BUF>. An INTSIO interrupt is generated when the specified number of words has been transferred. If the number of words is to be changed during transfer, the serial interface must be stopped before making the change. The number of words can be changed during automatic-wait operation of an internal clock. In this case, the serial interface is not required to be stopped.

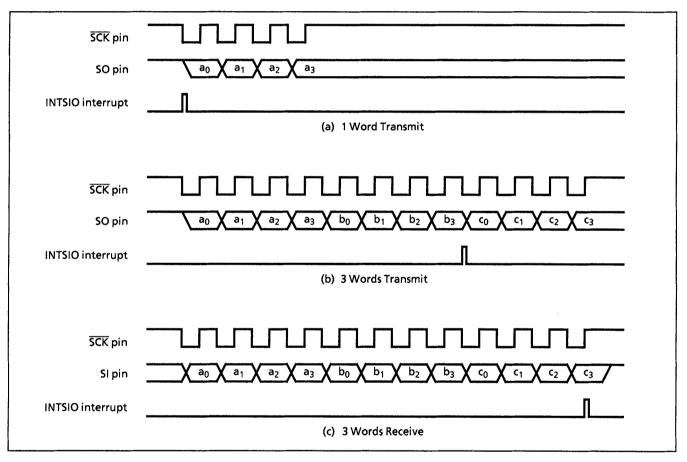


Figure 2-52. Number of Bits to Transfer (Example: 4-bit serial transfer)

#### 2.9.3 Transfer mode

SIOCR1 < SIOM > is used to select the transmit, receive, or transmit/receive mode.

## (1) 4-bit and 8-bit Transmit Modes

In these modes, the SIOCR1 is set to the transmit mode and then the data to be transmitted first are written to the data buffer registers (DBR). After the data are written, the transmission is started by setting SIOCR1<SIOS> to "1". The data are then output sequentially to the SO pin in synchronous with the serial clock, starting with the least significant bit (LSB). As soon as the LSB has been output, the data are transferred from the data buffer register to the shift register. When the final data bit has been transferred and the data buffer register is empty, an INTSIO (buffer empty) interrupt is generated to request the next transmitted data.

When the internal clock is used, the serial clock will stop and an automatic-wait will be initiated if the next transmitted data are not loaded to the data buffer register by the time the number of data words specified with the SIOCR2<BUF> has been transmitted. Writing even one word of data cancels the automatic-wait; therefore, when transmitting two or more words, always write the next word before transmission of the previous word is completed.

Note: Automatic-waits are also canceled by writing to a DBR not being used as a transmit data buffer register; therefore, during SIO do not use such DBR for other applications. For example, when 3 words are transmitted, do not use the DBR of the remained 5 words.

When an external clock is used, the data must be written to the data buffer register before shifting next data. Thus, the transfer speed is determined by the maximum delay time from the generation of the interrupt request to writing of the data to the data buffer register by the interrupt service program.

The transmission is ended by clearing SIOCR1<SIOS> to "0" or setting SIOCR1<SIOINH> to "1" in buffer empty interrupt service program. That the transmission has ended can be determined from the status of SIOSR<SIOF> because SIOSR<SIOF> is cleared to "0" when a transfer is completed.

When SIOCR1<SIOINH> is set, the transmission is immediately ended and SIOSR<SIOF> is cleared to "0".

When an external clock is used, it is also necessary to clear SIOCR1<SIOS> to "0" before shifting the next data; otherwise, dummy data will be transmitted and the operation will end.

If it is necessary to change the number of words, SIOCR1<SIOS> should be cleared to "0", then SIOCR2<BUF> must be rewritten after confirming that SIOSR<SIOF> has been cleared to "0".

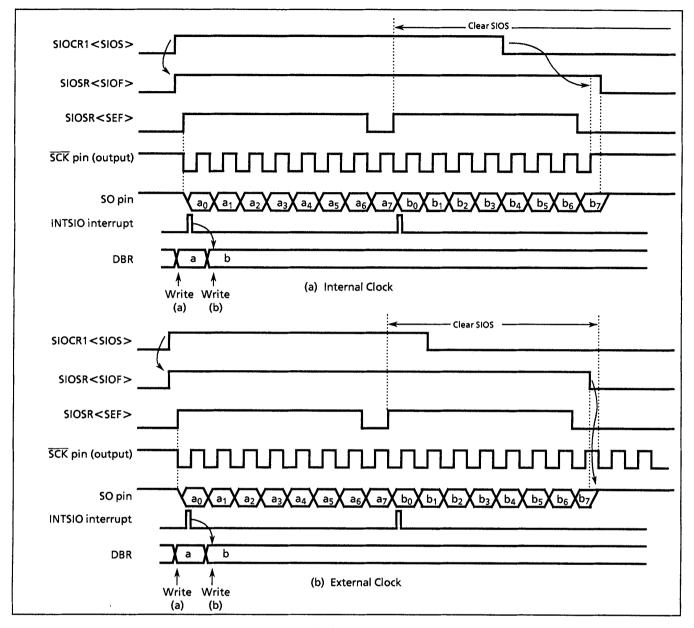


Figure 2-53. Transfer Mode (Example: 8-bit, 1 Word Transfer)

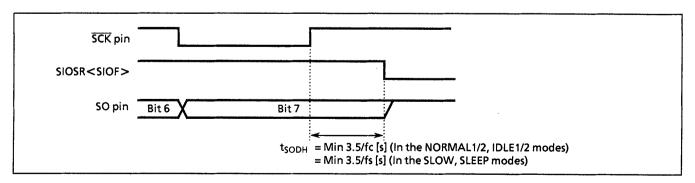


Figure 2-54. Transmitted Data Hold Time at End of Transmit

## (2) 4-bit and 8-bit receive modes

After setting the control registers to the receive mode, set SIOCR1<SIOS> to "1" to enable receiving. The data are then transferred to the shift register via the SI pin in synchronous with the serial clock. When one word of data has been received, it is transferred from the shift register to the data buffer register (DBR). When the number of words specified with the SIOCR2<BUF> has been received, an INTSIO (buffer full) interrupt is generated to request that these data be read out. The data are then read from the data buffer registers by the interrupt service program.

When the internal clock is used, and the previous data are not read from the data buffer register before the next data are received, the serial clock will stop and an automatic-wait will be initiated until the data are read. A wait will not be initiated if even one data word has been read.

Note: Waits are also canceled by reading a DBR not being used as a received data buffer register is read; therefore, during SIO do not use such DBR for other applications.

When an external clock is used, the shift operation is synchronized with the external clock; therefore, the previous data are read before the next data are transferred to the data buffer register. If the previous data have not been read, the next data will not be transferred to the data buffer register and the receiving of any more data will be canceled. When an external clock is used, the maximum transfer speed is determined by the delay between the time when the interrupt request is generated and when the data received have been read.

The receiving is ended by clearing SIOCR1<SIOS> to "0" or setting SIOCR1<SIOINH> to "1" in buffer full interrupt service program. When SIOCR1<SIOS> is cleared, the current data are transferred to the buffer. After SIOCR1<SIOS >cleared, the receiving is ended at the time that the final bit of the data has been received. That the receiving has ended can be determined from the status of SIOSR<SIOF>. SIOSR<SIOF> is cleared to "0" when the receiving is ended. After confirmed the receiving termination, the final receiving data is read. When SIOCR1<SIOINH> is set, the receiving is immediately ended and SIOSR<SIOF> is cleared to "0". (The received data is ignored, and it is not required to be read out.)

If it is necessary to change the number of words in external clock operation, SIOCR1 < SIOS > should be cleared to "0" then SIOCR2 < BUF > must be rewritten after confirming that SIOSR < SIOF > has been cleared to "0".

If it is necessary to change the number of words in internal clock, during automatic-wait operation which occurs after completion of data receiving, SIOCR2<BUF> must be rewritten before the received data is read out.

Note: The buffer contents are lost when the transfer mode is switched. If it should become necessary to switch the transfer mode, end receiving by clearing SIOCR1 < SIOS > to "0", read the last data and then switch the transfer mode.

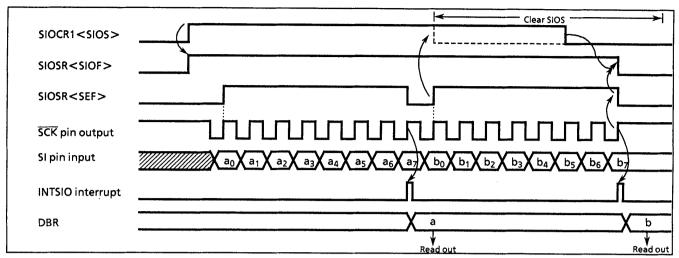


Figure 2-55. Receive Mode (Example: 8-bit, 1 word, internal clock)

## (3)8-bit transmit / receive mode

After setting the control registers to the 8-bit transmit / receive mode, write the data to be transmitted first to the data buffer registers (DBR). After that, enable transceiving by setting <SIOS> to "1". When transmitting, the data are output from the SO pin at leading edges of the serial clock. When receiving, the data are input to the SI pin at the trailing edges of the serial clock. 8-bit data are transferred from the shift register to the data buffer register. An INTSIO interrupt is generated when the number of data words specified with the <BUF> has been transferred. The interrupt service program reads the received data from the data buffer register and then writes the data to be transmitted. The data buffer register is used for both transmitting and receiving; therefore, always write the data to be transmitted after reading the received data.

When the internal clock is used, a wait is initiated until the received data are read and the next data are written. A wait will not be initiated if even one data word has been written.

Note: The wait is also canceld by writing to a DBR not being used as a transmit data buffer registers; therefore, during SIO do not use such DBR for other applications.

When an external clock is used, the shift operation is synchronized with the external clock; therefore, it is necessary to read the received data and write the data to be transmitted next before starting the next shift operation. When an external clock is used, the transfer speed is determined by the maximum delay between generation of an interrupt request and the received data are read and the data to be transmitted next are written.

The transmit / receive operation is ended by clearing SIOCR1<SIOS> to "0" or setting SIOSR<SIOINH> to "1" in interrupt service program.

When SIOCR1<SIOINH> is set, the transmit / receive operation is immediately ended and SIOSR<SIOF> is cleared to "0".

If it is necessary to change the number of words in external clock operation, SIOCR1 < SIOS > should be cleared to "0", then SIOCR2 < BUF > must be rewritten after confirming that SIOSR < SIOF > has been cleared to "0".

If it is necessary to change the number of words in internal clock, during automatic-wait operation which occurs after completion of transmit / receive operation, SIOCR2<BUF> must be rewritten before reading and writing of the receive / transmit data.

Note: The buffer contents are lost when the transfer mode is switched. If it should become necessary to switch the transfer mode, end receiving by clearing SIOCR1<SIOS> to "0", read the last data and then switch the transfer mode.

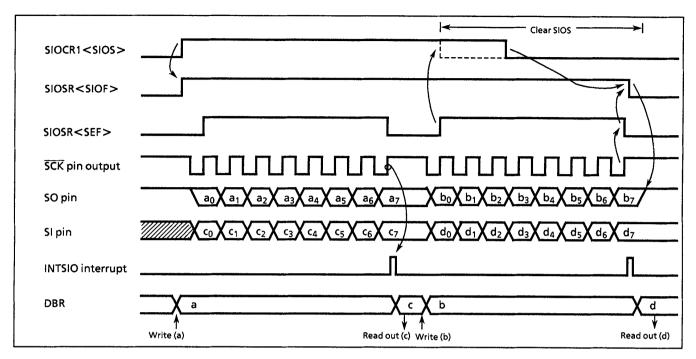


Figure 2-56. Transmit/Receive Mode (Example: 8-bit, 1word, internal clock)

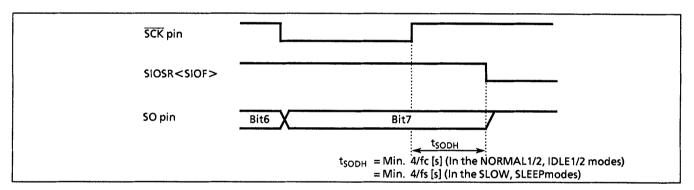


Figure 2-57. Transmitted Data Hold Time at End of Transmit/Receive

## 2.10 10-bit AD Converter (ADC)

The TMP86C829A/H29A/M29A have a 10-bit successive approximation type AD converter.

# 2.10.1 Configuration

The circuit configuration of the 10-bit AD converter is shown in Figure 2-58.

It consists of control registers ADCCR1 and ADCCR2, converted value registers ADCDR1 and ADCDR2, a DA converter, a sample-and-hold circuit, a comparator, and a successive comparison circuit.

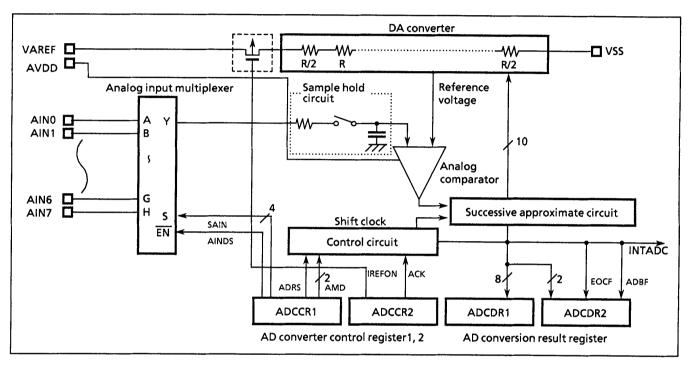


Figure 2-58. AD Converter (ADC)

## 2.10.2 Register Configuration

The AD converter consists of the following four registers:

- AD converter control register 1 (ADCCR1)
- AD converter control register 2 (ADCCR2)
- AD converted value register 1/2 (ADCDR1/ADCDR2)

### (1) AD converter control register 1 (ADCCR1)

This register selects the analog channels and operation mode (software start or repeat) in which to perform AD conversion and controls the AD converter as it starts operating.

# (2) AD converter control register 2 (ADCCR2)

This register selects the AD conversion time and controls the connection of the DA converter (ladder resistor network).

# (3) AD converted value register (ADCDR1)

This register is used to store the digital value after being converted by the AD converter.

# (4) AD converted value register (ADCDR2)

This register monitors the operating status of the AD converter.

The AD converter control register configurations are shown in Figures 2-59 and 2-60.

AD Converter Control Register 1 4 (Initial value: 0001 0000) ADCCR1 ADRS AMD AINDS SAIN (000E<sub>H</sub>) 0: -**ADRS** AD conversion start 1: Start 00: AD operation disable 01: Software start mode AMD AD Operating mode 10: reserved 11: Repeat mode 0: Analog input enable AINDS Analog input control 1: Analog input disable R/W 0000: Selects AIN0 0001: Selects AIN1 0010: Selects AIN2 0011: Selects AIN3 0100: Selects AIN4 Analog input channel select SAIN 0101: Selects AIN5 0110: Selects AIN6 0111: Selects AIN7 1\*\*\* : reserved Note 1: Select analog input when AD converter stops (ADCR2<ADBF> = "0"). Note 2: When the analog input is all use disabling, the AINDS should be set to "1". Note 3: During conversion, do not perform output instruction to maintain a precision for all of the pins. And port near to analog input, do not input intense signaling of change. Note 4: The ADRS is automatically cleared to "0" after starting conversion. Note 5: Do not set ADRS (ADCCR1 bit 7) newly again during AD conversion. Before setting ADRS newly again, check EOCF (ADCDR bit 5) to see that the conversion is completed or wait until the interrupt signal (INTADC) is generated (e.g., interrupt handling routine). Note 6: After STOP or SLOW mode are started, AD converter control register 1 (ADCCR1) is all initialized. Therefore, set the ADCCR1 newly again after exiting STOP mode. AD Converter Control Register 2 ....7 6 ADCCR2 : (Initial value: \*\*00 0000) IREFON ACK  $(000F_{H})$ Inputting current to the ladder resistor DA converter 0: Connected only during AD conversion **IREFON** (ladder resistor) 1: Always connected connection control Conversion ACK fc = 16 MHz fc = 8 MHzfc = 4 MHz fc = 2 MHztime 000 39/fc 19.5  $\mu$ s R/W 001 reserved 39.0 μs 19.5 μs 78/fc 010 AD conversion time select ACK 156.0 μs 19.5  $\mu$ s 39.0 µs 156/fc 011  $39.0~\mu s$ 100 312/fc 19.5 μs 156.0 μs 78.0 µs 101 624/fc 39.0  $\mu$ s 110 1248/fc 78.0 μs 156.0 μs reserved 111

Note 1: Settings for "-" in the above table are inhibited.

Note 2: Set conversion time by analog reference voltage (VAREF) as follows.

 $V_{AREF} = 4.5 \text{ to } 5.5 \text{ V } (15.6 \,\mu\text{ or more})$  $V_{AREF} = 2.7 \text{ to } 5.5 \text{ V } (31.2 \,\mu\text{ or more})$ 

 $V_{AREF} = 1.8 \text{ to } 5.5 \text{ V } (124.8 \,\mu \text{ or more})$ 

Note 3: Always set bit 0 in ADCCR2 to "0" and set bit 4 in ADCCR2 to "1".

Note 4: When a read instruction for ADCCR2, bit 6 to 7 in ADCCR2 read in as undefined data.

Note 5: fc; High-frequency clock [Hz]

Note 6: After STOP or SLOW mode are started, AD converter control register 2 (ADCCR2) is all initialized.

Therefore, set the ADCCR2 newly again after exiting STOP mode.

Figure 2-59. AD Converter Control Register

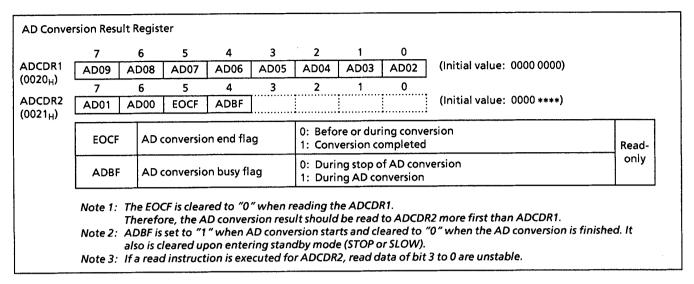


Figure 2-60. AD Converter Result Register

## 2.10.3 AD Converter operation

- (1) Set up the AD converter control register 1 (ADCCR1) as follows:
  - Choose the channel to AD convert using AD input channel select (SAIN).
  - Specify analog input enable for analog input control (AINDS).
  - Specify AMD for the AD converter control operation mode (software or repeat mode).
- (2) Set up the AD converter control register 2 (ADCCR2) as follows:
  - Set the AD conversion time using AD conversion time (ACK). For details on how to set the conversion time, refer to Note 2 for AD converter control register 2.
  - Choose IREFON for DA converter control.
- (3) After setting up (1) and (2) above, set AD conversion start (ADRS) of AD converter control register 1 (ADCCR1) to "1". If software start mode has been selected, AD conversion starts immediately.
- (4) After an elapse of the specified AD conversion time, the AD converted value is stored in AD converted value register 1 (ADCDR1) and the AD conversion finished flag (EOCF) of AD converted value register 2 (ADCDR2) is set to "1", upon which time AD conversion interrupt INTADC is generated.
- (5) EOCF is cleared to "0" by a read of the conversion result. However, if reconverted before a register read, although EOCF is cleared the previous conversion result is retained until the next conversion is completed.

## 2.10.4 AD converter operation modes

There are following two AD converter operation modes:

- Software start: AD conversion is performed once by setting AMD to "01" and ADRS to "1".
- Repeat mode: AD conversion is performed repeatedly by setting AMD to "11" and ADRS to "1".

## (1) Software start mode

After setting AMD (ADCCR1 bits 5, 6) to "01" (software start mode), set ADRS (ADCCR1 bit 7) to "1". AD conversion of the voltage at the analog input pin specified by SAIN (ADCCR1 bits 0-3) is thereby started.

After completion of the AD conversion, the conversion result is stored in AD converted value registers (ADCDR1, 2) and at the same time EOCF (ADCDR2 bit 5) is set to 1, the AD conversion finished interrupt (INTADC) is generated.

ADRS is automatically cleared after AD conversion has started. Do not set ADRS (ADCCR1 bit 7) newly again (restart) during AD conversion. Before setting ADRS newly again, check EOCF (ADCDR bit 5) to see that the conversion is completed or wait until the interrupt signal (INTADC) is generated (e.g., interrupt handling routine).

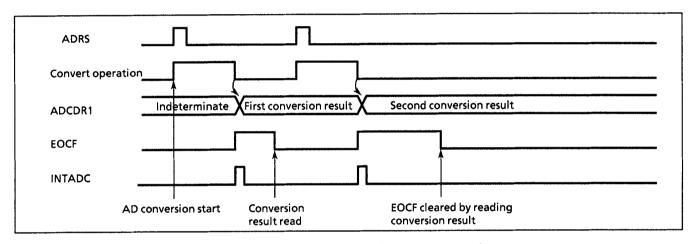


Figure 2-61. Operation in Software Start Mode

# (2) Repeat mode

AD conversion of the voltage at the analog input pin specified by SAIN (ADCCR1 bits 0 to 3) is performed repeatedly. In this mode, AD conversion is started by setting ADRS (ADCCR1 bit 7) to "1" after setting AMD (ADCCR1 bits 5,6) to "11".

After completion of the AD conversion, the conversion result is stored in AD converted value registers (ADCDR1, 2) and at the same time EOCF (ADCDR2 bit 5) is set to 1, the AD conversion finished interrupt (INTADC) is generated.

In repeat mode, each time one AD conversion is completed, the next AD conversion is started. To stop AD conversion, set AMD (ADCCR1 bits 5, 6) to "00" (disable mode) by writing 0s. The AD convert operation is stopped immediately. The converted value at this time is not stored in the AD converted value register.

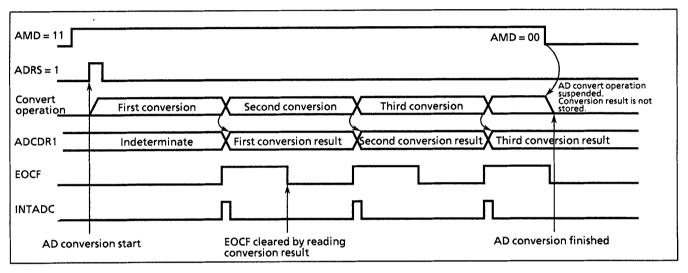


Figure 2-62. Operation in Repeat Mode

# 2.10.5 STOP and SLOW modes during AD conversion

When standby mode (STOP or SLOW mode) is entered forcibly during AD conversion, the AD convert operation is suspended and the AD converter is initialized (ADCCR1 and ADCCR2 are initialized to initial value). Also, the conversion result is indeterminate. (Conversion results up to the previous operation are cleared, so be sure to read the conversion results before entering standby mode.) When restored from standby mode, AD conversion is not automatically restarted, so it is necessary to restart AD conversion. Note that since the analog reference voltage is automatically disconnected, there is no possibility of current flowing into the analog reference voltage.

# 2.10.6 Analog Input Voltage and AD Conversion Result

Example: After selecting the conversion time of 19.5  $\mu s$  at 16 MHz and the analog input channel AIN3 pin, perform AD conversion once. After checking EOCF, read the converted value, store the lower 2 bits in address 009EH and store the upper 8 bits in address 009FH on RAM. The operation mode is software start mode.

```
: AIN SELECT
                (P6DR), 00000000B
                                      : P6DR bit 3 = 0
          LD
                                     ; P6CR bit 3 = 0
                (P6CR), 00000000B
          LD
                (ADCCR1), 00100011B ; Select AIN3
          LD
                (ADCCR2), 11011000B; Select conversion time (312/fc) and operation mode
          LD
          : AD CONVERT START
                                      ; ADRS = 1
          SET
                (ADCCR1), 7
                                      ; EOCF = 1?
SLOOP:
          TEST (ADCDR2).5
          JRS
                T, SLOOP
          ; RESULT DATA READ
          LD
                A, (ADCDR2)
          LD
                (9EH), A
                A, (ADCDR1)
          LD
          LD
                (9FH), A
```

The analog input voltage is corresponded to the 10-bit digital value converted by the AD as shown in Figure 2-63.

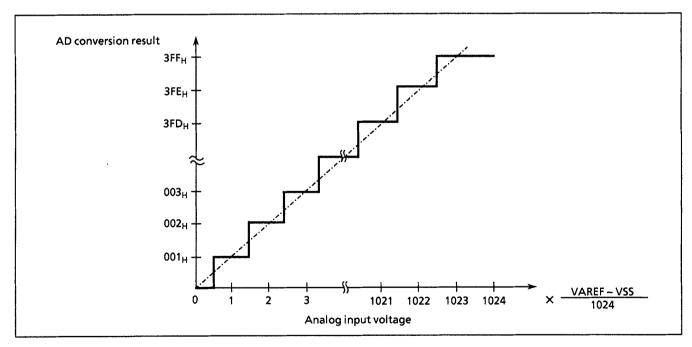


Figure 2-63. Analog Input Voltage and AD Conversion Result (typ.)

### 2.10.7 Precautions about AD converter

# (1) Analog input pin voltage range

Make sure the analog input pins (AIN0 to AIN7) are used at voltages within VSS below VAREF. If any voltage outside this range is applied to one of the analog input pins, the converted value on that pin becomes uncertain. The other analog input pins also are affected by that.

# (2) Analog input shared pins

The analog input pins (AIN0 to AIN7) are shared with input/output ports. When using any of the analog inputs to execute AD conversion, do not execute input/output instructions for all other ports. This is necessary to prevent the accuracy of AD conversion from degrading. Not only these analog input shared pins, some other pins may also be affected by noise arising from input/output to and from adjacent pins.

# (3) Noise countermeasure

The internal equivalent circuit of the analog input pins is shown in Figure 2-64. The higher the output impedance of the analog input source, more easily they are susceptible to noise. Therefore, make sure the output impedance of the signal source in your design is  $5~\mathrm{k}\Omega$  or less. Toshiba also recommends attaching a capacitor external to the chip.

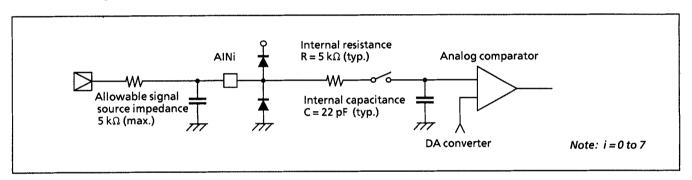


Figure 2-64. Analog Input Equivalent Circuit and Example of Input Pin Processing

# 2.11 Key-On Wake-Up (KWU)

In the TMP86C829A/H29A/M29A, the STOP mode must be released by not only P20 ( $\overline{\text{INT5}}$  /  $\overline{\text{STOP}}$ ) pin but also P64 to P67 pins.

When the STOP mode is released by P64 to P67 pins, the P20 ( $\overline{\text{INT5}}$  /  $\overline{\text{STOP}}$ ) pin needs to be used.

# 2.11.1 Configuration

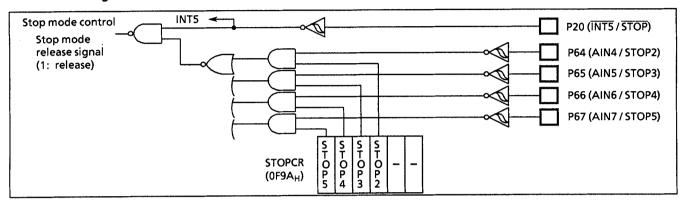


Figure 2-65. Stop Mode Control Circuit

Note: STOP pin doesn't have the control register such as STOPCR, so when STOP mode is relesed by STOPx (x; 2 to 5), STOP pin should be used as STOP function.

## 2.11.2 Control

P64 to P67 (STOP2 to STOP5) pin can controlled by Key-On Wake-Up control register (STOPCR). It can be configured as enable/disable in one-bit unit. When those pins are used by STOP mode release, those pins must be set input mode (P6CR, P6DR, ADCCR1).

STOP mode can be entered by setting up the System Control Register1 (SYSCR1), and can be exited by detecting the falling edge on STOP2 to 5 pins, which are enabled by STOPCR, for releasing STOP mode (Note 1). Also, because each level of the STOP2 to 5 can be confirmed by reading P6DR, check all STOP2 to 5 pins that is enabled by STOPCR before the STOP mode is started (Note 2).

- Note 1: When the STOP mode release by edge mode (SYSCR1<RELM> = "0"), prohibit input from STOP2 to STOP5 or must be set "1" level into STOP2 to STOP5 pins.
- Note 2: When the STOP pin input is high or STOP2 to STOP5 pin input which is enabled by STOPCR is low, executing an instruction which starts STOP mode will not place in STOP mode but instead will immediately start the release sequence (warm-up).

STOPCR	7	6	5	4	3		2	1	0			
(0F9A <sub>H</sub> )	STOP5	STOP4	STOP3	STOP2				-	_	(Initial value: 0000 ****)		
	STOP	2 Sto	p mode	released	by P	64 po	rt		): Disable I: Enable			
	STOP	3 Sto	p mode	released	by P	65 po	rt		): Disable I: Enable		w	rite
	STOP	4 Sto	p mode	released	by P	66 po	rt		): Disable I: Enable		٥	only
	STOP	5 Sto	op mode	released	by P	67 po	rt		D: Disable			

Figure 2-66. Key-On Wake-Up control register

## 2.12 LCD Driver

The TMP86C829A/H29A/M29A each have a driver and control circuit to directly drive the liquid crystal device (LCD). The pins to be connected to LCD are as follows:

Segment output port
 Segment output or P1, P5, P7 input/output port
 Common output port
 4 pins (SEG31 to SEG8)
 4 pins (COM3 to COM0)

In addition, C0, C1, V1, V2, V3 pin are provided for the LCD driver's booster circuit.

The devices that can be directly driven is selectable from LCD of the following drive methods:

① 1/4 Duty (1/3 Bias) LCD	Max 128 Segments (8-segment $\times$ 16 digits)
② 1/3 Duty (1/3 Bias) LCD	Max 96 Segments (8-segment × 12 digits)
③ 1/2 Duty (1/2 Bias) LCD	Max 64 Segments (8-segment × 8 digits)
4 Static LCD	Max 32 Segments (8-segment × 4 digits)

# 2.12.1 Configuration

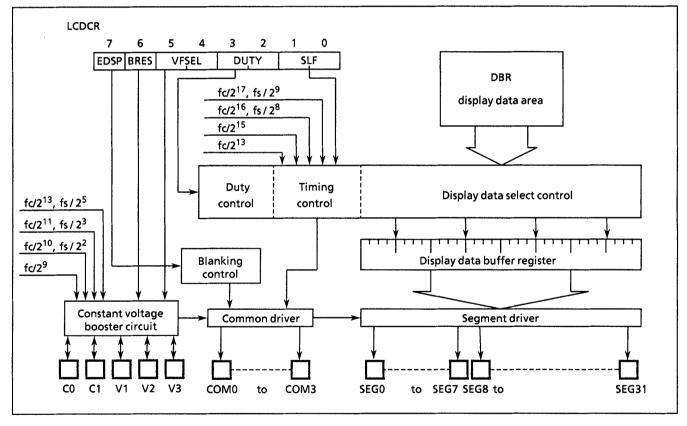


Figure 2-67. LCD Driver

## 2.12.2 Control

The LCD driver is controlled using the LCD control register (LCDCR). The LCD driver's display is enabled using the EDSP.

LCDCR (0028 <sub>H</sub> )	7 6 EDSP BRE	5 4 3 2 S VFŞEL DUTY	1 0 SLF (Initial value: 0000 0000)		
(0026µ)	SLF	Selection of LCD frame frequency	00: fc/2 <sup>17</sup> or fs/2 <sup>9</sup> [Hz] 01: fc/2 <sup>16</sup> or fs/2 <sup>8</sup> 10: fc/2 <sup>15</sup> 11: fc/2 <sup>13</sup>		
	DUTY	Selection of driving methods	00: 1/4 Duty (1/3 Bias) 01: 1/3 Duty (1/3 Bias) 10: 1/2 Duty (1/2 Bias) 11: Static	R/W	
	VFSEL Selection of boost frequency		00: fc/2 <sup>13</sup> or fs/2 <sup>5</sup> [Hz] 01: fc/2 <sup>11</sup> or fs/2 <sup>3</sup> 10: fc/2 <sup>10</sup> or fs/2 <sup>2</sup> 11: fc/2 <sup>9</sup>		
	BRES	Booster circuit control	Disable (use divider resistance)     Enable		
	EDSP	LCD Display Control	Blanking     Enables LCD display (Blanking is released)		
	Whe If th	en < BRES > is set to "1", 5.5 [V]	trol) is set to "0", $V_{DD} \ge V_3 \ge V_2 \ge V_1 \ge V_{SS}$ should be satisfied. $I \ge V_3 \ge V_{DD}$ should be satisfied. . it not only affects the quality of LCD display but also may damage port.		

Figure 2-68. LCD Driver Control Register

# (1) LCD driving methods

As for LCD driving method, 4 types can be selected by DUTY (bit 3 to bit 2 of LCDCR). The driving method is initialized in the initial program according to the LCD used.

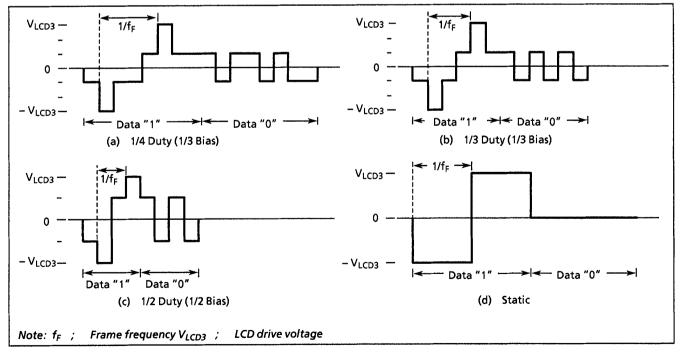


Figure 2-69. LCD Drive Waveform (COM - SEG pins)

# (2) Frame frequency

Frame frequency  $(f_F)$  is set according to driving method and base frequency as shown in the following Table 2-18. The base frequency is selected by SLF (bit 1 and 0 of LCDCR) according to the frequency fc and fs of the basic clock to be used.

Table 2-18. Setting of LCD Frame Frequency

# (a) At the single clock mode. At the dual clock mode (DV7CK = 0).

61.5	Page from the page [1] = 1		Frame freq	uency [Hz]	
SLF	Base frequency [Hz]	1/4 Duty	1/3 Duty	1/2 Duty	Static
	fc	<u>fc</u> 2 <sup>17</sup>	$\frac{4}{3} \cdot \frac{fc}{2^{17}}$	4 · fc 2 <sup>17</sup>	fc
00	(fc = 16 MHz)	122	163	244	122
İ	(fc = 8 MHz)	61	81	122	61
	<u>fc</u>	<u>fc</u> 2 <sup>16</sup>	4 • fc 2 <sup>16</sup>	4 • fc 2 2 <sup>16</sup>	<u>fc</u> 2 <sup>16</sup>
01	(fc = 8 MHz)	122	163	244	122
	(fc = 4 MHz)	61	81	122	61
	<u>fc</u>	<u>fc</u> 2 <sup>15</sup>	$\frac{4}{3} \cdot \frac{fc}{2^{15}}$	4 · fc 215	fc 2 <sup>15</sup>
10	(fc = 4 MHz)	122	163	244	122
	(fc = 2 MHz)	61	81	122	61
11	fc	<u>fc</u> 2 <sup>13</sup>	4 • fc 2 <sup>13</sup>	4 • fc 2 • 2 <sup>13</sup>	<u>fc</u>
1	(fc = 1 MHz)	122	163	244	122

Note: fc; High-frequency clock [Hz]

# (b) At the dual clock mode (DV7CK = 1 or SYSCK = 1)

615	B f (1/-1	Frame frequency [Hz]						
SLF	Base frequency [Hz]	1/4 Duty	1/3 Duty	1/2 Duty	Static			
00	- fs 29	<u>fs</u> 2 <sup>9</sup>	4 · fs 29	4 • fs_ 2 • 2 <sup>9</sup>	<u>fs</u> 2 <sup>9</sup>			
	(fs = 32.768 kHz)	64	85	128	64			
01	<u>fs</u>	<u>fs</u> 2 <sup>8</sup>	4 • fs 28	4 • fs 28	<u>fs</u> 2 <sup>8</sup>			
	(fs = 32.768 kHz)	128	171	256	128			

Note: fs; Low-frequency clock [Hz]

# (3) Booster circuit for LCD driver

The LCD voltage booster pin can select the booster circuit or the divider resistance.

The booster circuit control is selected by BRES (bit 6 in LCDCR).

The booster circuit boosts the output voltage for the segment / common signal by double (V2) and triple (V3) in relation to the on-chip output voltage (1 V typ.).

When used as the divider resistance, the V1, V2 and V3 pins are input by divider voltage of external supply.

When used as the booster circuit, the VLCD setting should be composed to 1/3 bias.

The selection of boost frequency is selected by SLFR (bit 1 to 0 in LCDCR).

Selecting the fast frequency using the SLFR in the command register (LCDCR) raises the drive capability of segment/common.

Table 2-19 shows the V3 pin current capacity and Boosting Frequency.

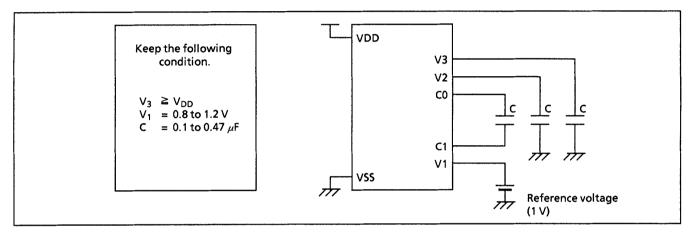


Figure 2-70. Example of a Booster Circuit (LCDCR < BRES > = "1")

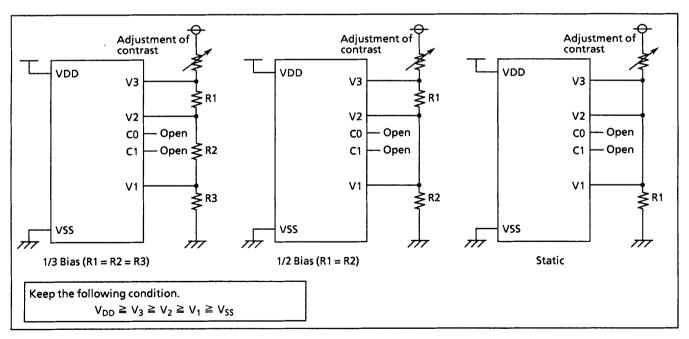


Figure 2-71. Example of Divider Registance (LCDCR<BRES> = "0")

Table 2-19. V3 Pin Current Capacity and Boosting Frequency (typ.)

VFSEL	Boosting frequency	fc = 16 MHz	fc = 8 MHz	fc = 4 MHz	fs = 32.768 kHz
00	fc/2 <sup>13</sup> or fs/2 <sup>5</sup>	– 37 mV/μA	– 80 mV/ <i>µ</i> A	– 138 mV/μA	– 76 mV/μA
01	fc/2 <sup>11</sup> or fs/2 <sup>3</sup>	– 19 mV/μA	– 24 mV/μA	– 37 mV/μA	– 23 mV/μA
10	fc/2 <sup>10</sup> or fs/2 <sup>2</sup>	– 17 mV/μA	– 19 mV/μA	– 24 mV/μA	– 18 mV/μA
11	fc/2 <sup>9</sup>	– 16 mV/μA	– 17 mV/μA	– 19 mV/μA	_

Note 1: The current capacity is the amount of voltage that falls per 1  $\mu$ A

Note 2: The boosting frequency should be selected depending on your LCD panel.

Note 3: For the reference pin V1, a current capacity ten times larger than the above is recommended to ensure stable operation.

For example, when the boosting frequency is  $fc/2^9$  (at fc=8 MHz), -1.7 mV/ $\mu$ A or more is recommended for the current capacity of the reference pin V1.

#### 2.12.3 LCD display operation

#### Display data setting (1)

Display data is stored to the display data area (assigned to address 0F80 to 0F8FH) in the DBR. The display data which are stored in the display data area is automatically read out and sent to the LCD driver by the hardware. The LCD driver generates the segment signal and common signal according to the display data and driving method. Therefore, display patterns can be changed by only over writing the contents of display data area by the program. Figure 2-72 shows the correspondence between the display data area and SEG/COM pins.

LCD light when display data is "1" and turn off when "0". According to the driving method of LCD, the number of pixels which can be driven becomes different, and the number of bits in the display data area which is used to store display data also becomes different.

Therefore, the bits which are not used to store display data as well as the data buffer which corresponds to the addresses not connected to LCD can be used to store general user process data (see Table 2-20).

Note: The display data memory contents become unstable when the power supply is turned on; therefore, the display data memory should be initialized by an initiation routine.

Table 2-20. Driving Method and Bit for Display Data

							· · · · · · · · · · · · · · · · · · ·
address 0F80 <sub>H</sub>	bit 7 bit 6 bit 5 bit 4	bit 3 bit 2 bit 1 bit 0	Driving methods	bit 7/3	bit 6/2	bit 5/1	bit 4/0
81	SEG3	SEG2	1 / 4 Duty	сомз	COM2	сом1	сомо
82 83	SEG5 SEG7	SEG4 SEG6	1/3 Duty	-	COM2	COM1	сомо
84	SEG9	SEG8	1/2 Duty	_	<del>-</del>	COM1	сомо
85 86	SEG11 SEG13	SEG10 SEG12	Static	_	<del></del>	_	COM0
87	SEG15	SEG14			:	: -	
88 89	SEG17 SEG19	SEG16 SEG18	Note: - ;	; This bit i	is not used f	for display o	data
0.5	SEG21	SEG20					

address	bit 7	bit 6	bit 5	bit 4	bit 3	bit 2	bit 1	bit 0
0F80 <sub>H</sub>		' SE	Ġ1	'		SE	Ġ0	'
81		SE	G3			SE	G2	
82		SE	G5		,	SE	G4	
83		SE	G7			SE	G6	
84		SE	G9			SE	G8	
85		SE	G11			SE	G10	
86		SE	G13			SE	G12	
87		SE	G15		l	SE	G14	
88		SE	G17			SE	G16	
89		SE	G19			SE	G18	
8A		SE	G21			SE	G20	
8B		SE	G23			SE	G22	
8C		SE	G25			SE	G24	
8D		SE	G27			SE	G26	
8E		SE	G29			SE	G28	
8F		SE	G31			SE	G30	ı
	сомз	COM2	COM1	COM0	сомз	COM2	COM1	COM0

Figure 2-72. LCD Display Data Area (DBR)

### Blanking (2)

Blanking is enabled when EDSP is cleared to "0".

Blanking turns off LCD through outputting a GND level to SEG/COM pin.

When in STOP mode, EDSP is cleared to "0" and automatically blanked. To redisplay ICD after exiting STOP mode, it is necessary to set EDSP back to "1".

Note: During reset, the LCD segment outputs (SEG0 to SEG7) and LCD common outputs are fixed "0" level. But the multiplex terminal (P1, P5 and P7 ports) of input / output port and LCD segment output becomes high impedance. Therefore, when the reset input is long remarkably, ghost problem may appear in LCD display.

### **Control method of LCD driver** 2.12.4

#### (1) Initial setting

Figure 2-73 shows the flowchart of initialization.

Example: To operate a 1/4 duty LCD of 32 segments × 4 com-mons at

frame frequency fc/216 [Hz]

LD (LCDCR), 00000001B; Sets LCD driving method

and frame frequency. Boost frequency

LD (P1LCR), 0FFH ; Sets P1 port as segment output.

: Sets the initial value of

display data.

(LCDCR), 10000001B; Display enable

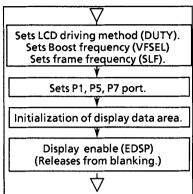


Figure 2-73. Initial Setting of LCD Driver

### Store of display data (2)

Generally, display data are prepared as fixed data in program memory and stored in display data area by load command.

Example 1: To display using 1/4 duty LCD a numerical value which corresponds to the LCD data stored in data memory at address 80H (when pins COM and SEG are connected to LCD as in Figure 2-74), display data become as shown in Table 2-19.

> LDA, (80H)

ADD A, TABLE -\$-7

HL,0F80H LD

LDW, (PC + A)

LD (HL), W

RET

TABLE: DB 11011111B, 00000110B,

11100011B, 10100111B. 00110110B, 10110101B,

11110101B, 00010111B,

11110111B, 10110111B

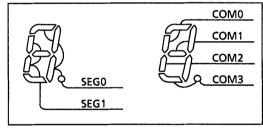


Figure 2-74. Example of COM, SEG Pin Connection (1/4 Duty)

SNEXT:

Note: DB is a byte data difinition instruction.

No.	display	display data	No.	display	display data
0		11011111	5		10110101
1		00000110	6		11110101
2		11100011	7		00000111
3		10100111	8		11110111
4		00110110	9		10110111

Table 2-21. Example of Display Data (1/4 Duty)

Example 2: Table 2-21 shows an example of display data which are displayed using 1/2 duty LCD in the same way as Table 2-22. The connection between pins COM and SEG are the same as shown in Figure 2-75.

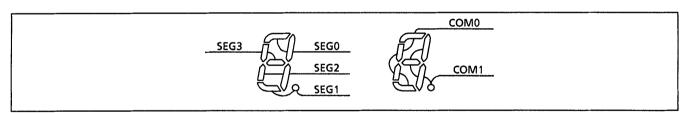


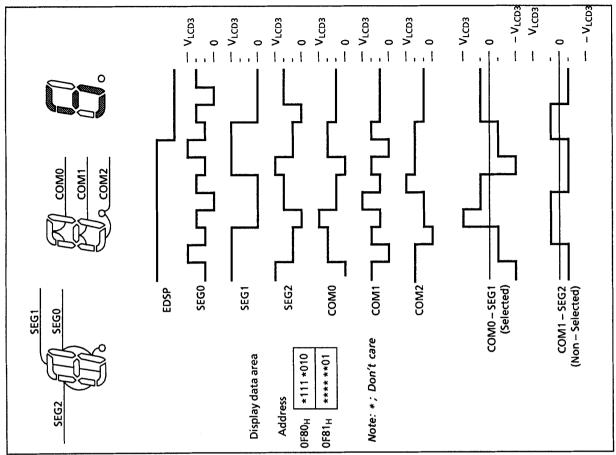
Figure 2-75. Example of COM, SEG Pin Connection

Table 2-22. Example of Display Data (1/2 Duty)

	Displa	Display data		Display data		
Number	High order address	Low order address	Number	High order address	Low order address	
0	**01**11	**01**11	5	**11**10	**01**01	
1	**00**10	**00**10	6	**11**11	**01**01	
2	**10**01	**01**11	7	**01**10	**00**11	
3	**10**10	**01**11	8	**11**11	**01**11	
4	**11**10	**00**10	9	**11**10	**01**11	

Note: \*; Don't care

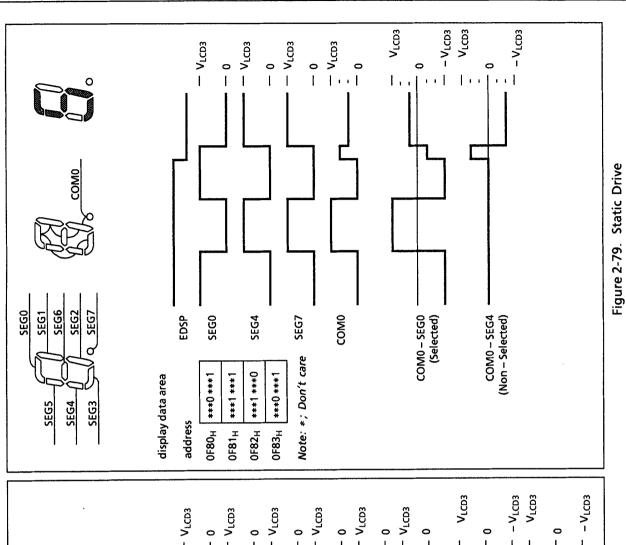
# (3) Example of LCD drive output



VLCD3 — V<sub>LCD3</sub> COMO COM3 COM2 COMO - SEGO -SEG0 COMO COM2 COM3 COM2 – SEG1 (Non – Selected) COM1 SEG1 (Selected) Display data area 1011 0101 Address 0F80<sub>H</sub>

Figure 2-76. 1/4 Duty (1/3 Bias) Drive

Figure 2-77. 1/3 Duty (1/3 Bias) Drive



— V<sub>LCD3</sub> — V<sub>LCD3</sub> \_ VLCD3 — V<sub>LCD3</sub> 0 0 COMO COM0 – SEG2 (Non – Selected) COMO COM1 EDSP SEG0 SEG3 COM0 - SEG1 SEG2 (Selected) SEG1 Note: \*; Don't care 0F81<sub>H</sub> | \*\*11 \*\*10 \*\*01 \*\*01 display data area SEG3 0F80<sub>H</sub>

Figure 2-78. 1/2 Duty (1/3 Bias) Drive

# Input / Output Circuitry

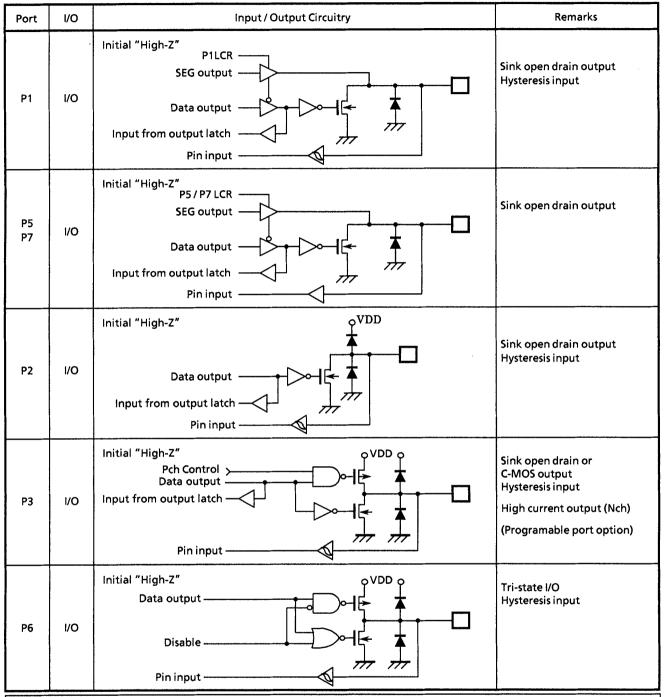
# (1) Control Pins

The input/output circuitries of the TMP86C829A/H29A/M29A control pins are shown below.

Control Pin	1/0	Input / Output Circuitry	Remarks
XIN XOUT	Input Output	Osc. enable fc  VDD OVDD  Rf  RO  XIN  XOUT	Resonator connecting pins (high-frequency) $R_f=1.2\ M\Omega\ (typ.)$ $R_O=1.0\ k\Omega\ (typ.)$
		Normal1 mode Normal2 mode	
XTIN XTOUT	Input Output	Refer to port P2  Osc. enable  VDD o R  Rf RO  XTEN  VDD O R  XTEN  XTOUT	Fig. Resonator connecting pins (Low-frequency)  R <sub>f</sub> = 6 MΩ (typ.)  R <sub>O</sub> = 220 kΩ (typ.)
RESET	I/O	Address-trap-reset Watchdog-timer System-clock-reset	Sink open drain output  Hysteresis input  Pull-up resistor  R <sub>IN</sub> = 220 kΩ (typ.)
STOP/INT5	Input	P20 STOP/INT5	Hysteresis input
TEST	Input	R <sub>IN</sub> &	Pull-down resistor $R_{IN} = 70 \text{ k}\Omega \text{ (typ.)}$

Note: The TEST pin of the TMP86PM29A does not have a pull-down resistor. Fix the TEST pin at low-level.

# (2) Input / Output Ports



Note: Port P1, P5 and P7 are sink open drain output. But they are also used as a segment output of LCD. Therefore, absolute maximum ratings of port input voltage should be used in -0.3 to  $V_{DD} + 0.3$  volts

# **Electrical Characteristics**

Absolute Maximum Ratings  $(V_{SS} = 0 V)$ 

Parameter	Symbol	Pins	Rating	Unit
Supply Voltage	$V_{DD}$		- 0.3 to 6.5	
Input Voltage	V <sub>IN</sub>		- 0.3 to V <sub>DD</sub> + 0.3	V
Output Voltage	V <sub>OUT1</sub>		- 0.3 to V <sub>DD</sub> + 0.3	1
	l <sub>OUT1</sub>	P3, P6 Port	- 1.8	
Output Current (Per 1 pin)	I <sub>OUT2</sub>	P1, P2, P5, P6, P7 Port	3.2	1
	Гоитз	P3 Port	30	mA
C 1 1 C 1 1 T 1 D	Σl <sub>OUT1</sub>	P1, P2, P5, P6, P7 Port	60	1
Output Current (Total)	ΣI <sub>OUT2</sub>	P3 Port	80	
Power Dissipation [Topr = 85℃]	PD		350	mW
Soldering Temperature (time)	Tsld		260 (10 s)	
Storage Temperature	Tstg		- 55 to 125	ე •c
Operating Temperature	Topr		- 40 to 85	

Note: The absolute maximum ratings are rated values which must not be exceeded during operation, even for an instant.

Any one of the ratings must not be exceeded. If any absolute maximum rating is exceeded, a device may break down or its performance may be degraded, causing it to catch fire or explode resulting in injury to the user. Thus, when designing products which include this device, ensure that no absolute maximum rating value will ever be exceeded.

Recommended Operating Condition

 $(V_{SS} = 0 \text{ V, Topr} = -40 \text{ to } 85^{\circ}\text{C})$ 

Parameter	Symbol	Pins	С	ondition	Min	Max	Unit	
				NORMAL1, 2 mode	4.5			
			fc = 16 MHz	IDLE0, 1, 2 mode	4.5			
				NORMAL1, 2 mode	2.7	5.5		
			fc = 8 MHz	IDLE0, 1, 2 mode	2.7			
Supply Voltage	V <sub>DD</sub>			NORMAL1, 2 mode			V	
			fc = 4.2 MHz	IDLE0, 1, 2 mode	1.8			
			fs =	SLOW1, 2 mode				
			32.768 kHz	SLEEP0, 1, 2 mode				
				STOP mode				
	V <sub>IH1</sub>	Except Hysteresis input	V <sub>DD</sub> ≧ 4.5 V		$V_{DD} \times 0.70$			
Input high Level	V <sub>IH2</sub>	Hysteresis input			$V_{DD} \times 0.75$	V <sub>DD</sub>	V	
	V <sub>IH3</sub>		V	V <sub>DD</sub> < 4.5 V				
	V <sub>IL1</sub>	Except Hysteresis input	.,	> 4 5 1/		$V_{DD} \times 0.30$		
Input low Level	V <sub>IL2</sub>	Hysteresis input	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	<sub>DD</sub> ≥ 4.5 V	0	V <sub>DD</sub> × 0.25	] v	
	V <sub>IL3</sub>		V	<sub>DD</sub> < 4.5 V		$V_{DD} \times 0.10$		
			V <sub>DD</sub> :	= 1.8 to 5.5 V		4.2		
Clask Francisco	fc	XIN, XOUT	V <sub>DD</sub> :	$V_{DD} = 2.7 \text{ to } 5.5 \text{ V}$		8.0	MHz	
Clock Frequency			$V_{DD} = 4.5 \text{ to } 5.5 \text{ V}$			16.0	]	
	fs	XTIN, XTOUT			30.0	34.0	kHz	

Note: The recommended operating conditions for a device are operating conditions under which it can be guaranteed that the device will operate as specified. If the device is used under operating conditions other than the recommended operating conditions (supply voltage, operating temperature range, specified AC/DC values etc.), malfunction may occur. Thus, when designing products which include this device, ensure that the recommended operating conditions for the device are always adhered to.

DC Characteristics

 $(V_{SS} = 0 \text{ V, Topr} = -40 \text{ to } 85^{\circ}\text{C})$ 

Parameter	Symbol	Pins	Condition	Min	Тур.	Max	Unit
Hysteresis Voltage	V <sub>HS</sub>	Hysteresis input			0.9	-	V
	l <sub>IN1</sub>	TEST					
Input Current	I <sub>IN2</sub>	Sink Open Drain, Tri-state	$V_{DD} = 5.5 \text{ V}, V_{IN} = 5.5 \text{ V} / 0 \text{ V}$	-	-	± 2	μΑ
	I <sub>IN3</sub>	RESET, STOP					
Lanut Desistance	R <sub>IN1</sub>	TEST Pull-Down		_	70	_	kΩ
Input Resistance	R <sub>IN2</sub>	RESET Pull-Up		100	220	450	K77
Output Leakage Current	ILO	Sink Open Drain, Tri-state	$V_{DD} = 5.5 \text{ V}, V_{OUT} = 5.5 \text{ V} / 0 \text{ V}$	-	-	± 2	μΑ
Output High Voltage	V <sub>OH2</sub>	C-MOS, Tri-st Port	$V_{DD} = 4.5 \text{ V}, I_{OH} = -0.7 \text{ mA}$	4.1	-	_	V
Output Low Voltage	V <sub>OL</sub>	Except XOUT and P3 Port	$V_{DD} = 4.5 \text{ V}, I_{OL} = 1.6 \text{mA}$	-	_	0.4	\ \
Output Low Current	loL	High Current Port (P3 Port)	$V_{DD} = 4.5 \text{ V}, V_{OL} = 1.0 \text{ V}$	-	20	-	mA
Supply Current in NORMAL 1, 2 mode			V <sub>DD</sub> = 5.5 V V <sub>IN</sub> = 5.3 / 0.2 V	_	7.5	9	
Supply Current in IDLE 0, 1, 2 mode			fc = 16 MHz fs = 32.768 kHz	_	5.5	6.5	mA
Supply Current in SLOW 1 mode	I <sub>DD</sub>			-	18	42	
Supply Current in SLEEP 1 mode			$V_{DD} = 3.0 \text{ V}$ $V_{IN} = 2.8 \text{ V} / 0.2 \text{ V}$ $f_{S} = 32.768 \text{ kHz}$	_	16	25	
Supply Current in SLEEP 0 mode			LCD driver is not enable.	_	12	20	μA
Supply Current in STOP mode			V <sub>DD</sub> = 5.5 V V <sub>IN</sub> = 5.3 V / 0.2 V	-	0.5	10	

Note 1: Typical values show those at Topr =  $25^{\circ}$ C,  $V_{DD} = 5 \text{ V}$ 

Note 2: Input current (I<sub>IN1</sub>, I<sub>IN2</sub>); The current through pull-up or pull-down resistor is not included.

Note 3: IDD does not include IREF current.

Note 4: The supply currents of SLOW 2 and SLEEP 2 modes are equivalent to IDLE 0, 1, 2.

# **AD Conversion Characteristics**

# $(V_{SS} = 0.0 \text{ V}, 4.5 \text{ V} \le V_{DD} \le 5.5 \text{ V}, \text{Topr} = -40 \text{ to } 85^{\circ}\text{C})$

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Analog Reference Voltage	VAREF		A <sub>VDD</sub> - 1.0		A <sub>VDD</sub>	V
Power Supply Voltage of Analog Control Circuit	A <sub>VDD</sub>			V <sub>DD</sub>		V
Analog Reference Voltage Range (Note 4)	$\triangle V_{AREF}$		3.5		T -	V
Analog Input Voltage	V <sub>AIN</sub>		V <sub>SS</sub>	_	VAREF	٧
Power Supply Current of Analog Reference Voltage	I <sub>REF</sub>	$V_{DD} = A_{VDD} = V_{AREF} = 5.5 \text{ V}$ $V_{SS} = 0.0 \text{ V}$	_	0.6	1.0	mA
Non linearity Error			_	_	±2	
Zero Point Error		$\nabla_{DD} = A_{VDD} = 5.0 \text{ V},$	_	***	± 2	1
Full Scale Error		$V_{SS} = 0.0 \text{ V}$ $V_{AREF} = 5.0 \text{ V}$	_	_	± 2	LSB
Total Error		Aner	-	_	± 2	1

# $(V_{SS} = 0.0 \text{ V}, 2.7 \text{ V} \le V_{DD} < 4.5 \text{ V}, \text{Topr} = -40 \text{ to } 85^{\circ}\text{C})$

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Analog Reference Voltage	VAREF		A <sub>VDD</sub> - 1.0	-	A <sub>VDD</sub>	V
Power Supply Voltage of Analog Control Circuit	A <sub>VDD</sub>			$V_{DD}$		V
Analog Reference Voltage Range (Note 4)	△V <sub>AREF</sub>		2.5	-		٧
Analog Input Voltage	V <sub>AIN</sub>		Vss	-	VAREF	V
Power Supply Current of Analog Reference Voltage	I <sub>REF</sub>	$I_{REF}$ $V_{DD} = A_{VDD} = V_{AREF} = 4.5 V$ $V_{SS} = 0.0 V$		0.5	0.8	mA
Non linearity Error			_	-	± 2	
Zero Point Error		$V_{DD} = A_{VDD} = 2.7 \text{ V},$	-	-	± 2	LSB
Full Scale Error		$V_{SS} = 0.0 \text{ V}$ $V_{AREF} = 2.7 \text{ V}$	_	_	± 2	1 138
Total Error		Aner	-	_	± 2	1

# (V<sub>SS</sub> = 0.0 V, 2.0 V $\leq$ V<sub>DD</sub> < 2.7 V, Topr = - 40 to 85°C) Note 5 (V<sub>SS</sub> = 0.0 V, 1.8 V $\leq$ V<sub>DD</sub> < 2.0 V, Topr = - 10 to 85°C) Note 5

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Analog Reference Voltage	VAREF		A <sub>VDD</sub> - 0.9	_	A <sub>VDD</sub>	V
Power Supply Voltage of Analog Control Circuit	A <sub>VDD</sub>			$V_{DD}$		V
A . I . Defense Neltone Description (Neto A)		$1.8 \text{ V} \le \text{V}_{DD} < 2.0 \text{ V}$	1.8	_	T -	V
Analog Reference Voltage Range (Note 4)	$\triangle V_{AREF}$	$2.0 \text{ V} \le \text{V}_{DD} < 2.7 \text{ V}$	2.0	_	T -	7 <b>'</b>
Analog Input Voltage	V <sub>AIN</sub>		V <sub>SS</sub>	_	VAREF	V
Power Supply Current of Analog Reference Voltage	IREF	$V_{DD} = A_{VDD} = V_{AREF} = 2.7 \text{ V}$ $V_{SS} = 0.0 \text{ V}$	-	0.3	0.5	mA
Non linearity Error			_	_	±4	
Zero Point Error		$V_{DD} = A_{VDD} = 1.8 \text{ V},$	-	_	± 4	1
Full Scale Error		$V_{SS} = 0.0 \text{ V}$ $V_{AREF} = 1.8 \text{ V}$	_			LSB
Total Error		Ancr	_	-	±4	1

- Note 1: The total error includes all errors except a quantization error, and is defined as a maximum deviation from the ideal conversion line.
- Note 2: Conversion time is different in recommended value by power supply voltage.

  About conversion time, please refer to "2.10.2 Register Framing".

  Note 3: Please use input voltage to AIN input Pin in limit of V<sub>AREF</sub> V<sub>SS</sub>.
- - When voltage of range outside is input, conversion value becomes unsettled and gives affect to other channel conversion value.
- Note 4: Analog Reference Voltage Range:  $\triangle V_{AREF} = V_{AREF} V_{SS}$ Note 5: When AD is used with  $V_{DD} < 2.7 \text{ V}$ , the guaranteed temperature range varies with the operating voltage.

# **AC** Characteristics

# $(V_{SS} = 0 \text{ V}, V_{DD} = 4.5 \text{ to } 5.5 \text{ V}, Topr = -40 \text{ to } 85^{\circ}\text{C})$

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
		NORMAL 1, 2 mode				
Machine Cycle Time	tcy	IDLE 1, 2 mode	0.25	-	4	
		SLOW 1, 2 mode		-	133.3	μS
		SLEEP 1, 2 mode	117.6			
High Level Clock Pulse Width	twcH	For external clock operation (XIN input)		31.25	_	1
Low Level Clock Pulse Width	twcL	fc = 16 MHz	-			ns
High Level Clock Pulse Width	twcH	For external clock operation (XTIN input)		15.26	-	
Low Level Clock Pulse Width	twcL	fs = 32.768 kHz				μS

# $(V_{SS} = 0 \text{ V}, V_{DD} = 2.7 \text{ to } 4.5 \text{ V}, Topr = -40 \text{ to } 85^{\circ}\text{C})$

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
		NORMAL 1, 2 mode				
Machine Cycle Time		IDLE 1, 2 mode	0.5	-	4	
	tcy	SLOW 1, 2 mode		_	133.3	μS
		SLEEP 1, 2 mode	117.6			
High Level Clock Pulse Width	twcH	For external clock operation (XIN input)		62.5	_	T
Low Level Clock Pulse Width	twcL	fc = 8 MHz	-			ns
High Level Clock Pulse Width	twcH	For external clock operation (XTIN input)			_	
Low Level Clock Pulse Width	twcL	fs = 32.768 kHz	-	15.26		μ\$

# $(V_{SS} = 0 \text{ V}, V_{DD} = 1.8 \text{ to } 2.7 \text{ V}, Topr = -40 \text{ to } 85^{\circ}\text{C})$

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
		NORMAL 1, 2 mode				
Machine Cycle Time		IDLE 1, 2 mode	0.95	-	4	
	tcy	SLOW 1, 2 mode		_	133.3	μS
		SLEEP 1, 2 mode	117.6			
High Level Clock Pulse Width	twcH	For external clock operation (XIN input)		119.05	_	
Low Level Clock Pulse Width	twcL	fc = 4.2 MHz	-			ns
High Level Clock Pulse Width	twcH	For external clock operation (XTIN input)		15.26	-	_
Low Level Clock Pulse Width	twcL	fs = 32.768 kHz	-			μ5

# Timer Counter 1 input (ECIN) Characteristics $(V_{SS} = 0 \text{ V}, \text{Topr} = -40 \text{ to } 85^{\circ}\text{C})$

Parameter	Symbol	Condition		Min	Тур.	Max	Unit
		Frequency measurement mode V <sub>DD</sub> = 4.5 to 5.5 V	Single edge count		_	16	
			Both edge count		_		
TC1 input (ECIN input)	4 -	Frequency measurement mode $V_{DD} = 2.7$ to $4.5$ V	Single edge count	_	-		7
TCT input (ECIN input)	t <sub>TC1</sub>		Both edge count	_	_	1 8	MHz
		Frequency measurement mode	Single edge count	_	_	4.2	1
		$V_{DD} = 1.8 \text{ to } 2.7 \text{ V}$	Both edge count	-	_	4.2	

Recommended Oscillating Conditions - 1

$$(V_{SS} = 0 \text{ V}, V_{DD} = 4.5 \text{ to } 5.5 \text{ V}, Topr = -40 \text{ to } 85^{\circ}\text{C})$$

Donomotor	0111-4	Oscillation			Recommended Constant		
Parameter	Oscillator	Frequency	Kecom	mended Oscillator	C <sub>1</sub>	C <sub>2</sub>	
		16 MHz	MURATA	CSA16.00MXZ040	10 pF	10 pF	
High francisco		8 MHz	MURATA	CSA8.00MTZ	30 pF	30 pF	
High-frequency	Ceramic Resonator			CST8.00MTW	30 pF (built-in)	30 pF (built-in)	
Oscillation			MURATA	CSA4.19MG	30 pF	30 pF	
		4.19 MHz		CST4.19MGW	30 pF (built-in)	30 pF (built-in)	
Low-frequency	Crystal Oscillator	32.768 kHz	SII	VT-200	6 = 5	6 5	
Oscillation	Crystal Oscillator	32.766 KHZ	311	V 1-200	6 pF	6 pF	

Recommended Oscillating Conditions - 2

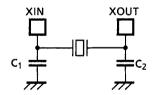
$$(V_{SS} = 0 \text{ V}, V_{DD} = 2.7 \text{ to } 5.5 \text{ V}, \text{ Topr} = -40 \text{ to } 85^{\circ}\text{C})$$

Damana atau	0 111 4	Oscillation			Recommended Constant		
Parameter Oscillator		Frequency Recommended Oscillator		C <sub>1</sub>	C <sub>2</sub>		
		8 MHz	MURATA	CSA8.00MTZ	30 pF	30 pF	
High-frequency	Canania Danasatan			CST8.00MTW	30 pF (built-in)	30 pF (built-in)	
Oscillation	llation   Ceramic Resonator		MURATA	CSA4.19MG	30 pF	30 pF	
		4.19 MHz		CST4.19MGW	30 pF (built-in)	30 pF (built-in)	

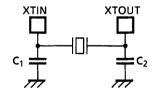
# Recommended Oscillating Conditions - 3

$$(V_{SS} = 0 \text{ V}, V_{DD} = 1.8 \text{ to } 5.5 \text{ V}, Topr = -40 \text{ to } 85^{\circ}\text{C})$$

Davamatas	0	Oscillation			Recommend	led Constant
Parameter Oscillator		Frequency	Recommended Oscillator		C <sub>1</sub>	C <sub>2</sub>
High-frequency	Canania Danasatan	4.40.141-	MURATA	CSA4.19MG	30 pF	30 pF
Oscillation	Ceramic Resonator	4.19 MHz		CST4.19MGW	30 pF (built-in)	30 pF (built-in)



(1) High-frequency Oscillation



(2) Low-frequency Oscillation

- Note 1: An electrical shield by metal shield plate on the surface of IC package is recommended in order to protect the device from the high electric field stress applied from CRT (Cathodic Ray Tube) for continuous reliable operation.
- Note 2: The product numbers and specifications of the resonators by Murata Manufacturing Co., Ltd. are subject to change.

  For up-to-date information, please refer to the following

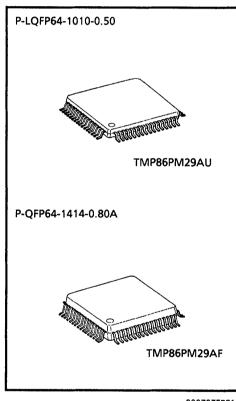
  URL; http://www.murata.co.jp/search/index.html

## **CMOS 8-Bit Microcontroller**

# TMP86PM29AU/AF

The TMP86PM29A is a OTP type MCU which includes 32 Kbyte One-time PROM. It is a pin compatible with a mask ROM product of the TMP86C829A/H29A/M29A. Writing the program to built-in PROM, the TMP86PM29A operates as the same way as the TMP86C829A/H29A/M29A. Also, this product has upper compatibility for TMP86CH21 and TMP86C420/820 and can be used as an one-time PROM for these products. Please refer to detail "Functional differences of product basis". Using the Adapter socket, you can write and verify the data for the TMP86PM29A with a general-purpose PROM programmer same as TC571000D/AD.

Part No.	ОТР	RAM	Package	Adapter Socket
TMP86PM29AU	32 K × 8-bit	1 5 K O hia	P-LQFP64-1010-0.50	BM11162
TMP86PM29AF	32 K X 8-DIT	1.5 K × 8 bit	P-QFP64-1414-0.80A	BM11163



000707EBP1

- For a discussion of how the reliability of microcontrollers can be predicted, please refer to Section 1.3 of the chapter entitled Quality and Reliability Assurance
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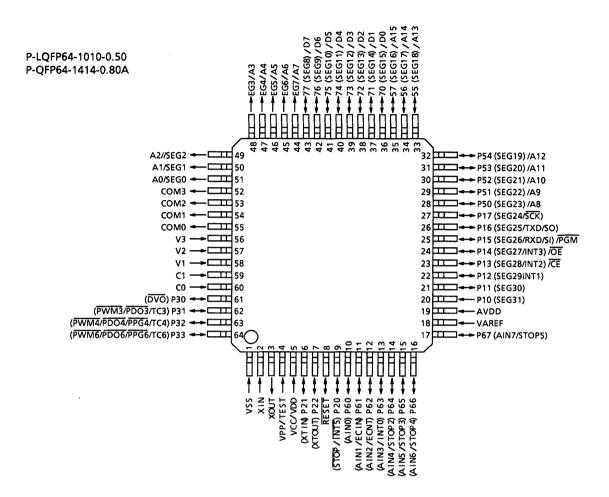
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# Functional differences on product basis

	TMP86C829A/H29A/M29A	TMP86CH21	TMP86C420/820					
Input/Output ports		39 pins						
Package		P-LQFP64-1010-0.50 P-QFP64-1414-0.80A						
Instruction execution time		0.25 μs (at 16 MHz) 122 μs (at 32.768 kHz)	71.					
Operating voltage	2.7	to 5.5 V at 4.2 MHz / 32.768 kl to 5.5 V at 8 MHz / 32.768 kH to 5.5 V at 16 MHz / 32.768 kH	Z					
18-bit timer counter	1 cl (ECIN input is both ec	1 ch (ECIN is single edge)						
8-bit timer counter	4 c	1	2 ch					
Time Base Timer		1 ch						
Watchdog Timer		1 ch						
AD converter	10 bit × 8 ch	8 bit >	< 8 ch					
UART	1 cł	1	-					
SIO	(Not	(Note) 1 ch						
LCD driver		32 seg × 4 com						
Operating Temperature		– 40 to 85°C						

Note: UART and SIO can not use function synchronously because each function pin is shared.

# Pin Assignments (Top View)



## **Pin Function**

The TMP86PM29A has MCU mode and PROM mode.

# (1) MCU mode

In the MCU mode, the TMP86PM29A is a pin compatible with the TMP86C420/820, TMP86CH21 and TMP86C829A/H29A/M29A (Make sure to fix the TEST pin to low level). However, TMP86C420/820 have not timer/counter 6 input/ouput and UART input/output.

# (2) PROM mode

Pin Name	Input/Output	Functions	Pin Name (MCU mode)
A15 to A8	Input	Input of Memory address for program	P57 to P50
A7 to A0		I mpara i mana i y ada i cos tor program	SEG7 to SEG0
D7 to D0	1/0	Input/Output of Memory data for program	P77 to P70
Œ		Chip enable	P13
ŌĒ	Input	Output enable	P14
PGM		Program control	P15
VPP		+ 12.75 V / 5 V (Power supply of program)	TEST
VCC, AVDD	Power supply	+6.25 V / 5 V	VDD, AVDD
GND, VAREF	ļ	ov	VSS, VAREF
P11, P21		PROM mode setting pin. Fix to high.	
P10, P22, P20, P61	1/0		
RESET		PROM mode setting pin. Fix to low.	
P64, P65, P67	Output	Output pin for PROM operation test. Open or release.	
P17, P16, P12			
P66, P63 to P62, P60	i		
P33 to P30	1 40	0.000	
COM3 to COM0	1/0	Open	
V3 to V1	Ī		
C1, C0			
XIN	Input	Solf oscillation with reconstant (9 MALL)	
XOUT	Output	Self oscillation with resonator (8 MHz).	

Note: No pin is applied to A16 input.

# **Operation**

This section describes the functions and basic operational blocks of TMP86PM29A.

The TMP86PM29A has PROM in place of the mask ROM which is included in the TMP86C420/820, TMP86CH21 and TMP86C829A/H29A/M29A. The configuration and function are the same as the mask ROM products. For TMP86C420/820 and TMP86CH21, however, some functions have been partially changed or deleted.

In addition, TMP86PM29A operates as the single clock mode when releasing reset.

When using the dual clock mode, oscillate a low-frequency clock by SET. XTEN command at the beginning of program.

# 1. Operating Mode

The TMP86PM29A has MCU mode and PROM mode.

### 1.1 MCU Mode

The MCU mode is set by fixing the TEST/VPP pin to the low level. (TEST/VPP pin cannot be used open because it has no built-in pull-down resister).

# 1.1.1 Program memory

The TMP86PM29A has a 32 Kbyte built-in one time PROM (addresses 8000 to FFFF<sub>H</sub> in the MCU mode, addresses 0000 to  $7FFF_H$  in the PROM mode).

When using TMP86PM29A for evaluation of mask ROM products, the program is written in the program storing area shown in Figure 1-1.

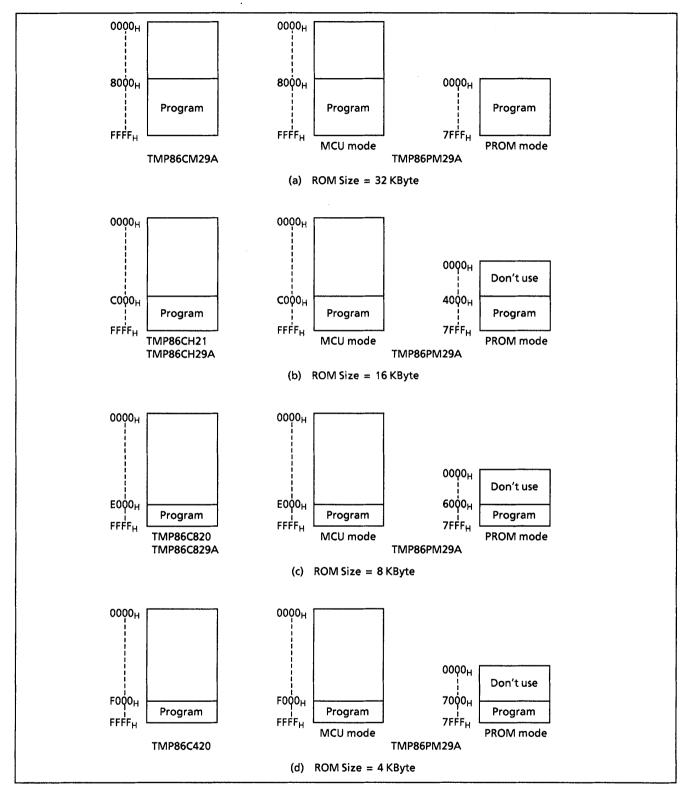


Figure 1-1. Program Memory Area

Note: The area that is not in use should be set data to FFH, or a general-purpose PROM programmer should be set only in the program memory area to access.

# 1.1.2 Data Memory

TMP86PM29A has a built-in 1.5 Kbyte Data memory (static RAM).

# 1.1.3 Input/Output circuitry

# (1) Control pins

The control pins of the TMP86PM29A are the same as those of the TMP86C420/820, TMP86CH21 and TMP86C829A/H29A/M29A except that the TEST pin does not have a built-in pull-down resister.

# (2) I/O ports

The I/O circuitries of TMP86PM29A I/O ports are the same as the those of TMP86C420/820, TMP86CH21 and TMP86C829A/H29A/M29A. However, TMP86C420/820 have not timer/counter 6 input/output and UART input/output.

# 1.2 PROM Mode

The PROM mode is set by setting the RESET pin, the ports P11, P10, P22 to P20, P61 and TEST as shown in Figure 1-2. The programming and verification for the internal PROM is achieved by using a general-purpose PROM programmer with the adapter socket.

Note: The high-speed program mode can be used. The setting is different according to the type of PROM programmer to use, refer to each description of PROM programmer.

The TMP86PM29A does not support the electric signature mode, apply the ROM type of PROM programmer to TC571000D/AD.

Always set the switch of Adapter socket to the N side when using TOSHIBA's Adapter socket.

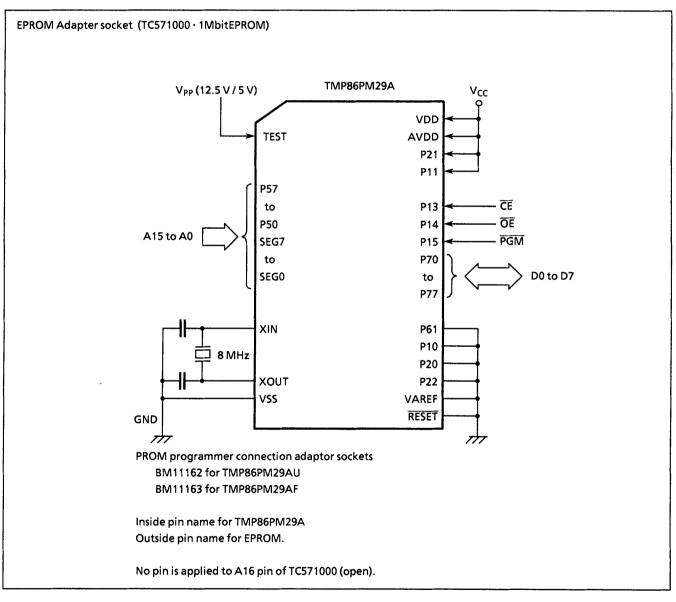


Figure 1-2. PROM Mode Setting

# 1.2.1 Programming flowchart (High-speed program writing)

The high-speed programming mode is set by applying 12.75 V (programming voltage) to the  $V_{PP}$  pin when the  $V_{CC}$  is 6.25 V. After the address and data are fixed, the data in the address is written by applying 0.1ms of low level program pulse to  $\overline{PGM}$  pin. Then verify if the data is written.

If the programmed data is incorrect, another 0.1 ms pulse is applied to  $\overline{PGM}$  pin.

This programming procedure is repeated until correct data is read from the address (maximum of 25 times).

Subsequently, all data are programmed in all addresses.

When all data were written, verify all address under the condition of  $V_{CC} = V_{PP} = 5 \text{ V}$ .

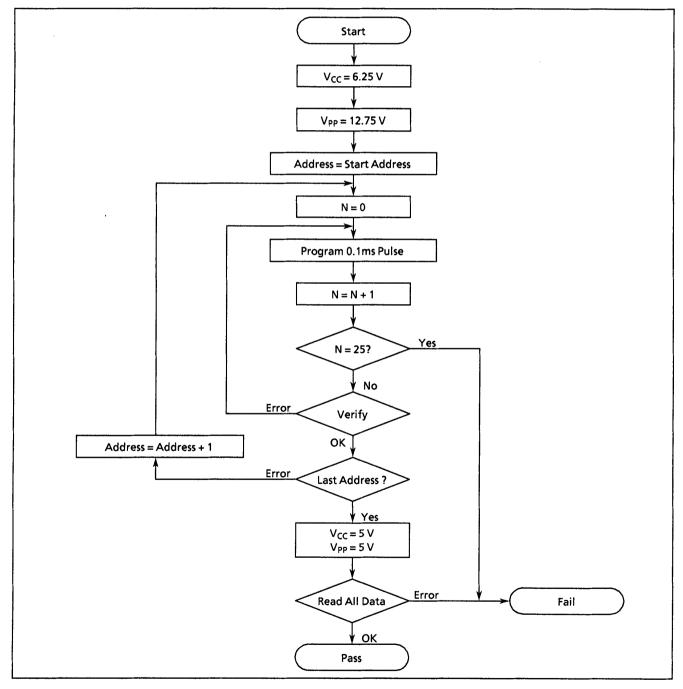


Figure 1-3. Programming Flowchart

# 1.2.2 Program Writing using a general-purpose PROM programmer

(1) Recommended OTP Adapter

BM11162: for TMP86PM29AU BM11163: for TMP86PM29AF

(2) Setting of OTP Adapter

Set the switch (SW1) to N side.

- (3) Setting of PROM programmer
  - i) Set PROM type to TC571000D/AD. VPP: 12.75 V (high-speed program writing)
  - ii) Data transmission (Note 1)

The PROM of TMP86PM29A is located on different addresses; it depends on operating modes: MCU mode and PROM mode. When you write the data of ROM for mask ROM products, the data should be transferred from the address for MCU mode to that for PROM mode before writing operation is executed. For the applicable program areas of MCU mode and PROM mode are different, refer to Figure 1-1 Program Memory Area.

Example:In the block transfer (copy) mode, executed as below.

ROM capacity of 32 KB: Transferred address  $8000_{\rm H}$  to FFFF $_{\rm H}$  to addresses  $0000_{\rm H}$  to 7FFF $_{\rm H}$  ROM capacity of 16 KB: Transferred address  $C000_{\rm H}$  to FFFF $_{\rm H}$  to addresses  $4000_{\rm H}$  to 7FFF $_{\rm H}$  ROM capacity of 8 KB: Transferred address  $E000_{\rm H}$  to FFFF $_{\rm H}$  to addresses  $6000_{\rm H}$  to 7FFF $_{\rm H}$  ROM capacity of 4 KB: Transferred address  $F000_{\rm H}$  to FFFF $_{\rm H}$  to addresses  $F000_{\rm H}$  to 7FFF $_{\rm H}$ 

iii) Setting of the program address (Note 1)

Start address: 00000<sub>H</sub> (When ROM capacity of 16 KB, start address is 4000<sub>H</sub>.) When ROM capacity of 8 KB, start address is 6000<sub>H</sub>.)

End address: 07FFFH

(4) Writing program

Write and verify according to the above mentioned "Setting of PROM programmer."

- Note 1: For the setting method, refer to each description of PROM programmer.

  Make sure to set the data of address area that is not in used to FF<sub>H</sub>.
- Note 2: When setting MCU to the adapter or when setting the adapter to the PROM programmer, set the first pin of the adapter and that of PROM programmer socket matched. If the first pin is conversely set, MCU or adapter or programmer would be damaged.
- Note 3: The TMP86PM29A does not support the electric signature mode.

  If PROM programmer uses the signature, the device would be damaged because of applying voltage of 12 ± 0.5 V to pin 9 (A9) of the address.

  Do not use the signature.

# **Electrical Characteristics**

**Absolute Maximum Ratings** 

 $(V_{SS} = 0 V)$ 

Parameter	Symbol	Pins	Rating	Unit
Supply Voltage	V <sub>DD</sub>		- 0.3 to 6.5	
Program Voltage	V <sub>PP</sub>	TEST/V <sub>PP</sub>	- 0.3 to 13.0	٦.,
Input Voltage	V <sub>IN</sub>		- 0.3 to V <sub>DD</sub> + 0.3	^
Output Voltage	V <sub>OUT1</sub>		- 0.3 to V <sub>DD</sub> + 0.3	1
	I <sub>OUT1</sub>	P3, P6 Port	- 1.8	
Output Current (Per 1 pin)	I <sub>OUT2</sub>	P1, P2, P5, P6, P7 Port	3.2	
	Гоитз	P3 Port	30	m <sub>A</sub>
Output Current (Tatal)	Σl <sub>OUT1</sub>	P1, P2, P5, P6, P7 Port	60	
Output Current (Total)	Σl <sub>OUT2</sub>	P3 Port	80	1
Power Dissipation [T <sub>opr</sub> = 85℃]	PD		350	mW
Soldering Temperature (time)	Tsld		260 (10 μ)	
Storage Temperature	Tstg		- 55 to 125	_ ℃
Operating Temperature	Topr		- 40 to 85	1

Note: The absolute maximum ratings are rated values which must not be exceeded during operation, even for an instant.

Any one of the ratings must not be exceeded. If any absolute maximum rating is exceeded, a device may break down or its performance may be degraded, causing it to catch fire or explode resulting in injury to the user. Thus, when designing products which include this device, ensure that no absolute maximum rating value will ever be exceeded.

**Recommended Operating Condition** 

 $(V_{SS} = 0 \text{ V, Topr} = -40 \text{ to } 85^{\circ}\text{C})$ 

Parameter	Symbol	Pins	С	ondition	Min	Max	Unit
				NORMAL1, 2 mode			
			fc = 16 MHz	IDLE0, 1, 2 mode	4.5		
				NORMAL1, 2 mode			
			fc = 8 MHz	IDLE0, 1, 2 mode	2.7		
Supply Voltage	V <sub>DD</sub>			NORMAL1, 2 mode		5.5	V
			fc = 4.2 MHz	IDLE0, 1, 2 mode			
			fs = 32.768 kHz	SLOW1, 2 mode	1.8		
				SLEEP0, 1, 2 mode	1		
			STOP mode				
	V <sub>IH1</sub>	Except Hysteresis input		> 4.5.7	$V_{DD} \times 0.70$		
Input high Level	V <sub>IH2</sub>	Hysteresis input	$V_{DD} \ge 4.5 V$ $V_{DD} < 4.5 V$		$V_{DD} \times 0.75$	V <sub>DD</sub>	V
	V <sub>IH3</sub>				$V_{DD} \times 0.90$		
	V <sub>IL1</sub>	Except Hysteresis input		> 4 5 1/		$V_{DD} \times 0.30$	
Input low Level	V <sub>IL2</sub>	Hysteresis input	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	<sub>D</sub> ≧ 4.5 V	0	V <sub>DD</sub> × 0.25	V
	V <sub>IL3</sub>		V <sub>D</sub>	<sub>D</sub> < 4.5 V		V <sub>DD</sub> × 0.10	
			V <sub>DD</sub> =	= 1.8 to 5.5 V		4.2	
Clock Frequency fc	XIN, XOUT	$V_{DD} = 2.7 \text{ to } 5.5 \text{ V}$		1.0	8.0	MHz	
Clock Frequency			V <sub>DD</sub> = 4.5 to 5.5 V			16.0	1
	fs	XTIN, XTOUT			30.0	34.0	kHz

Note: The recommended operating conditions for a device are operating conditions under which it can be guaranteed that the device will operate as specified. If the device is used under operating conditions other than the recommended operating conditions (supply voltage, operating temperature range, specified AC/DC values etc.), malfunction may occur. Thus, when designing products which include this device, ensure that the recommended operating conditions for the device are always adhered to.

**DC** Characteristics

 $(V_{SS} = 0 \text{ V, Topr} = -40 \text{ to } 85^{\circ}\text{C})$ 

Parameter	Symbol	Pins	Condition	Min	Тур.	Max	Unit
Hysteresis Voltage	V <sub>HS</sub>	Hysteresis input		_	0.9	-	V
	l <sub>IN1</sub>	TEST					
Input Current	I <sub>IN2</sub>	Sink Open Drain, Tri-state	$V_{DD} = 5.5 \text{ V}, V_{IN} = 5.5 \text{ V} / 0 \text{ V}$	-	_	± 2	μΑ
	l <sub>IN3</sub>	RESET, STOP					
Input Resistance	R <sub>IN2</sub>	RESET Pull-Up		100	220	450	kΩ
Output Leakage Current	I <sub>LO</sub>	Sink Open Drain, Tri-state	V <sub>DD</sub> = 5.5 V, V <sub>OUT</sub> = 5.5 V / 0 V	_	_	± 2	μΑ
Output High Voltage	V <sub>OH2</sub>	C-MOS, Tri-st Port	$V_{DD} = 4.5 \text{ V}, I_{OH} = -0.7 \text{ mA}$	4.1	-	-	V
Output Low Voltage	V <sub>OL</sub>	Except XOUT and P3 Port	$V_{DD} = 4.5 \text{ V}, I_{OL} = 1.6 \text{mA}$	-	-	0.4	V
Output Low Current	lou	High Current Port (P3 Port)	$V_{DD} = 4.5 \text{ V}, V_{OL} = 1.0 \text{ V}$	-	20	-	mA
Supply Current in NORMAL 1, 2 mode			V <sub>DD</sub> = 5.5 V V <sub>IN</sub> = 5.3 / 0.2 V	-	7.5	9	
Supply Current in IDLE 0, 1, 2 mode			fc = 16 MHz fs = 32.768 kHz	_	5.5	6.5	mA
Supply Current in SLOW 1 mode				-	18	42	
Supply Current in SLEEP 1 mode	→ V <sub>DD</sub>		$V_{DD} = 3.0 \text{ V}$ $V_{IN} = 2.8 \text{ V} / 0.2 \text{ V}$ $fs = 32.768 \text{ kHz}$		16	25	
Supply Current in SLEEP 0 mode			LCD driver is not enable.	-	12	20	μΑ
Supply Current in STOP mode			V <sub>DD</sub> = 5.5 V V <sub>IN</sub> = 5.3 V / 0.2 V	_	0.5	10	

Note 1: Typical values show those at Topr =  $25^{\circ}$ C,  $V_{DD} = 5 V$ 

Note 2: Input current (I<sub>IN1</sub>, I<sub>IN2</sub>); The current through pull-up or pull-down resistor is not included.

Note 3: IDD does not include IREF current.

Note 4: The supply currents of SLOW 2 and SLEEP 2 modes are equivalent to IDLE 0, 1, 2.

# **AD Conversion Characteristics**

# $(V_{SS} = 0.0 \text{ V}, 4.5 \text{ V} \le V_{DD} \le 5.5 \text{ V}, \text{Topr} = -40 \text{ to } 85^{\circ}\text{C})$

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Analog Reference Voltage	VAREF		A <sub>VDD</sub> - 1.0	_	A <sub>VDD</sub>	V
Power Supply Voltage of Analog Control Circuit	A <sub>VDD</sub>			$V_{DD}$		V
Analog Reference Voltage Range (Note 4)	△V <sub>AREF</sub>		3.5	-	T -	V
Analog Input Voltage	V <sub>AIN</sub>		Vss	-	VAREF	V
Power Supply Current of Analog Reference Voltage	I <sub>REF</sub>	$V_{DD} = A_{VDD} = V_{AREF} = 5.5 V$ $V_{SS} = 0.0 V$	-	0.6	1.0	mA
Non linearity Error			1 1	_	±2	
Zero Point Error		$V_{DD} = A_{VDD} = 5.0 \text{ V},$	-	_	± 2	1
Full Scale Error		$V_{SS} = 0.0 \text{ V}$ $V_{AREF} = 5.0 \text{ V}$	_	_	± 2	LSB
Total Error		Aner	-	_	±2	1

# $(V_{SS} = 0.0 \text{ V}, 2.7 \text{ V} \le V_{DD} < 4.5 \text{ V}, \text{Topr} = -40 \text{ to } 85^{\circ}\text{C})$

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Analog Reference Voltage	VAREF		A <sub>VDD</sub> - 1.0	-	A <sub>VDD</sub>	V
Power Supply Voltage of Analog Control Circuit	A <sub>VDD</sub>			$V_{DD}$		V
Analog Reference Voltage Range (Note 4)	$\Delta v_{AREF}$		2.5	_	-	V
Analog Input Voltage	V <sub>AIN</sub>		Vss	_	VAREF	V
Power Supply Current of Analog Reference Voltage	I <sub>REF</sub>	$V_{DD} = A_{VDD} = V_{AREF} = 4.5 \text{ V}$ $V_{SS} = 0.0 \text{ V}$	-	0.5	0.8	mA
Non linearity Error				_	± 2	
Zero Point Error		$V_{DD} = A_{VDD} = 2.7 \text{ V},$	_	_	± 2	1 '
Full Scale Error		$V_{SS} = 0.0 \text{ V}$ $V_{AREF} = 2.7 \text{ V}$	-	_	± 2	LSB
Total Error		Aner	-	_	± 2	1

# $(V_{SS} = 0.0 \text{ V}, 2.0 \text{ V} \le V_{DD} < 2.7 \text{ V}, Topr = -40 to 85°C) \text{ Note 5}$ $(V_{SS} = 0.0 \text{ V}, 1.8 \text{ V} \le V_{DD} < 2.0 \text{ V}, Topr = -10 to 85°C) \text{ Note 5}$

· Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Analog Reference Voltage	VAREF		A <sub>VDD</sub> - 0.9	-	A <sub>VDD</sub>	V
Power Supply Voltage of Analog Control Circuit	A <sub>VDD</sub>			V <sub>DD</sub>		V
Analog Reference Voltage Rence (Note 4)	Λ.ν.	$1.8  \text{V} \leq \text{V}_{\text{DD}} < 2.0  \text{V}$	1.8	-	-	.,
Analog Reference Voltage Range (Note 4)	△V <sub>AREF</sub>	$2.0  \text{V} \le \text{V}_{\text{DD}} < 2.7  \text{V}$	2.0		_	^
Analog Input Voltage	V <sub>AIN</sub>		V <sub>SS</sub>	-	VAREF	V
Power Supply Current of Analog Reference Voltage	REF	$V_{DD} = A_{VDD} = V_{AREF} = 2.7 \text{ V}$ $V_{SS} = 0.0 \text{ V}$	-	0.3	0.5	mA
Non linearity Error			- 1		± 4	
Zero Point Error		$V_{DD} = A_{VDD} = 1.8 \text{ V},$	-	-	± 4	1
Full Scale Error		$V_{SS} = 0.0 \text{ V}$ $V_{AREF} = 1.8 \text{ V}$	_	_	±4	LSB
Total Error		Anci	-	-	±4	

- Note 1: The total error includes all errors except a quantization error, and is defined as a maximum deviation from the ideal conversion line.
- Conversion time is different in recommended value by power supply voltage. Note 2:

About conversion time, please refer to "2.10.2 Register Framing".

Note 3: Please use input voltage to AIN input Pin in limit of V<sub>AREF</sub> - V<sub>SS</sub>.

When voltage of range outside is input, conversion value becomes unsettled and gives affect to other channel conversion value.

- Note 4: Analog Reference Voltage Range:  $\triangle V_{AREF} = V_{AREF} V_{SS}$ Note 5: When AD is used with  $V_{DD} < 2.7 \text{ V}$ , the guaranteed temperature range varies with the operating voltage.

# **AC Characteristics**

 $(V_{SS} = 0 \text{ V}, V_{DD} = 4.5 \text{ to } 5.5 \text{ V}, Topr = -40 \text{ to } 85^{\circ}\text{C})$ 

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
		NORMAL 1, 2 mode				
Machine Cycle Time		IDLE 1, 2 mode	0.25	-	4	
	tcy	SLOW 1, 2 mode		_	133.3	μS
		SLEEP 1, 2 mode	117.6			
High Level Clock Pulse Width	twcH	For external clock operation (XIN input)				
Low Level Clock Pulse Width	twcL	fc = 16 MHz	-	31.25	-	ns
High Level Clock Pulse Width	twcH	For external clock operation (XTIN input)			_	
Low Level Clock Pulse Width	twcL	fc = 32.768 kHz	-	15.26		μ\$

# $(V_{SS} = 0 \text{ V}, V_{DD} = 2.7 \text{ to } 4.5 \text{ V}, \text{Topr} = -40 \text{ to } 85^{\circ}\text{C})$

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
Machine Cycle Time tcy		NORMAL 1, 2 mode				
	4	IDLE 1, 2 mode	0.5	-	4	
	τεν	SLOW 1, 2 mode		_	133.3	μs
•		SLEEP 1, 2 mode	117.6			
High Level Clock Pulse Width	twcH	For external clock operation (XIN input)				1
Low Level Clock Pulse Width	twcL	fc = 8 MHz	-	62.5	_	ns
High Level Clock Pulse Width	twcH	For external clock operation (XTIN input)		15.26	-	
Low Level Clock Pulse Width	twcL	fc = 32.768 kHz	-			μS

# $(V_{SS} = 0 \text{ V}, V_{DD} = 1.8 \text{ to } 2.7 \text{ V}, Topr = -40 \text{ to } 85^{\circ}\text{C})$

Parameter	Symbol	Condition	Min	Тур.	Max	Unit
		NORMAL 1, 2 mode			4	
Machine Cycle Time	tcy	IDLE 1, 2 mode	0.95	-		
		SLOW 1, 2 mode				μS
		SLEEP 1, 2 mode	117.6	-	133.3	
High Level Clock Pulse Width	twcH	For external clock operation (XIN input)				
Low Level Clock Pulse Width	twcL	fc = 4.2 MHz	-	119.05	-	ns
High Level Clock Pulse Width	twcH	For external clock operation (XTIN input)	73	15.26		
Low Level Clock Pulse Width	twcL	fc = 32.768 kHz	_		-	μς

# Timer Counter 1 input (ECIN) Characteristics

# $(V_{SS} = 0 \text{ V, Topr} = -40 \text{ to } 85^{\circ}\text{C})$

Parameter	Symbol	Condition	Min	Тур.	Max	Unit	
TC1 input (ECIN input)		Frequency measurement mode V <sub>DD</sub> = 4.5 to 5.5 V	Single edge count	_	_	16	MHz
			Both edge count	_	_		
		Frequency measurement mode V <sub>DD</sub> = 2.7 to 4.5 V	Single edge count	-	_	8	
			Both edge count	_	_		
		Frequency measurement mode $V_{DD} = 1.8$ to 2.7 V	Single edge count	_	_	4.2	
			Both edge count	_	_		

Recommended Oscillating Conditions - 1

$$(V_{SS} = 0 \text{ V}, V_{DD} = 4.5 \text{ to } 5.5 \text{ V}, \text{ Topr} = -40 \text{ to } 85^{\circ}\text{C})$$

PARAMETER	0. 11. 1	Oscillation			Recommended Constant		
PARAIVIETER	Oscillator	Frequency	Kecom	mended Oscillator	C <sub>1</sub>	C <sub>2</sub>	
		16 MHz	MURATA	CSA16.00MXZ040	10 pF	10 pF	
High-frequency Oscillation	Ceramic Resonator	8 MHz	MURATA	CSA8.00MTZ	30 pF	30 pF	
				CST8.00MTW	30 pF (built-in)	30 pF (built-in)	
		4.19 MHz	MURATA	CSA4.19MG	30 pF	30 pF	
				CST4.19MGW	30 pF (built-in)	30 pF (built-in)	
Low-frequency	Crystal Oscillator	32.768 kHz	SII	VT-200	6 - 5	6 - 5	
Oscillation	Crystal Oscillator	32.768 KHZ	311	V 1-200	6 pF	6 pF	

Recommended Oscillating Conditions - 2

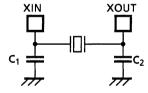
$$(V_{SS} = 0 \text{ V}, V_{DD} = 2.7 \text{ to } 5.5 \text{ V}, \text{ Topr} = -40 \text{ to } 85^{\circ}\text{C})$$

PARAMETER		Oscillation			Recommended Constant		
PARAIVIETER	Oscillator	Frequency	Recom	mended Oscillator	C <sub>1</sub>	C <sub>2</sub>	
High-frequency Oscillation	Ceramic Resonator	8 MHz	MURATA	CSA8.00MTZ	30 pF	30 pF	
				CST8.00MTW	30 pF (built-in)	30 pF (built-in)	
		4.19 MHz	MURATA	CSA4.19MG	30 pF	30 pF	
				CST4.19MGW	30 pF (built-in)	30 pF (built-in)	

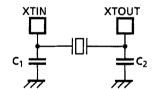
Recommended Oscillating Conditions - 3

$$(V_{SS} = 0 \text{ V}, V_{DD} = 1.8 \text{ to } 5.5 \text{ V}, \text{ Topr} = -40 \text{ to } 85^{\circ}\text{C})$$

PARAMETER		Oscillation	Recommended Oscillator		Recommend	Recommended Constant		
	Oscillator	Frequency			C <sub>1</sub>	C <sub>2</sub>		
High-frequency	Caramia Basanatas	4.40.8411-	MURATA	CSA4.19MG	30 pF	30 pF		
Oscillation	Ceramic Resonator	4.19 MHz		CST4.19MGW	30 pF (built-in)	30 pF (built-in)		



(1) High-frequency Oscillation



(2) Low-frequency Oscillation

- Note 1: An electrical shield by metal shield plate on the surface of IC package is recommended in order to protect the device from the high electric field stress applied from CRT (Cathodic Ray Tube) for continuous reliable operation.
- Note 2: The product numbers and specifications of the resonators by Murata Manufacturing Co., Ltd. are subject to change.

  For up-to-date information, please refer to the following

  URL; http://www.murata.co.jp/search/index.html

DC Characteristics, AC Characteristics (PROM Mode) (V<sub>SS</sub> = 0 V, Topr = -40 to 85°C)

# Read operation in PROM mode

Parameter	Symbol	Conditions	Min	Тур.	Max	Unit
High level input voltage (TTL)	V <sub>IH4</sub>		2.2	_	V <sub>CC</sub>	V
Low leve input voltage (TTL)	V <sub>IL4</sub>		0	-	0.8	V
Power supply	V <sub>CC</sub>		4.75	5.0	5.25	V
Power supply of program	$V_{PP}$		4.75	3.0	5.25	"
Address access time	t <sub>ACC</sub>	$V_{CC} = 5.0 \pm 0.25 \text{ V}$	-	1.5tcyc + 300	-	ns

Note: tcyc = 500 ns at 8 MHz

